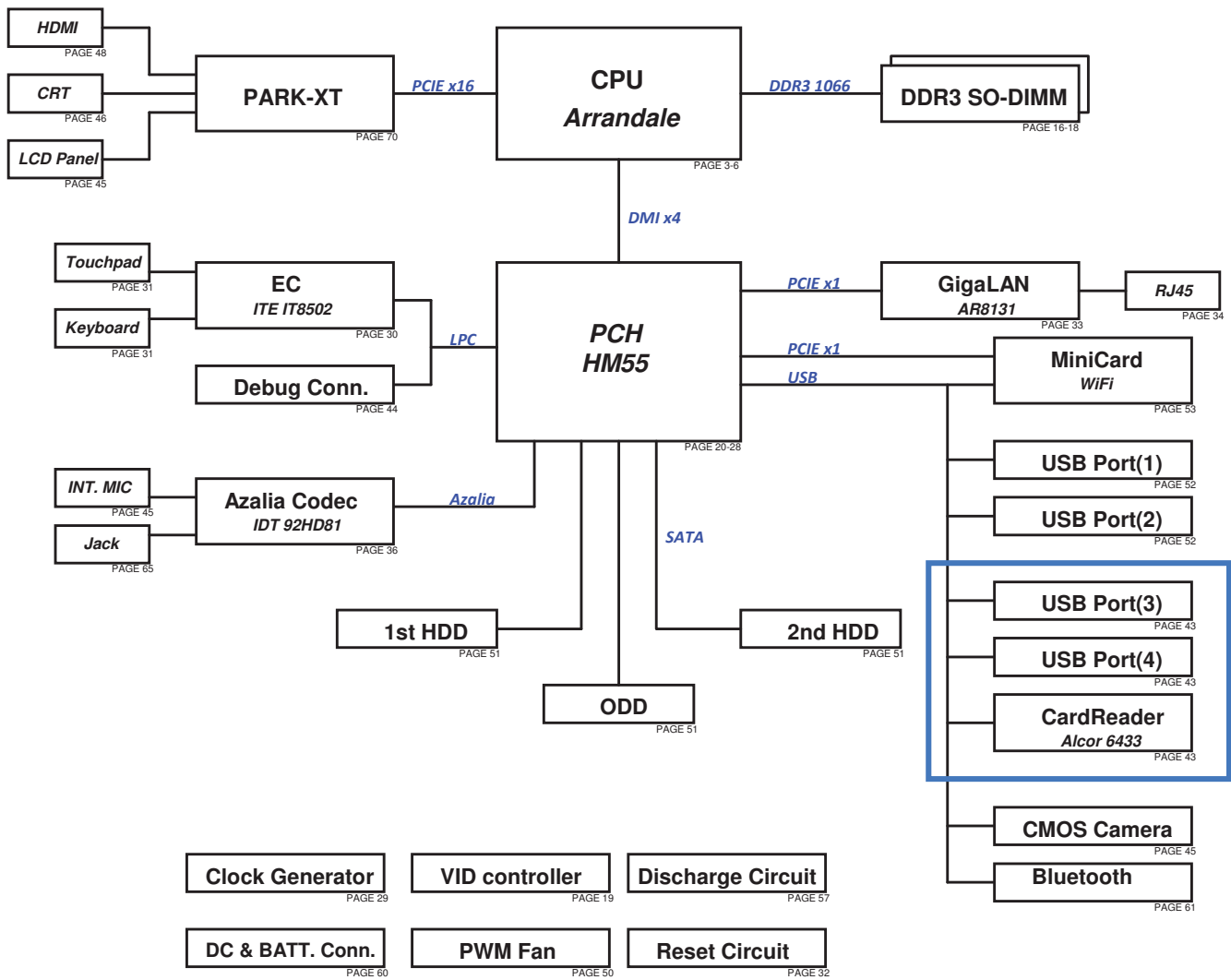
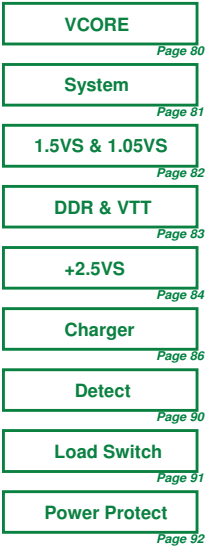


PAGE	Content
1	Block Diagram
2	System Setting
3	CPU(1)_DMI, PEG, FDI, CLK, MISC
4	CPU(2)_DDR3
5	CPU(3)_CFG, RSVD, GND
6	CPU(4)_PWR
7	CPU(5)_XDP
16	DDR3 SO-DIMM_0
17	DDR3 SO-DIMM_1
18	DDR3 CA_DQ VOLTAGE
19	VID controller
20	PCH_IBEX(1) SATA, IHDA, RTC, LPC
21	PCH_IBEX(2)_PCIE, CLK, SMB, PEG
22	PCH_IBEX(3)_FDI, DMI, SYS PWR
23	PCH_IBEX(4)_DP, LVDS, CRT
24	PCH_IBEX(5)_PCI, NVRAM, USB
25	PCH_IBEX(6) CPU, GPIO, MISC
26	PCH_IBEX(7)_POWER, GND
27	PCH_IBEX(8)_POWER, GND
28	PCH_SPI ROM, OTH
29	CLK_ICS9LPR362
30	EC_IT8541(1/2)
31	EC_IT8541(2/2) KB, TP
32	RST_Reset Circuit
33	HANKSVILLE
34	LAN_RJ45
36	CODEC-ALC269
37	AUD_Amp & Jack
40	CB_R5C833
41	CB_R5C833
42	CB_4in1 CardReader
43	CB_NewCard
44	BUG_Debug
45	CRT_LCD Panel
46	CRT_D-Sub
48	TV_HDMI
50	FAN_Fan & Sensor
51	XDD_HDD & ODD
52	USB_USB Port *2
53	MINICARD(WLAN)
56	LED_Indicator
57	DSG_Discharge
60	DC_DC & BAT Conn.
61	BT_Bluetooth
65	ME_Conn & Skew Hole
67	PCH_XDP, ONFI
70	VGA_M96 Main (1)
71	VGA_M96 Main (2)
72	VGA_M96 MEM CHANNEL A
73	VGA_M96 MEM CHANNEL B
74	VGA_M96 Power (1)
75	VGA_M96 Power (2)
76	VGA_M96 THERMAL/Memory SS
77	VGA_M96 Straps
78	VGA_POWER_VGA_CORE & RAM
79	VGA_POWER_VGA_+1.2VS_+1.1VS
80	PW_VCORE(MAX17034)
81	PW_SYSTEM(MAX17020)
82	PW_I/O_VTT_CPU&+1.1VM
83	PW_I/O_DDR & VTT& +1.8VS
84	PW_I/O_3VM & ME_+VM_PWEGD
86	PW_+VGFX_CORE(MAX17028)
88	PW_CHARGER(MAX17015)
90	PW_DETECT
91	PW_LOAD SWITCH
92	PW_PROTECT
93	PW_SIGNAL
94	PW_FLOWCHART

K72JK Schematic R2.0



Power



Daughter Board

PCH GPIO	Usage	Signal Name	Pull Up / Pull Down	Power
GPIO 00	GPO		INT PU 20K	+3VS
GPIO 01	GPO		EXT PU 10K	+3VS
GPIO [02:05]	Native	PCI_INT[E:H]#	INT PU 20K	+5VS
GPIO 06	GPO		INT PU 20K	+3VS
GPIO 07	GPO		INT PU 20K	+3VS
GPIO 08	GPI	EXT_SMI#	EXT PU & INT PU	+3VSUS
GPIO 09	Native	USB_OC#5	EXT PU 10K	+3VSUS
GPIO 10	Native	USB_OC#6	EXT PU 10K	+3VSUS
GPIO 11	GPI	EXT_SCI#	EXT PU 10K	+3VSUS
GPIO 12	GPO		INT PD 20K	+3VSUS
GPIO 13	GPO		EXT PU 10K	+3VSUS
GPIO 14	GPO	USB_OC#7	INT PD 20K	+3VSUS
GPIO 15	GPO	BT_LED		+3VSUS
GPIO 16	GPO		EXT PU 10K	+3VS
GPIO 17	GPO		EXT PU 10K	+3VS
GPIO 18	Native	CLKREQ1#	EXT PU 10K	+3VS
GPIO 19	Native	SATA1GP	EXT PU 10K	+3VS
GPIO 20	Native	CLKREQ2#	EXT PD 10K	+3VS
GPIO 21	Native	SATA0GP	EXT PU 10K	+3VS
GPIO 22	GPO	WLAN_LED		+3VS
GPIO 23	GPO		INT PU 20K	+3VS
GPIO 24	GPO			+3VSUS
GPIO 25	Native	CLKREQ3#	EXT PU 10K	+3VSUS
GPIO 26	Native	CLKREQ4#	EXT PU 10K	+3VSUS
GPIO 27	GPO		INT PU 20K	+3VSUS
GPIO 28	GPO	WLAN_ON#	INT PU 20K	+3VSUS
GPIO 29	GPO			+3VSUS
GPIO 30	Native	ME_SusPwrDnAck	EXT PU 10K	+3VSUS
GPIO 31	Native	ME_AC_PRESENT	EXT PU 10K	+3VSUS
GPIO 32	Native	PM_CLKRUN#	EXT PU 10K	+3VS
GPIO 33	GPI	PCH_SPL_OV	INT PU 20K	+3VS
GPIO 34	Native	STP_PCI#		+3VS
GPIO 35	Native	SATA_CLK_REQ#	EXT PD 10K	+3VS
GPIO 36	GPO		EXT PU 10K	+3VS
GPIO 37	GPO		EXT PU 10K	+3VS
GPIO 38	GPI	PCB_ID0	EXT PU/PD	+3VS
GPIO 39	GPI	PCB_ID1	EXT PU/PD	+3VS
GPIO 40	Native	USB_OC#1	EXT PU 10K	+3VSUS
GPIO 41	Native	USB_OC#2	EXT PU 10K	+3VSUS
GPIO 42	Native	USB_OC#3	EXT PU 10K	+3VSUS
GPIO 43	Native	USB_OC#4	EXT PU 10K	+3VSUS
GPIO 44	Native	CLK_REQ5#	EXT PU 10K	+3VSUS
GPIO 45	Native	CLK_REQ6#	INT & EXT PU	+3VSUS
GPIO 46	GPO			+3VSUS
GPIO 47	Native	CLKREQ_PEG#A	EXT PD 10K	+3VSUS
GPIO 48	GPO			+3VS
GPIO 49	Native	TEMP_ALERT#	EXT PU 10K	+3VS
GPIO 50	Native	PCI_REQ1#	EXT PU 10K	+5VS
GPIO 51	Native	PCI_GNT1#	INT PU 20K	+3VS
GPIO 52	Native	PCI_REQ2#	EXT PU 10K	+5VS
GPIO 53	Native	PCI_GNT2#	INT PU 20K	+3VS
GPIO 54	Native	PCI_REQ3#	EXT PU 10K	+5VS
GPIO 55	Native	PCI_GNT3#	INT PU 20K	+3VS
GPIO 56	Native	CLKREQ_PEG#B	EXT PU 10K	+3VSUS
GPIO 57	GPO	BT_ON	EXT PU(DIODE)	+3VSUS
GPIO 58	Native	SML1_CLK	EXT PU 10K	+3VSUS
GPIO 59	Native	USB_OC#0	EXT PU 10K	+3VSUS
GPIO 60	Native	SML0ALERT#	EXT PU 10K	+3VSUS
GPIO 61	Native	SUS_STAT#		+3VSUS
GPIO 62	Native	SUSCLK		+3VSUS
GPIO 63	Native	SLP_S5#		+3VSUS
GPIO 64	Native	CLK_OUT0	INT PD 20K	+3VS
GPIO 65	Native	CLK_OUT1	INT PD 20K	+3VS
GPIO 66	Native	CLK_OUT2	INT PD 20K	+3VS
GPIO 67	Native	CLK_CARD_READER_48	INT PD 20K	+3VS
GPIO 72	Native	PM_BATLOW#	INT PU 20K	+3VSUS
GPIO 73	Native	CLK_REQ0#	EXT PU 10K	+3VSUS
GPIO 74	Native	SML1ALERT#	EXT PU 10K	+3VSUS
GPIO 75	Native	SML1_DATA	EXT PU 10K	+3VSUS

EC GPIO	Use As	Signal Name
GPA0	O	PWR_LED#
GPA1	O	CHG_LED#
GPA2		CHG_FULL_LED#
GPA3		-
GPA4	O	LCD_BL_PWM
GPA5	O	FAN0_PWM
GPA6		-
GPA7		-
GPB0	O	BATSEL_0
GPB1	O	BATSEL_1
GPB2		ME_AC_PRESENT_EC
GPB3	IO	SMB0_CLK
GPB4	IO	SMB0_DAT
GPB5	O	A20GATE
GPB6	O	RCIN#
GPB7	O	PM_RSMRST#
GPC0		-
GPC1	IO	SMB1_CLK
GPC2	IO	SMB1_DAT
GPC3	O	PM_PWRBTN#
GPC4	I	AC_IN_OC#
GPC5	O	OP_SD#
GPC6	I	BAT1_IN_OC#
GPC7	I	-
GPD0	I	PWRLIMIT#
GPD1	I	PM_SUSC#
GPD2	I	BUF_PLT_RST#
GPD3	O	EXT_SCI#
GPD4	O	EXT_SMI#
GPD5	O	LCD_BACKOFF#
GPD6	I	FAN0_TACH
GPD7		SD_CD#_EC
GPE0	O	VSUS_ON
GPE1	O	-
GPE2	O	-
GPE3	O	-
GPE4	I	PWR_SW#
GPE5		-
GPE6	I	LID_SW#
GPE7		-
GPF0	O	-
GPF1		-
GPF2	I	-
GPF3		-
GPF4	I	TP_CLK
GPF5	IO	TP_DAT
GPF6	O	THRO_CPU
GPF7		PCH_SPL_OV
GPG0		ME_SusPwrDnAck_EC
GPJ1	I	PM_SUSB#
GPJ2	O	OCMV_CTL0
GPJ6	O	OCMV_CTL1
GPJ0	IO	PM_CLKRUN#
GPH1	O	-
GPH2	O	CHG_EN
GPH3	O	SUSC_EC#
GPH4	O	SUSB_EC#
GPH5	O	NUM_LED#
GPH6	O	CAP_LED#
GPI0		-
GPI1	I	SUS_PWRGD
GPI2	I	ALL_SYSTEM_PWRGD
GPI3	I	VRM_PWRGD
GPI4	I	PCH_TEMP_ALERT#
GPI5	I	-
GPI6	I	-
GPI7	I	-
GPU0	O	CPU_VRON
GPJ1	O	PM_PWROK
GPJ2	O	VSET_EC
GPJ3	O	ISET_EC
GPJ4	O	-
GPJ5		-

EC GPIO	Use As	Signal Name
GPIO0	I	
GPIO1	I	
GPIO2		-
GPIO3		-
GPIO4	I	
GPIO5	I	
GPIO6	O	
GPIO7		-
GPIO8		-
GPIO9		-
GPIO10		-
GPIO11		-
GPIO12	O	
GPIO13		-
GPIO14	O	
GPIO15		-
GPIO16		-
GPIO17		-
GPIO18		-
GPIO19		-
GPIO20		-
GPIO21		-
GPIO22		-
GPIO23		-
GPIO24		-
GPIO25		-
GPIO26		-
GPIO27		-
GPIO28		-
GPIO29		-
GPIO30		-
GPIO31		-
GPIO32		-
GPIO33		-
GPIO34		-
GPIO35		-
GPIO36		-
GPIO37		-

SM_BUS ADDRESS :

PCH Master		
SM-Bus Device	SM-Bus Address	
Clock Generator(IC59LRS3162)	1101001x (D2)	
SO-DIMM 0	1010000x (A0)	
SO-DIMM 1	1010001x (A2)	
EC Master (SMB1)		
SM-Bus Device	SM-Bus Address	
CPU Thermal Sensor(G781)	1001100x (98)	
VGA Thermal IC(G781-1)	1001101x (9A)	

Device Identification

	CPU Thermal Sensor P/N:	component name
1st	06G023048011	G781F
S		
S		
S		

	Clock Gen P/N:	component name
1st	06G011610010	ICS9LRS3162
S		
S		

	VGA Thermal Sensor	component name
1st	06G023048020	G781-1
S		
S		

PCIE 1	
PCIE 2	Minicard WLAN
PCIE 3	
PCIE 4	
PCIE 5	
PCIE 6	GLAN
PCIE 7	
PCIE 8	

SATA 0	SATA HDD (1)
SATA1	SATA ODD
SATA4	SATA HDD (2)
SATA5	

	K72J
0	USB port
1	USB port
2	USB port (D/B)
3	USB port (D/B)
4	
5	MiniCard (Full)
6	
7	
8	MiniCard (Half)
9	Camera
10	
11	Card Reader
12	Bluetooth
13	

1. NC:
FDI_TX#[0:7],FDI_TX[0:7],FDI_RX#[0:7],FDI_RX[0:7]
VCC_AXGSENSE,VSS_AXGSENSE

FDI_FSYNC[0:1],FDI_LSYNC[0:1],FDI_INT,GFX_IMON
~15mW power saving.(DG R0.8 P.70)

VCCAXG,

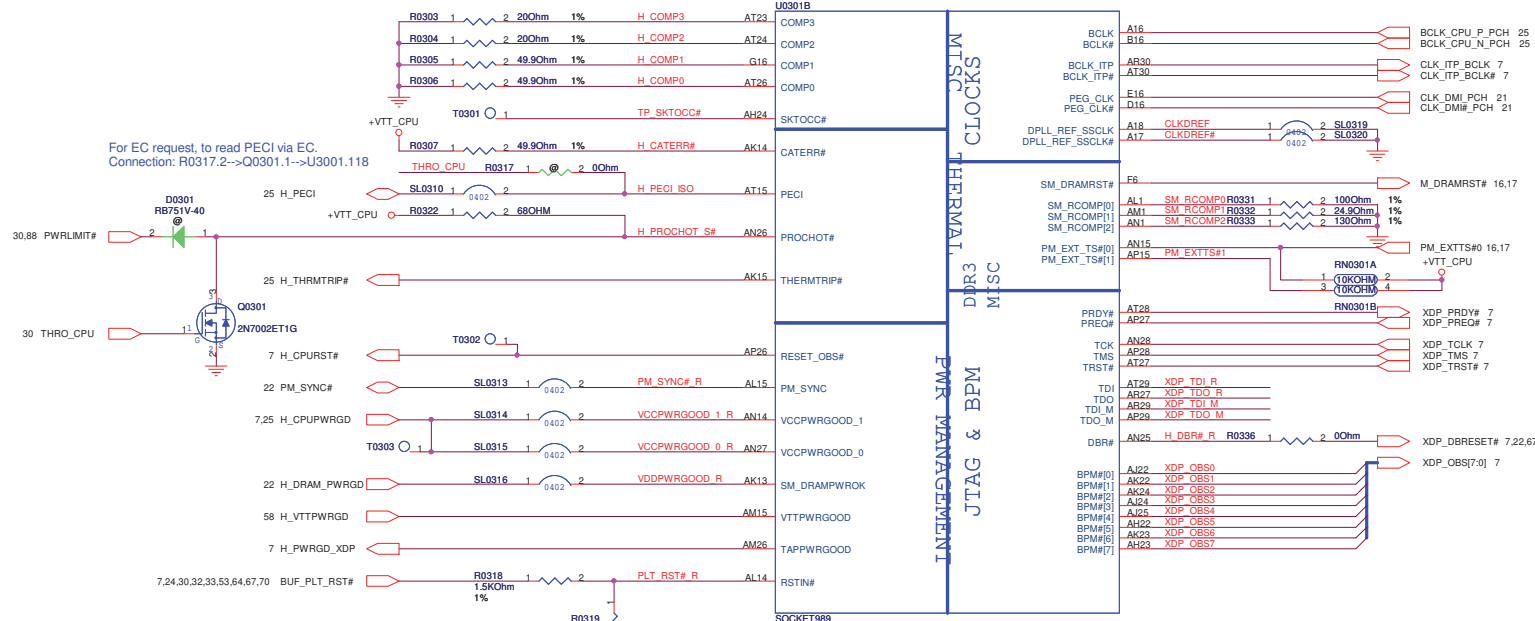
DPLL_REF_CLK,DPLL_REF_CLK#

VCCEDIPLI

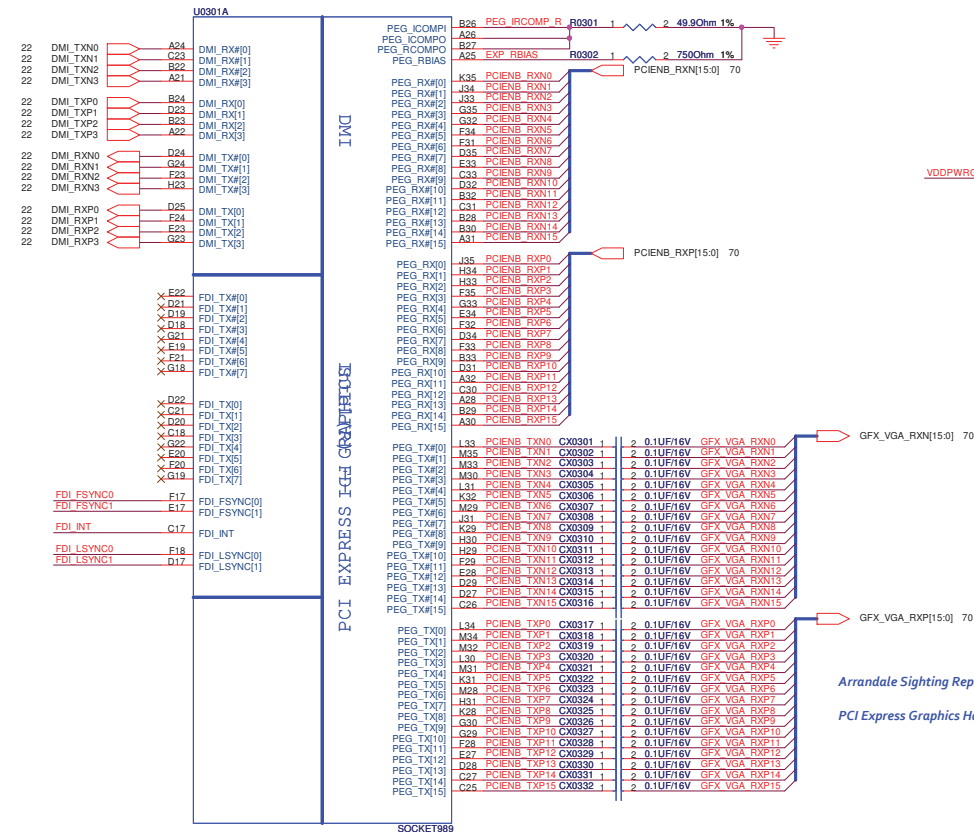
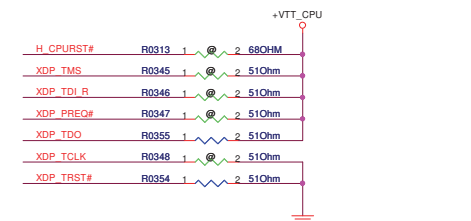


*On the other hand, FDI_FSYNC[0], FDI_FSYNC[1], FDI_LSYNC[0], FDI_LSYNC[1], and FDI_INT signals on PCH side can be left as no connect without any power or functional impact.

System May Hang With DMI L1 Enabled.



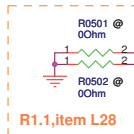
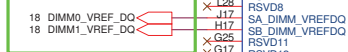
Tape & Reel : 12G011909893



PCI Express Graphics Hang With L1 Enabled in Rare Cases.

*On Clarksfield rPGA only designs, VCCPWRGOOD_1 on the Clarksfield processor can be left as No Connect.

10 mil



U0301E

RESERVED

SOCKET989

CFG strapping information:

CFG[1:0]: PCI Express Port Bifurcation:(Clarksfield Only)
- 11 = 1 x 16 PEG (Default)
- 10 = 2 x 8 PEG

CFG[3]: PCIE Static Numbering Lane Reversal.(Auburndale Only)

- 1:Normal Operation (Default)
- 0:Lane Numbers Reversed 15 -> 0, 14 -> 1, ...

CFG[4]: Embedded DisplayPort Detection.(Auburndale Only)

- 1:Disabled - No Physical Display Port attached to Embedded DisplayPort
- 0:Enabled - An external Display Port device is connected to the Embedded Display Port

CFG[7]: Fixed for PCI Express 2.0 jitter specifications.(Clarksfield)

Clarksfield (only for early samples pre-ES1) - Connect to GND with 3.01K Ohm/5% resistor

For a common motherboard design (for AUB and CFD), the pull-down resistor should be used. Does not impact AUB functionality.

Unmount if Intel has fixed this issue.

Note: (Auburndale)Hardware Straps are sampled on the asserting edge of VCCPWRGOOD_0 and VCCPWRGOOD_1 and latched inside the processor.

Note: (Clarksfield)Hardware Straps are sampled after RSTIN# de-assertion.

U0301H

VSS

SOCKET989

Intel sighting #: 402607(3393727)

To drive a value of zero on CFG[0] pin use a 250 Ohm pull down resistor to Vss.



Unmount R0501& R0502 & R0505 & R0506 for Intel CRB sugestion.

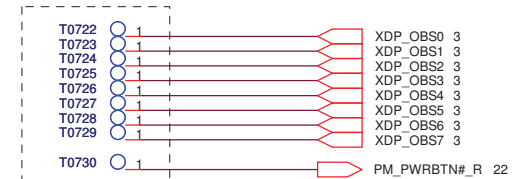
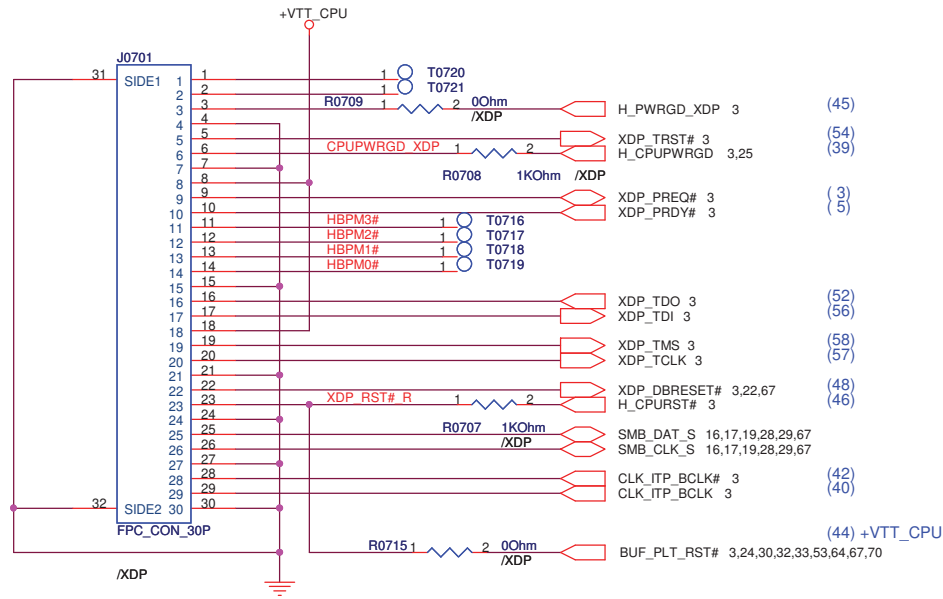
U0301I

VSS

NCTF

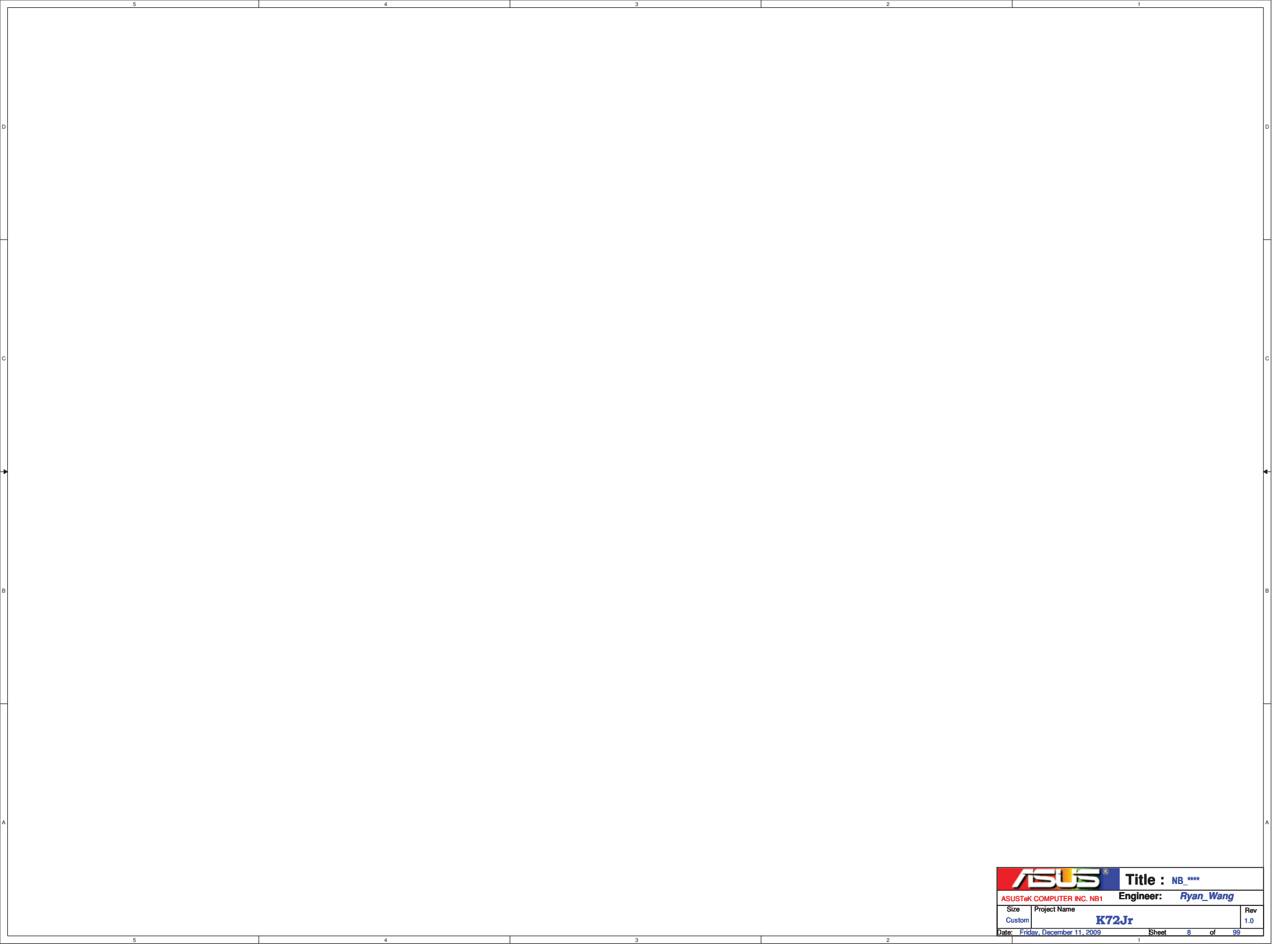
SOCKET989

CPU XDP connector

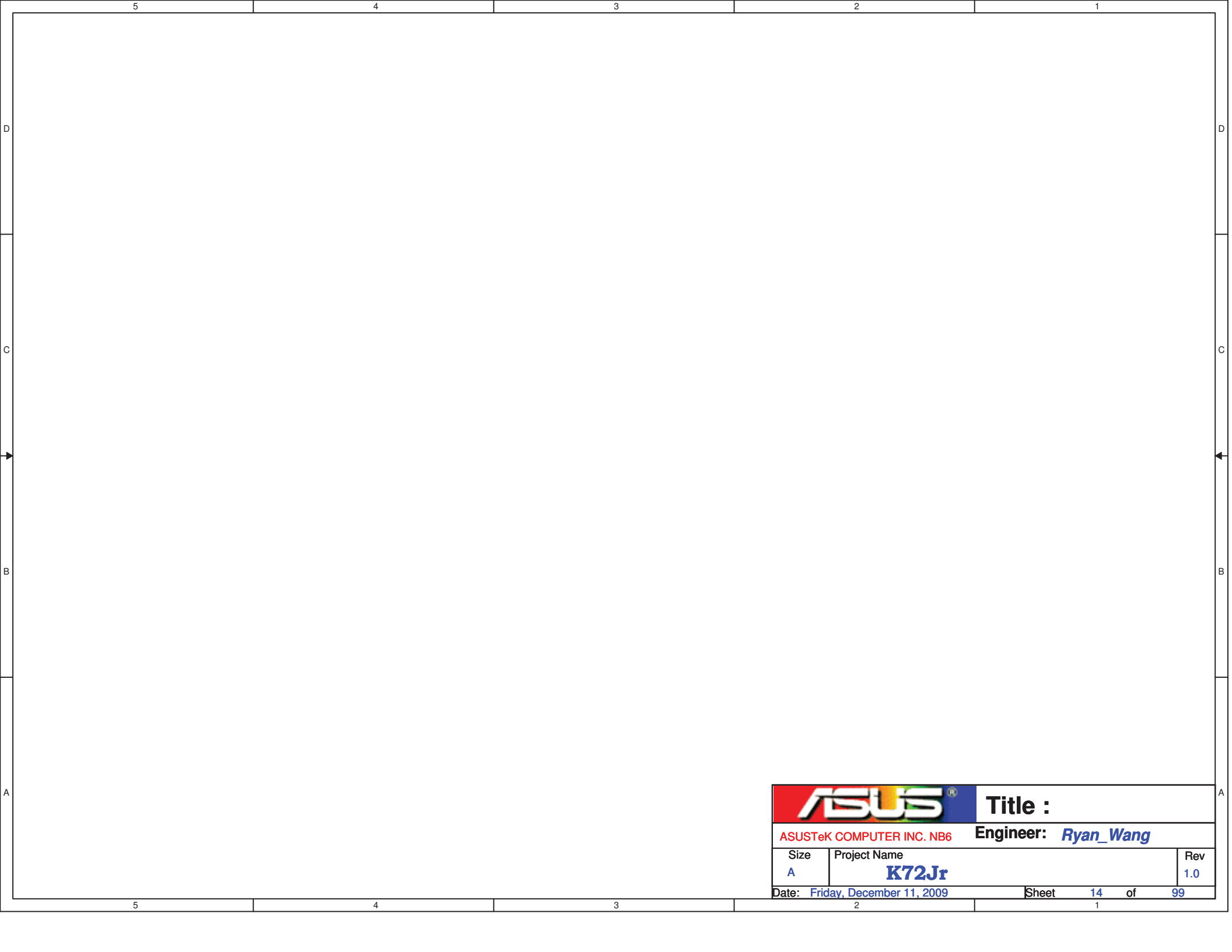


Put these test point near J0701.

Put it away from the FFC path.



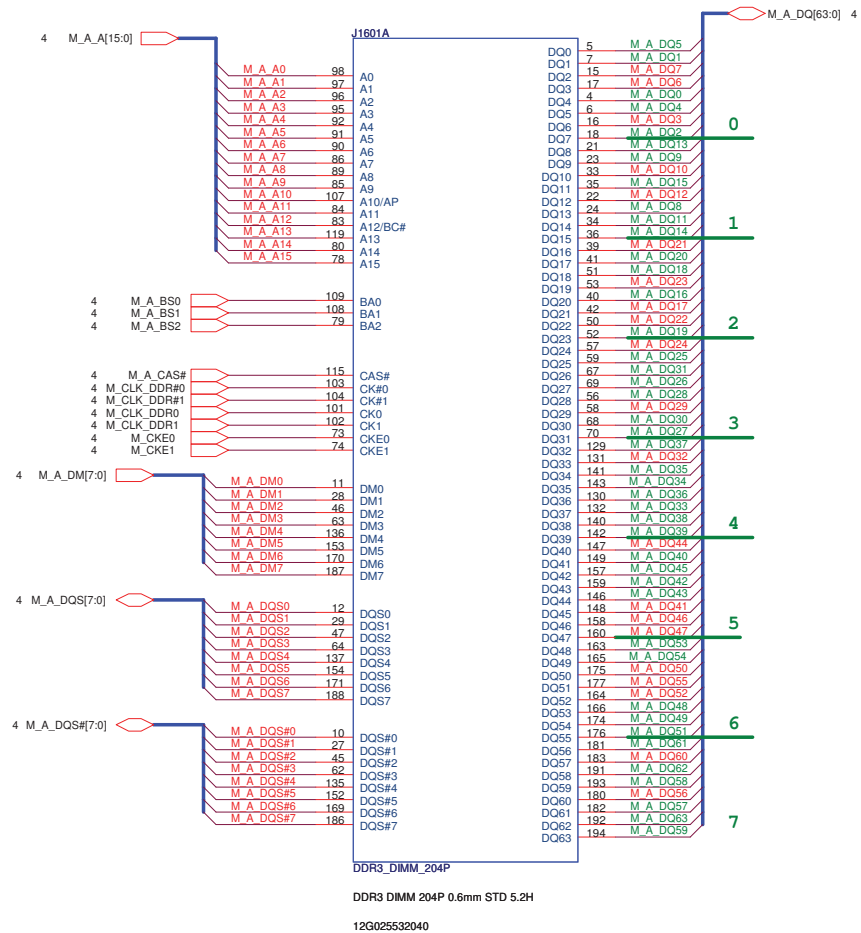
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ASUSTeK COMPUTER INC. NB1		Engineer: <i>Ryan_Wang</i>	
Size Custom	Project Name K72Jr		Rev 1.0
Date: Friday, December 11, 2009		Sheet	8 of 99



		Title :	
ASUSTeK COMPUTER INC. NB6		Engineer: <i>Ryan_Wang</i>	
Size A	Project Name K72Jr		Rev 1.0
Date: <i>Friday, December 11, 2009</i>		Sheet	<i>14</i> of <i>99</i>

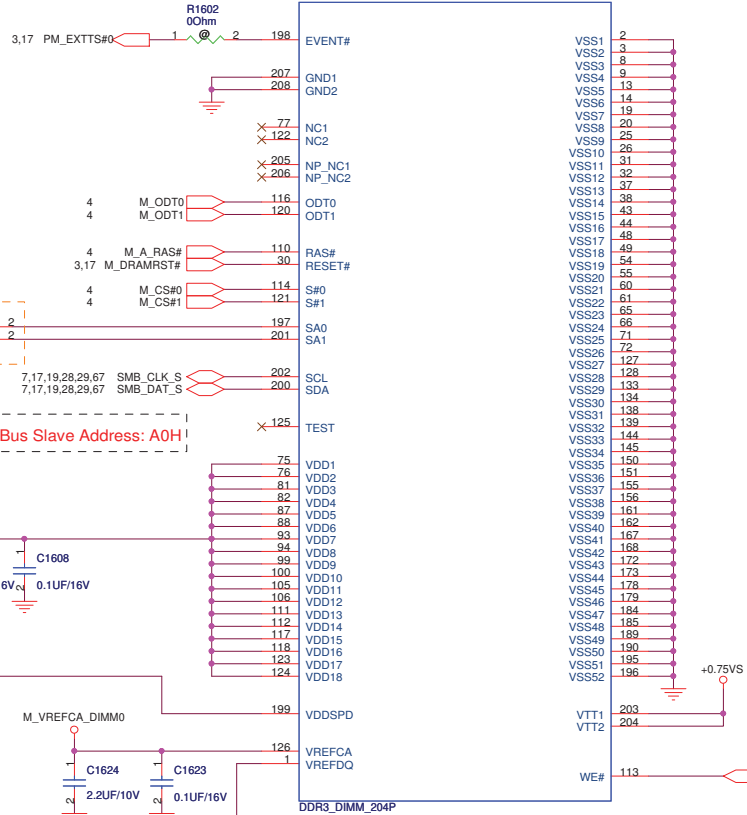
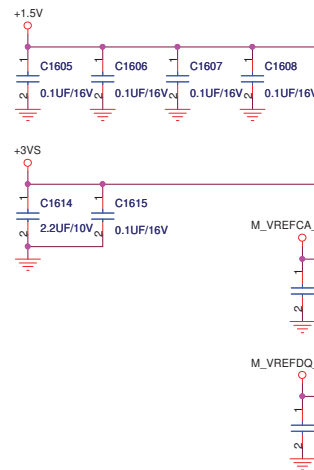
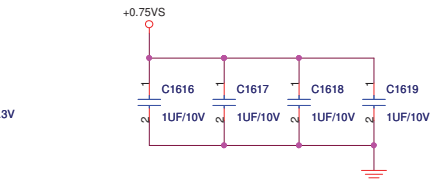
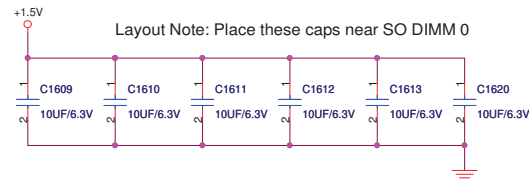
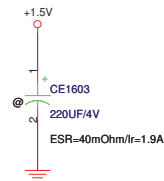
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D				D
C				C
B				B
A				A
5	4	3	2	1

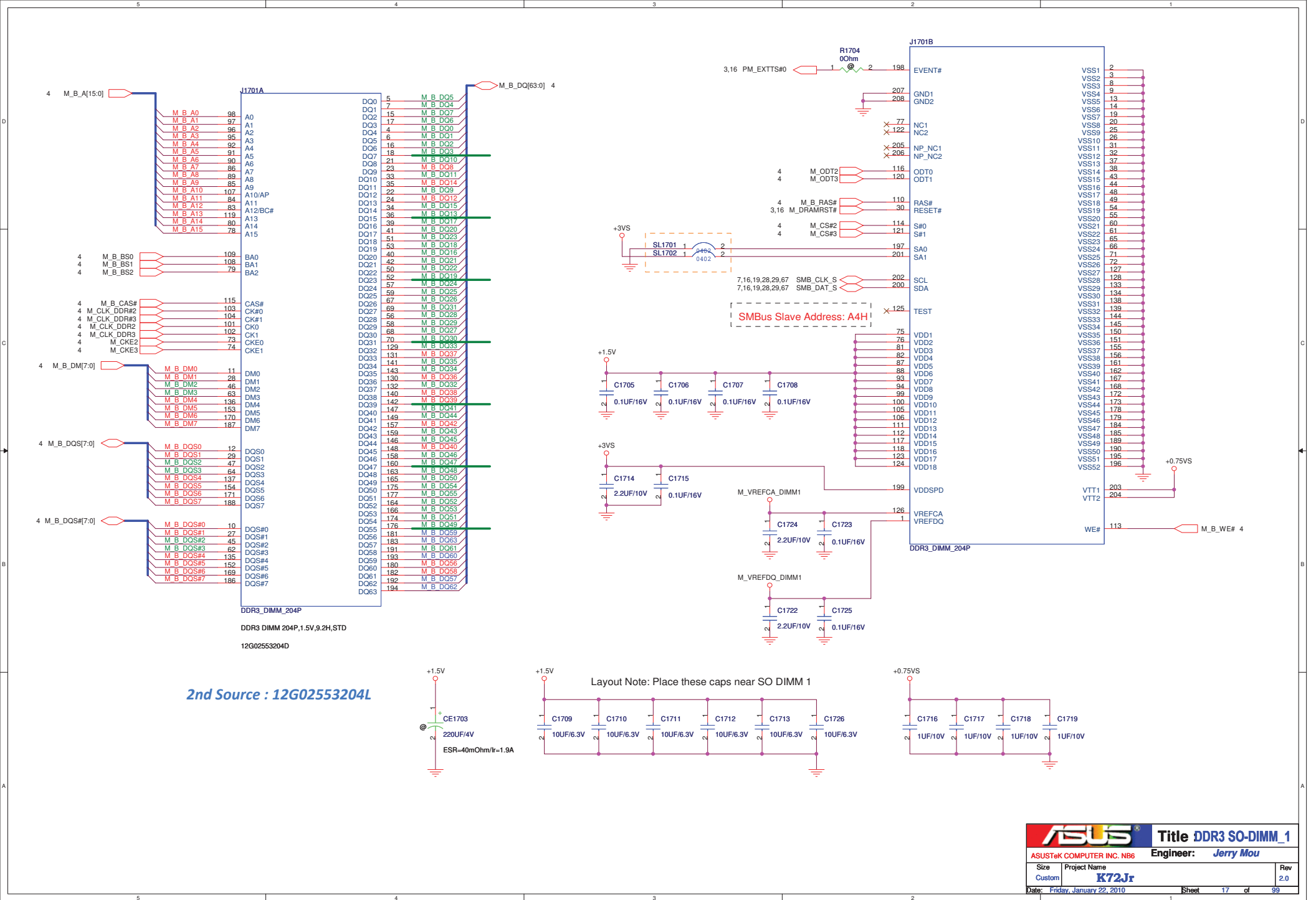
		Title :	
ASUSTeK COMPUTER INC. NB6		Engineer: <i>Ryan_Wang</i>	
Size A	Project Name K72Jr		Rev 1.0
Date: <i>Friday, December 11, 2009</i>		Sheet	15 of 99



Tyco new P/N : 12G02553204G

2nd Source : 12G02553204K

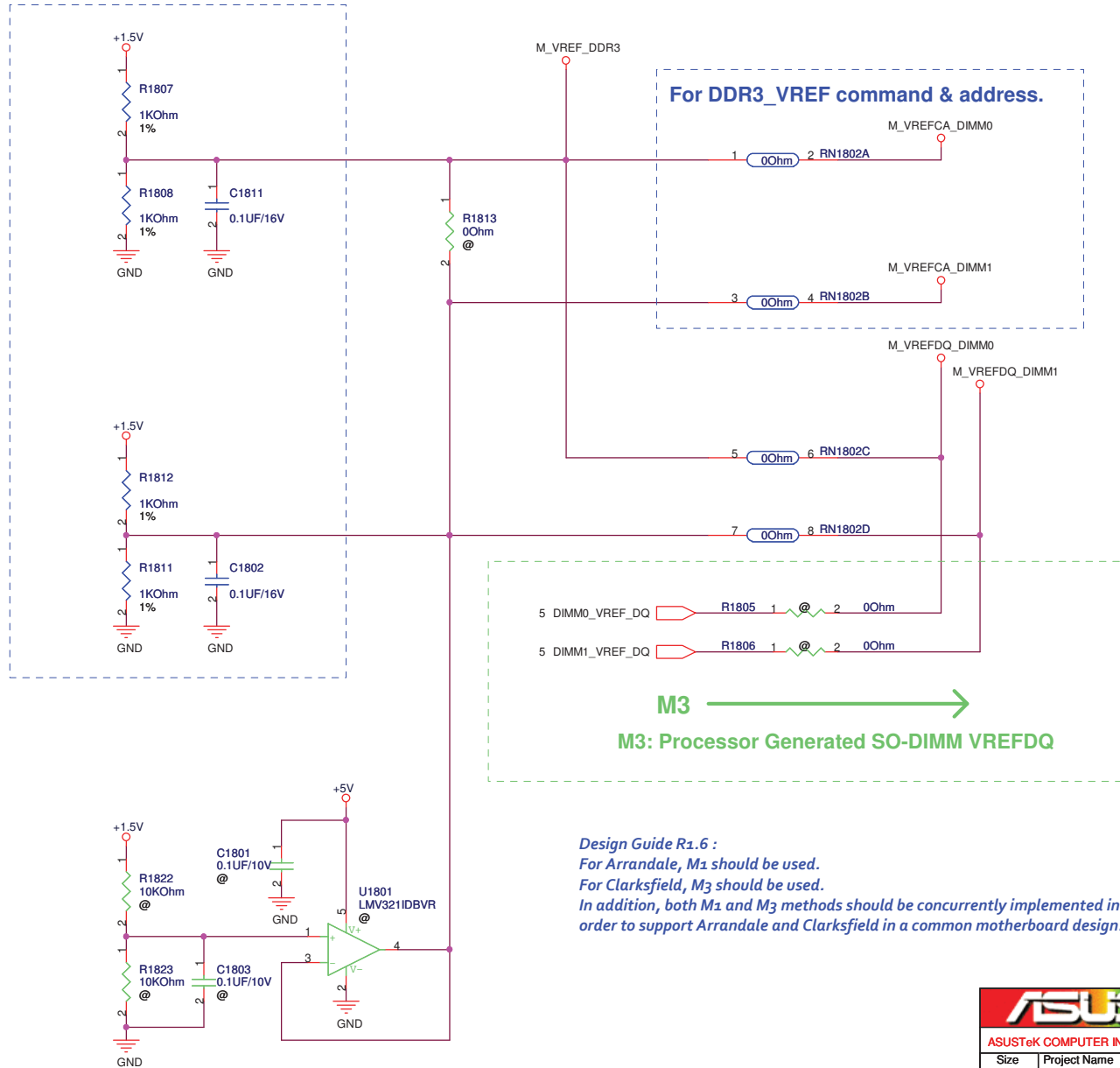


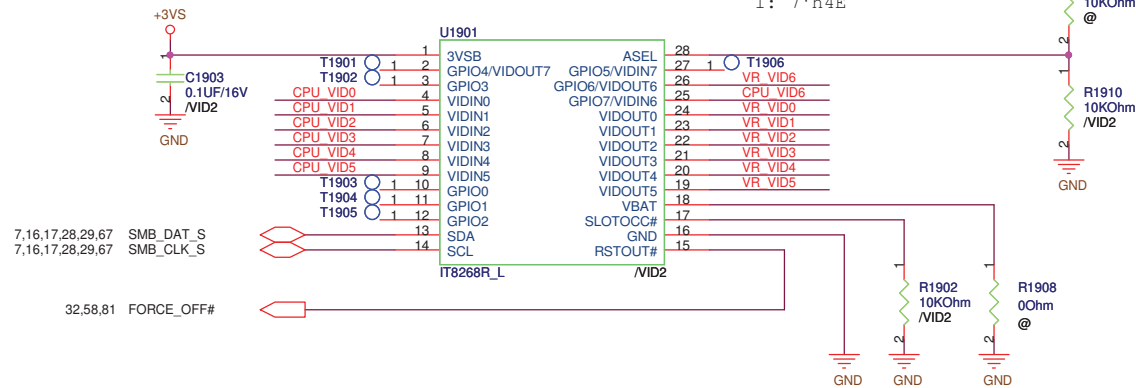
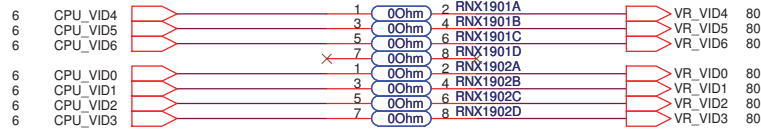
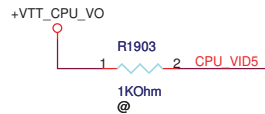


Default M1 

DDR3 Vref

Intel Document Number: 400755

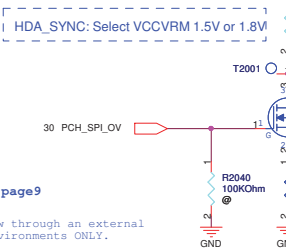
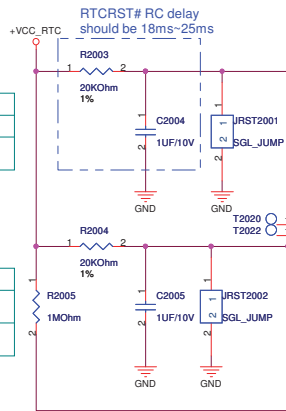




ASEL (Address Select)
0: 7'h37
1: 7'h4E

CMOS Settings	JRST2001
Clear CMOS	Shunt
Keep CMOS	Open (Default)

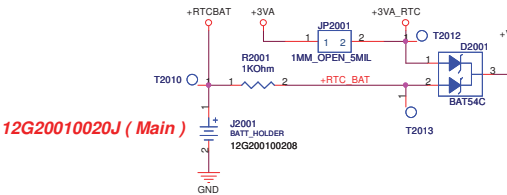
TPM Settings	JRST2002
Clear ME RTC Registers	Shunt
Keep ME RTC Registers	Open (Default)



414044 Design Guide R1.11 Update: page9

GPIO33:
This signal should be only asserted low through an external pull-down in manufacturing or debug environments ONLY.

Without connecting GPIO33, customers may not be able to override SPI flash contents.



12G20010020J (Main)

Strap information:

HDA_SPKR: No reboot strap
Low: Disable.
High: Enable

HDA_DOCK_EN#:
1. Flash descriptor security:
Sampled low: override
Sampled high: in effect.
2. GPIO33 low on the rising edge of PWROK,
Will also disable Intel ME.

SPI_MOSI: iTPM strap.
Mount R2015: Enable
Unmount R2015: Disable(default)

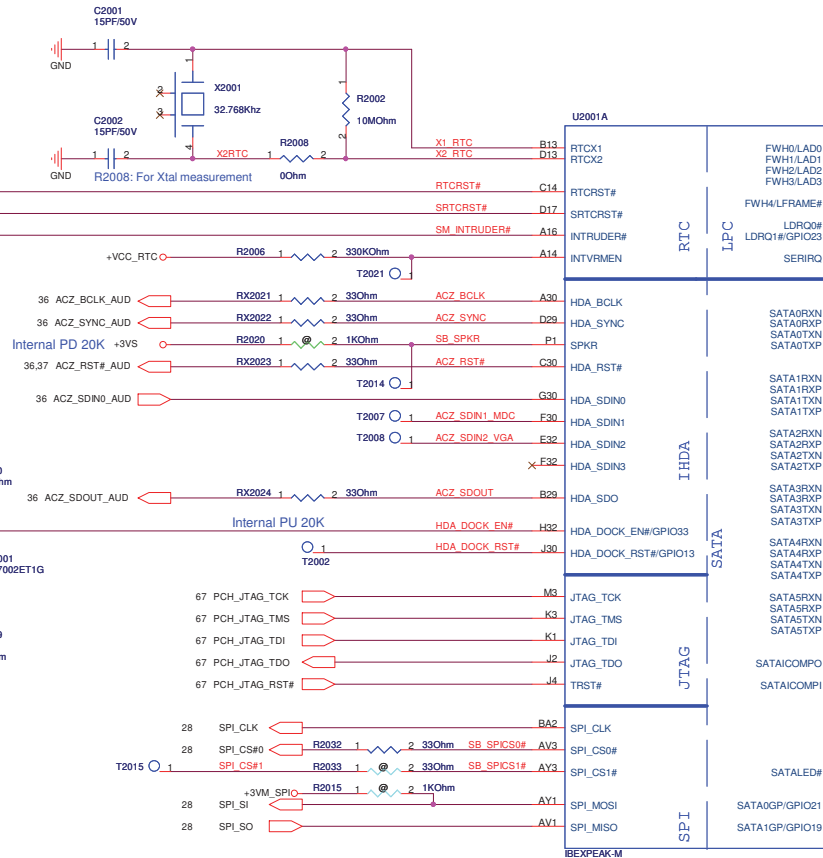
MoW 11, 2009 :

Ibex peak JTAG and Ibex Peak Test Interface requirements

For pre-production systems, please refer to the latest Calpella Platform Debug Port Design Guide (Doc #385422)

		Pre-Production Systems		Production Systems
PCH Pin	RefDes	ES1	ES2	
TDO	R1	No Stff	200 Ohms	No Stuff
	R2	No Stff	100 Ohms	No Stuff
	R3	200 Ohms	200 Ohms	No Stuff
TMS	R4	100 Ohms	100 Ohms	No Stuff
	R5	200 Ohms	200 Ohms	No Stuff
	R6	100 Ohms	100 Ohms	No Stuff
TCK	R7	51 Ohms	51 Ohms	51 Ohms
	R8	20K Ohms	Not Applicable ¹	Not Applicable ¹
	R9	10K Ohms	Not Applicable ¹	Not Applicable ¹

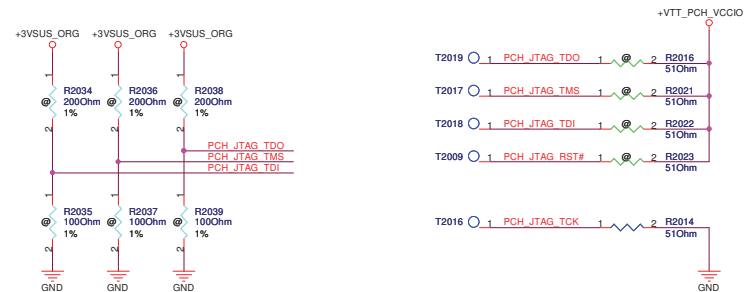
Note 1: For IBX ES2 and later, TRST# does not require an external pull-up; but should be routed to a test point pad for PCH JTAG debug purposes



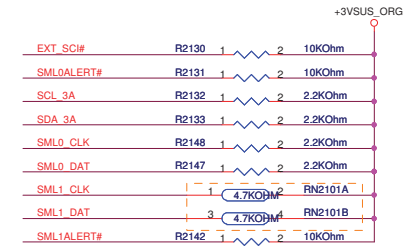
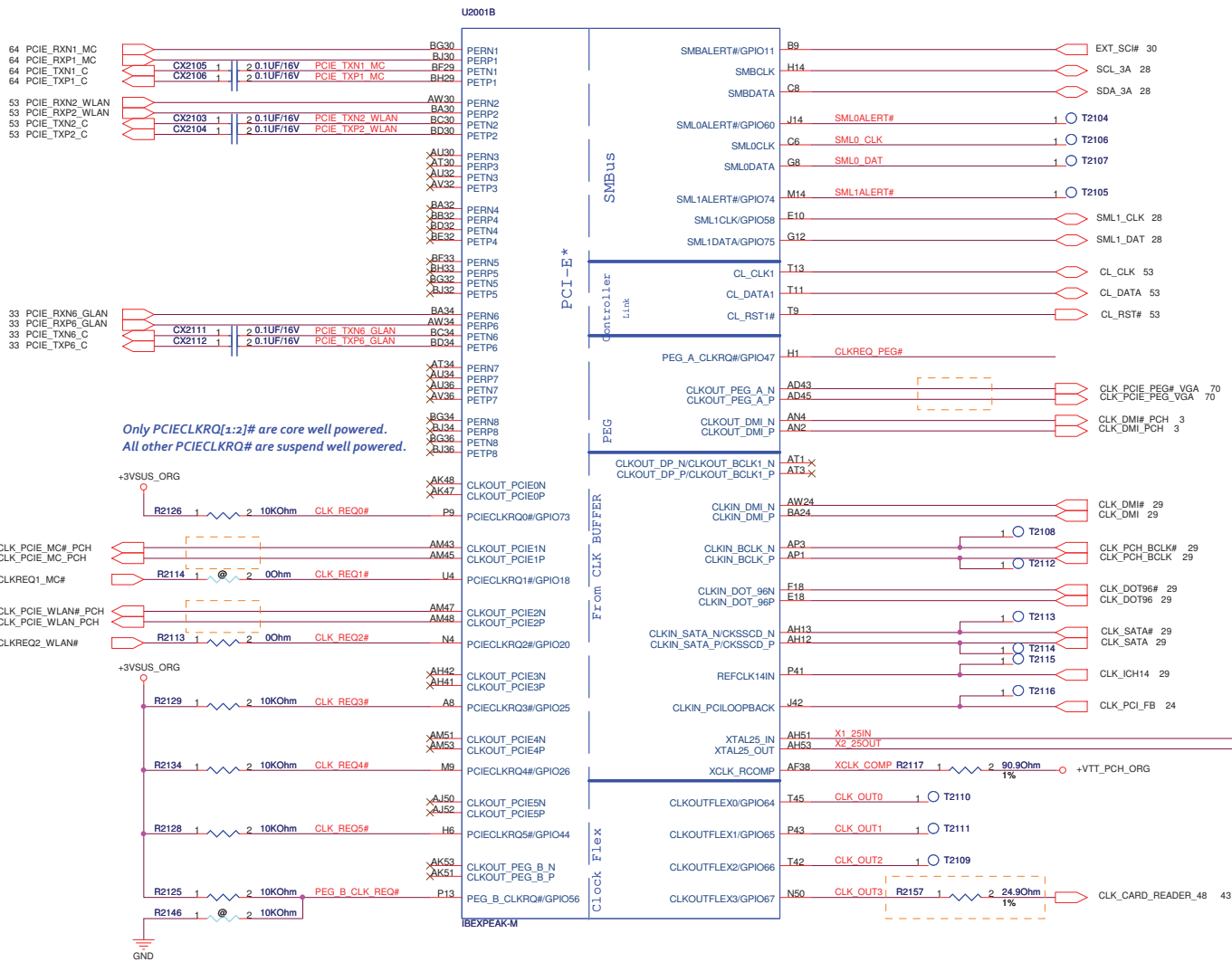
02G010026101

C.S BD82HM55 904127

GA INT IBEXPEAK HM55

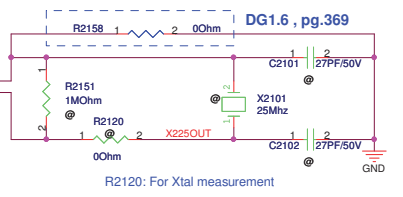
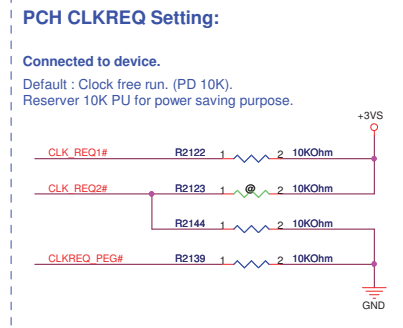


ASUS		Title : PCH - SATA,HDA	
ASUSTek COMPUTER INC. N96		Engineer: Jerry Mou	
Size	Project Name		Rev
Custom	K72Jr		2.0
Date: Friday, December 11, 2009		Sheet 20 of 99	

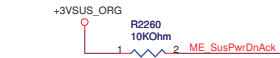


DG R1.1, page 43:

The pull-up resistor value for SML0DATA and SML0CLK has been updated from 4.7 K $\pm$ 5% to 2.2 K $\pm$ 5% to support 400-kHz bus speed



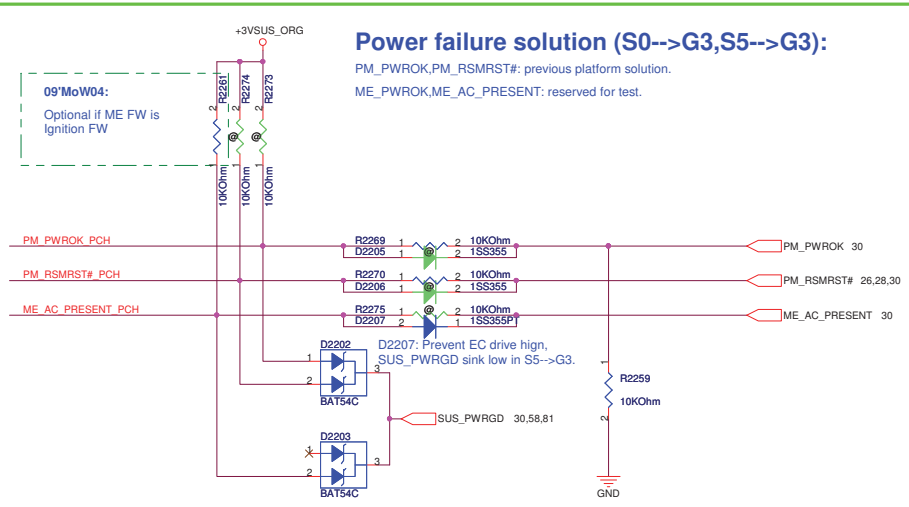
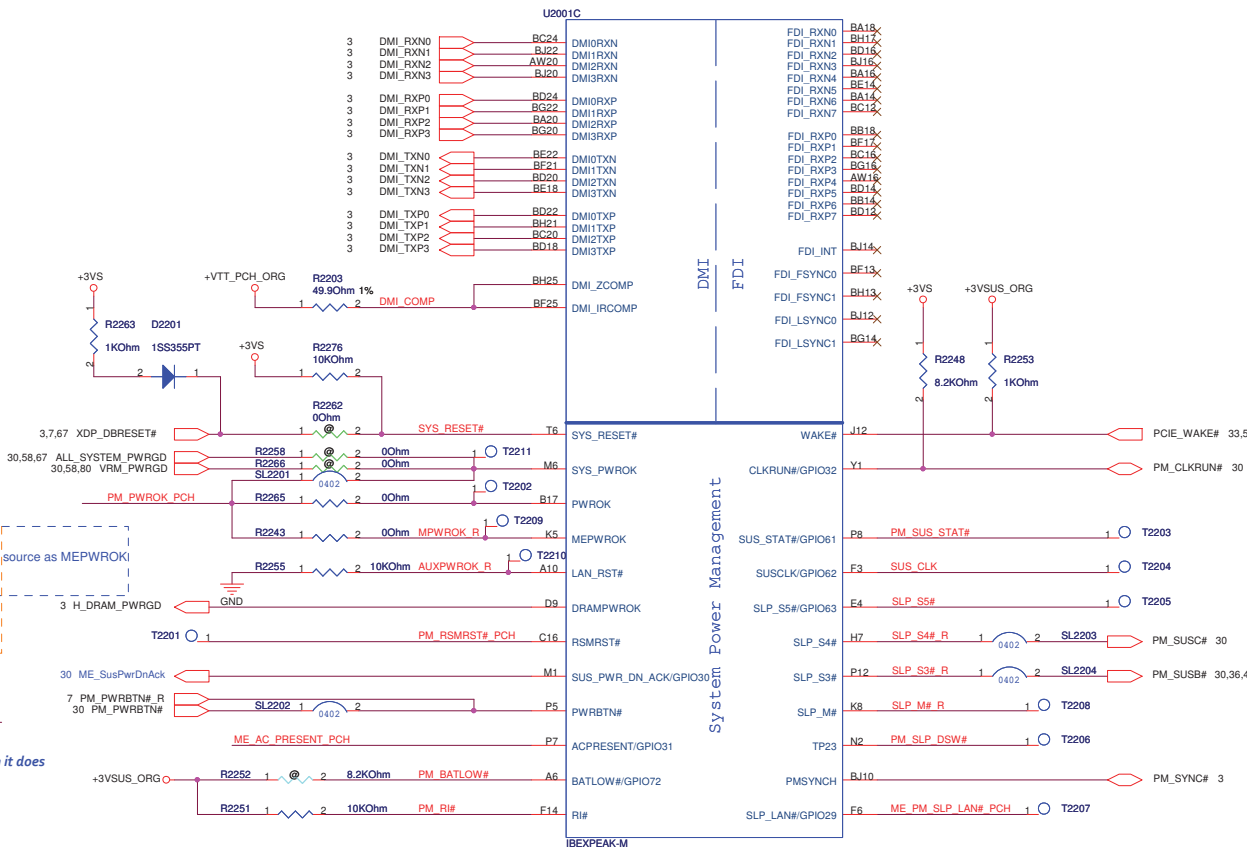
EDS 1.0: Intel LAN
Enabled : LAN_RST# connected to the same source as MEPWROK
Disabled : LAN_RST# must be grounded
Disabled : SLP_LAN#->NC.
P27. Disabled : VCCLAN connected to GND.

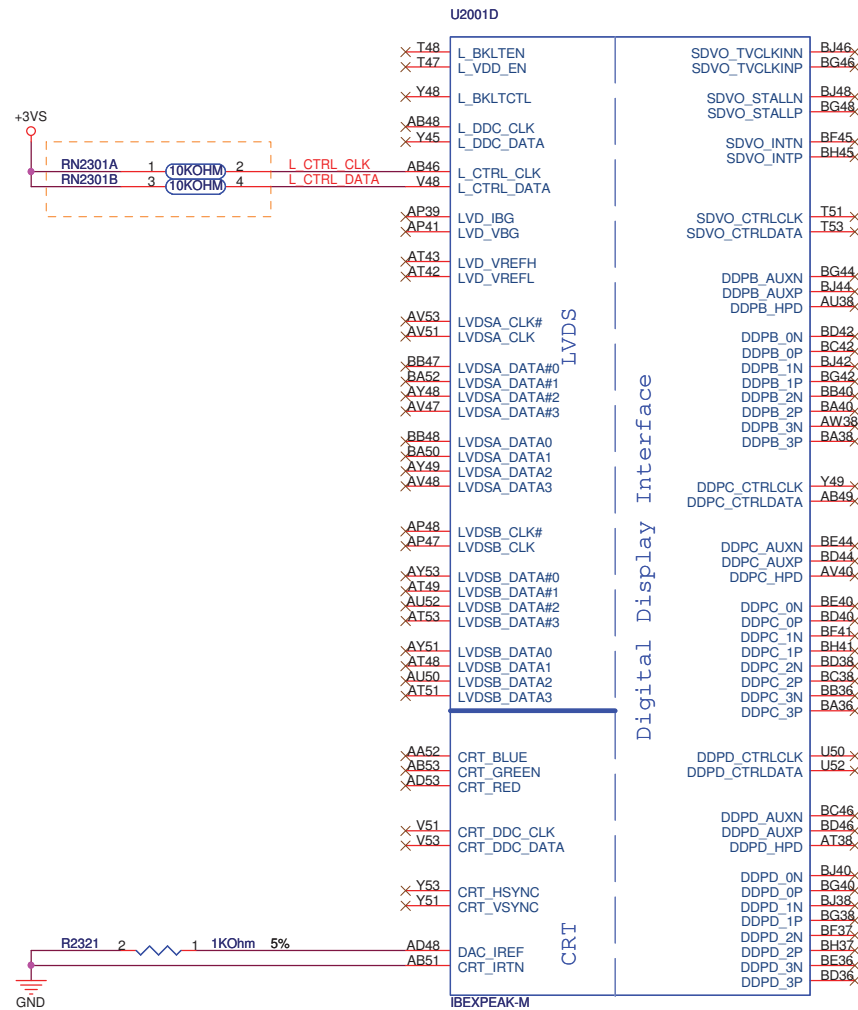


SUS_PWR_DN_ACK :
Active high. Asserted by Intel ME when it does not require the PCH Suspend well to be powered.

ACPRESENT :
Active high. Asserted by EC when the platform is connected to an AC source.

MoW z6 , 2009 :
The minimum time from WLAN device power valid until MEPWROK assertion is 20 mSecs.





Port	Strap	How to enable the port	How to Disable the Port
LVDS	L_DDC_DATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
Port B	SDVO_CTRLDATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
Port C	DDPC_CTRLDATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
Port D	DDPD_CTRLDATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
eDP on CPU	CFG[4]	Pulled the signal down to the GND through a 3.3K ohm resistor	NC

GNT0#,GNT1#: Boot BIOS Strap.

Boot BIOS Strap

PCI_GNT1#	PCI_GNT0#	Boot BIOS Location
0	0	LPC
0	1	PCI
1	0	Reserved
1	1	SPI (PCH)

Sampled on rising edge of PWROK.



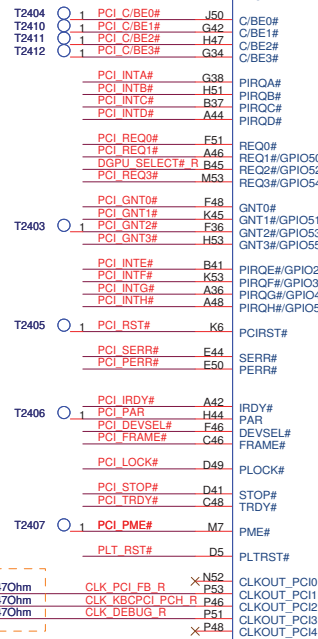
GNT3#: A16 swap override Strap/ Top-Block swap override jumper

Low=Enabled A16 swap override/
Top-Block swap override

High=Default

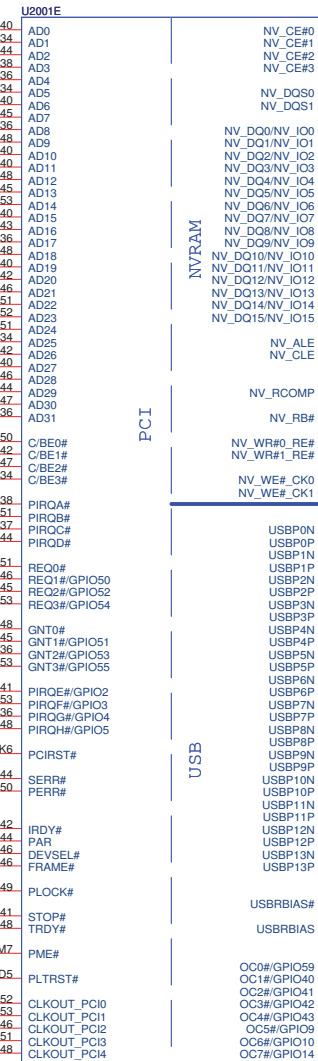


K72J	
0	USB port
1	USB port
2	USB port (D/B)
3	USB port (D/B)
4	
5	MiniCard (Full)
6	
7	
8	MiniCard (Half)
9	Camera
10	
11	Card Reader
12	Bluetooth
13	



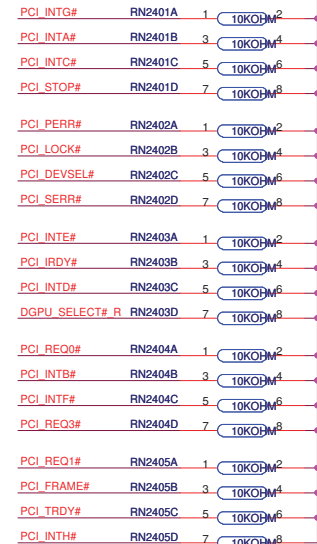
PCI

USB



PCI

USB



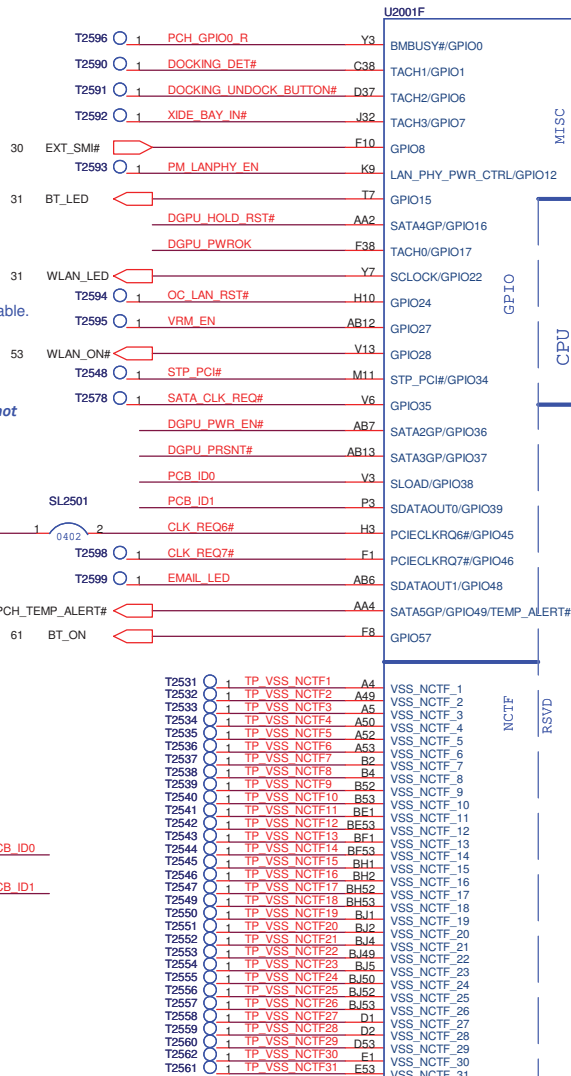
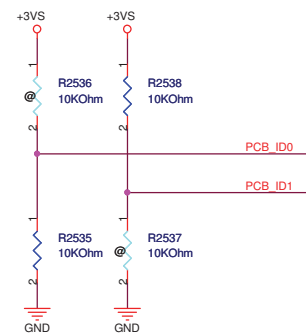
MoW 02 , 2009
Intel recommends that customers do not perform USB or SATA Signal Quality testing at this time. Ibox Peak Sightings Report Rev. 004 contains a new sighting about USB Eye Diagram Failure. A similar sighting about SATA will be available in the next sightings report release. Customers may begin Signal Quality testing on PCIe.

GPIO 15: Default internal PD 20K.

GPIO 27: Enable VCCVRM, Low=disable.
Default internal pull up.

GPIO 28: Default internal PU 20K.

MoW 50, 2008 :
SATACLKREQ# protocol not
supported on Ibox Peak.



MISC

GPIO

CPU

NCTF

RSVD

IBEXPEAK-M

CLKOUT_BCLK0_N/CLKOUT_PCIE8N

CLKOUT_BCLK0_P/CLKOUT_PCIE8P

PECI

RCIN#

PROCPWRGD

THRMTRIP#

TP1

TP2

TP3

TP4

TP5

TP6

TP7

TP8

TP9

TP10

TP11

TP12

TP13

TP14

TP15

TP16

TP17

TP18

TP19

NC_1

NC_2

NC_3

NC_4

NC_5

INIT3_3V#

TP24

CLKOUT_PCIE8N
CLKOUT_PCIE8P

CLKOUT_PCIE7N
CLKOUT_PCIE7P

A20GATE

BCLK_CPU_N_PCH 3

BCLK_CPU_P_PCH 3

H_PECI 3

RCIN# 30

H_CPUPWRGD 3,7

H_THRMTRIP# 3

EXT_SMI#

DGPU_PWR_EN#

DGPU_HOLD_RST#

PCH_TEMP_ALERT#

DGPU_PRSTNT#

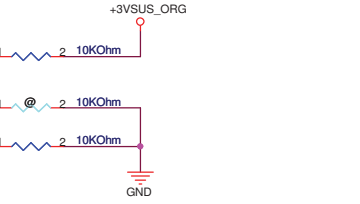
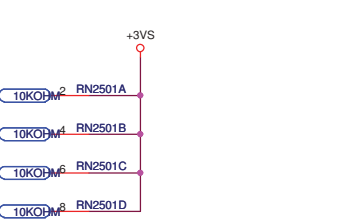
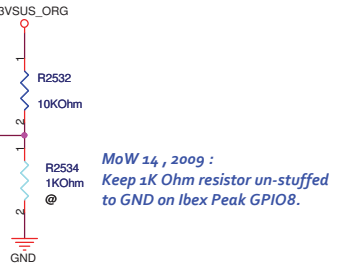
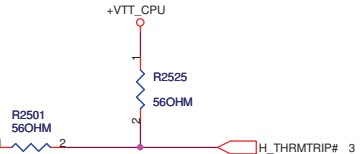
CLKREQ#

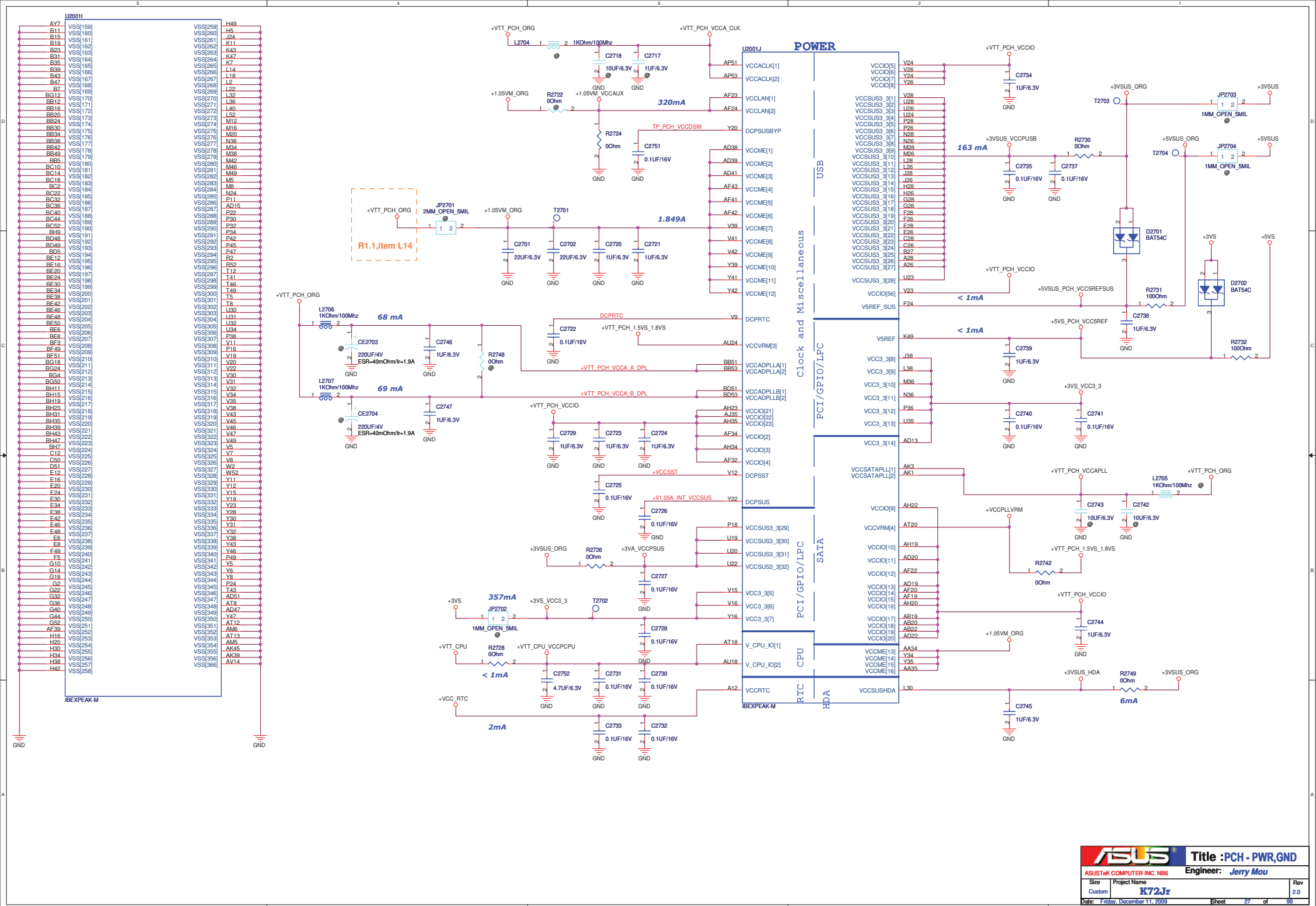
DGPU_PWROK

SATA_CLK_REQ#

INT3_3V#

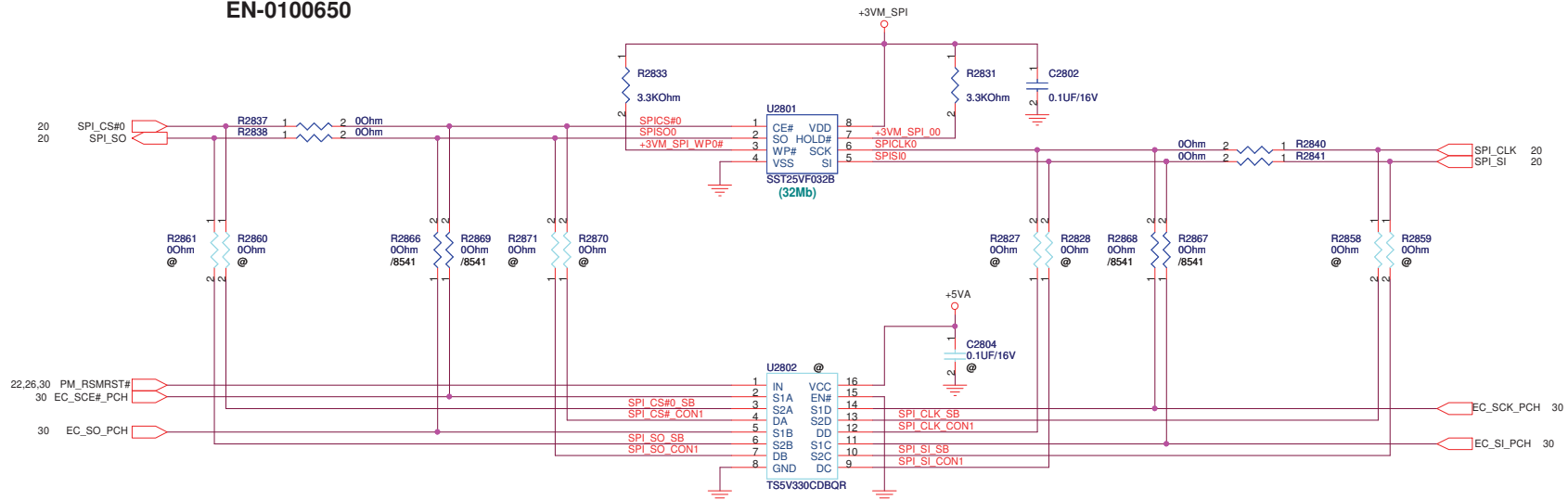
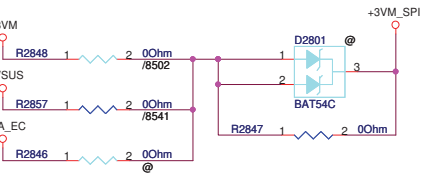
TP_PCH_SST





PCH SPI ROM

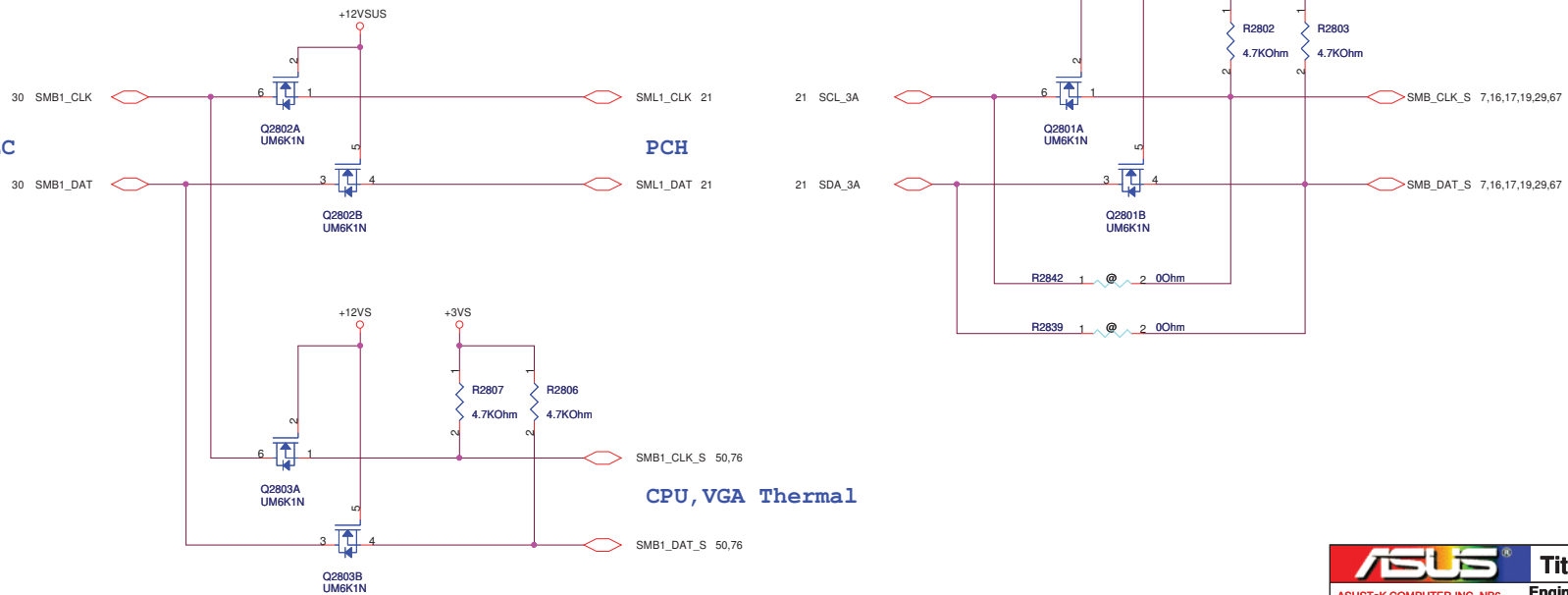
EN-0100650



EC

PCH

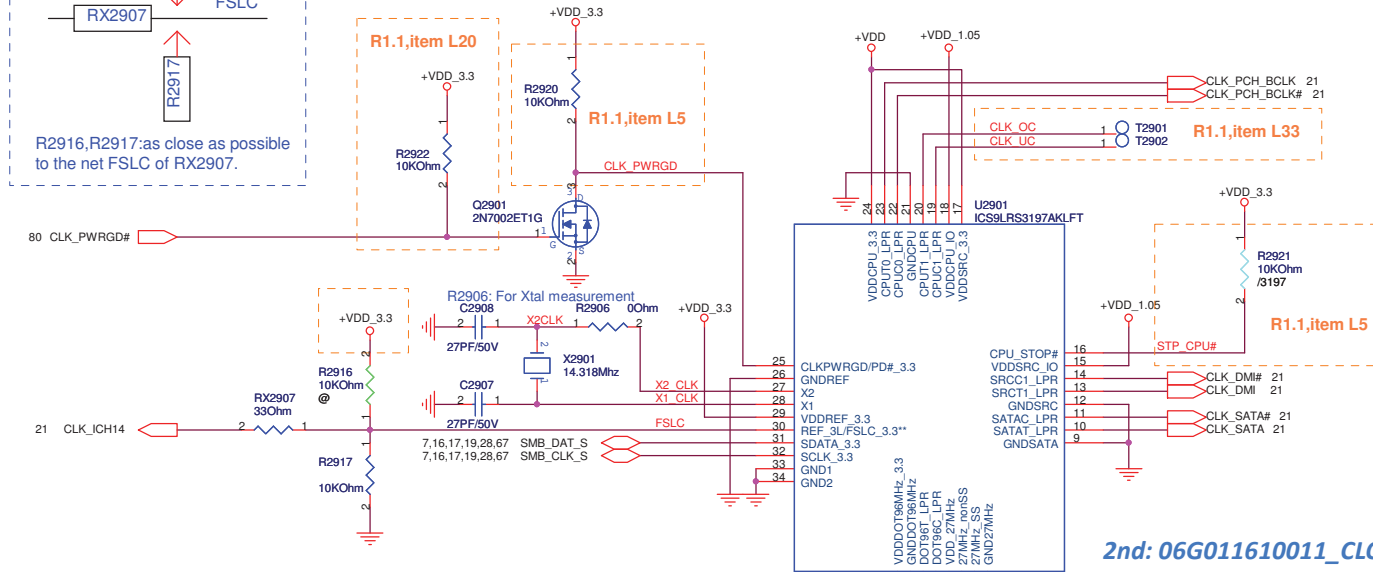
CPU, VGA Thermal



Layout note:

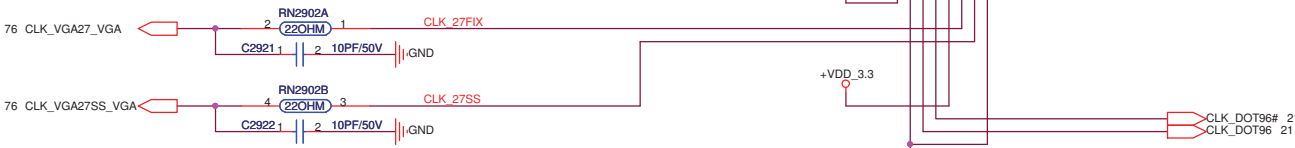
R2916, R2917: as close as possible to the net FSLC of RX2907.

BCLK	FSLC
133	0
100	1



3162 Pin16 : T-track

2nd: 06G011610011_CLOCK GEN 3162B(A改成B)

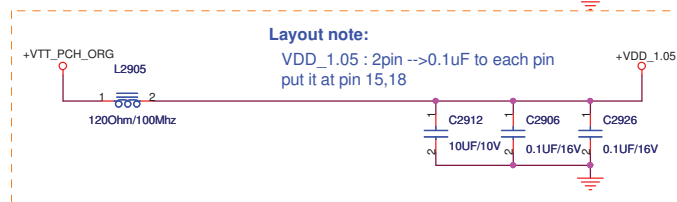


Layout note:
VDD_3.3: 5pin --> 0.1uF to each pin
put it at pin 5,29

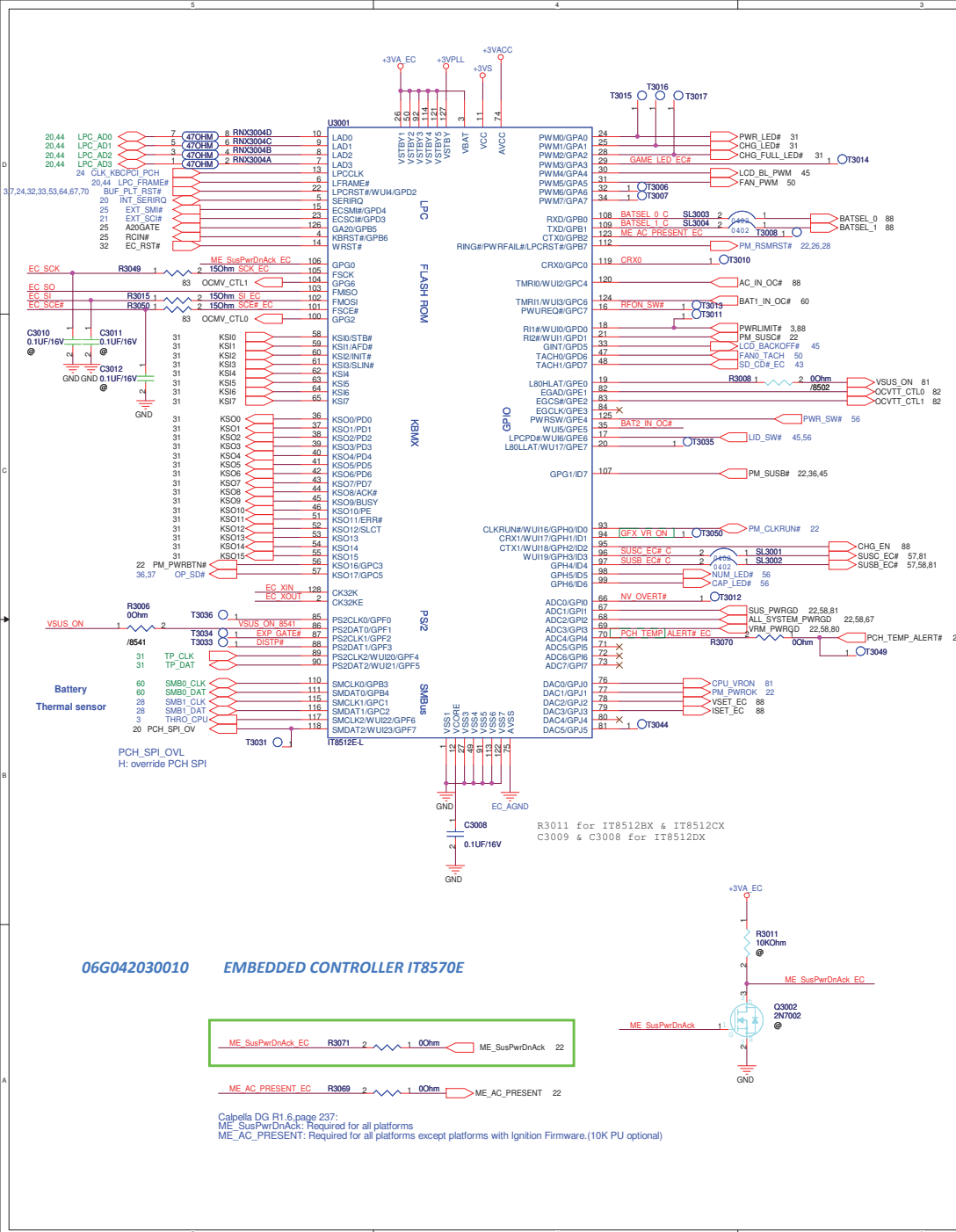
9LRS3197----mount L2904,unmount L2903

9LVS3162----mount L2903,unmount L2904,R2921

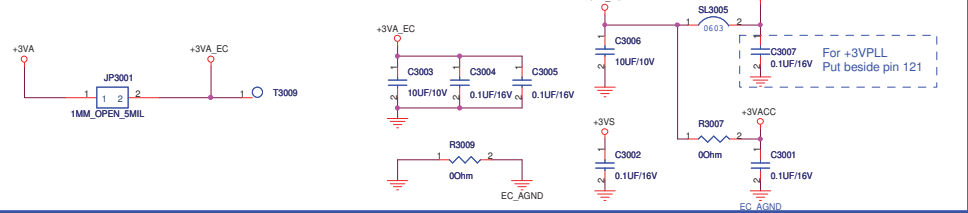
Layout note:
VDD: 3pin --> 0.1uF to each pin
put it at pin 1,17,24



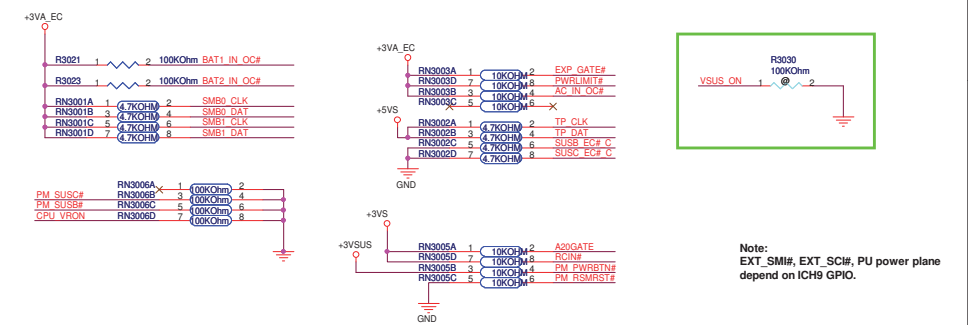
Layout note:
VDD_1.05 : 2pin --> 0.1uF to each pin
put it at pin 15,18



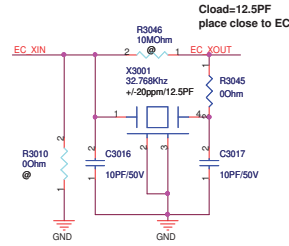
For IT8752 Power



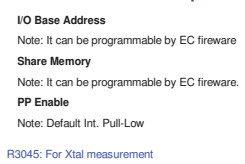
For PU / PD



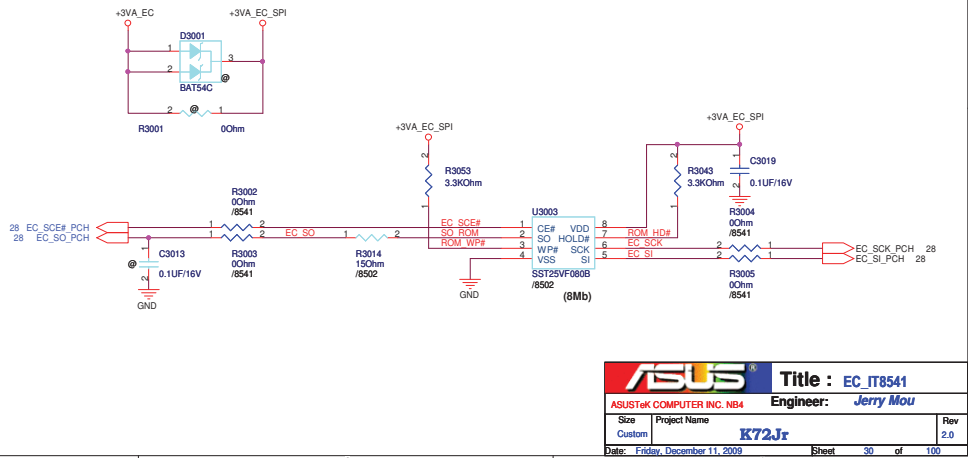
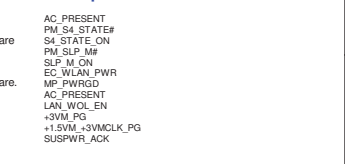
For X'tal

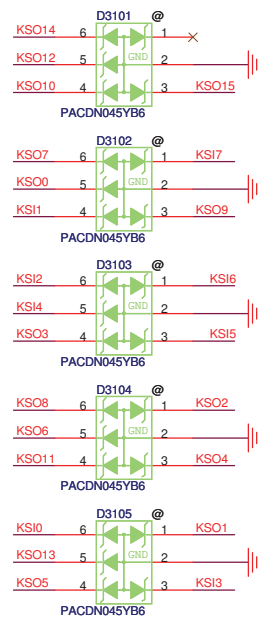


For EC Hardware Strap

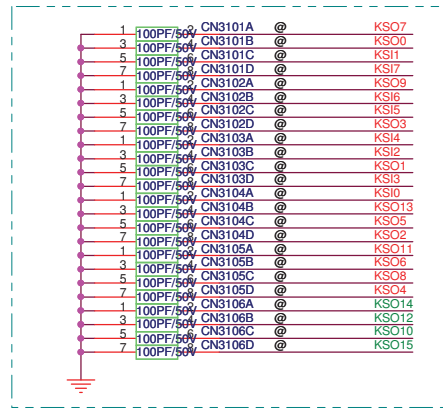


For iAMT pin name



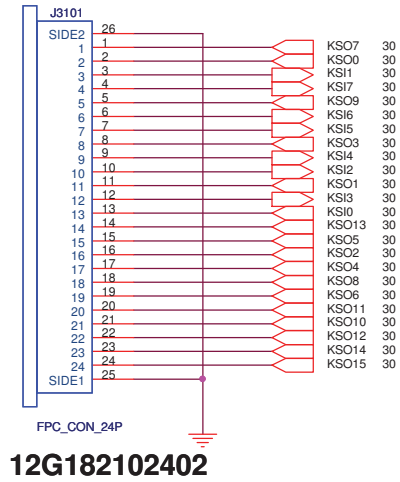


EMI



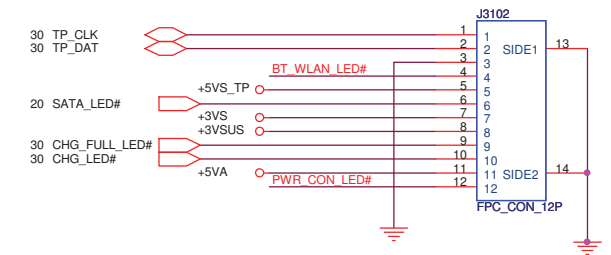
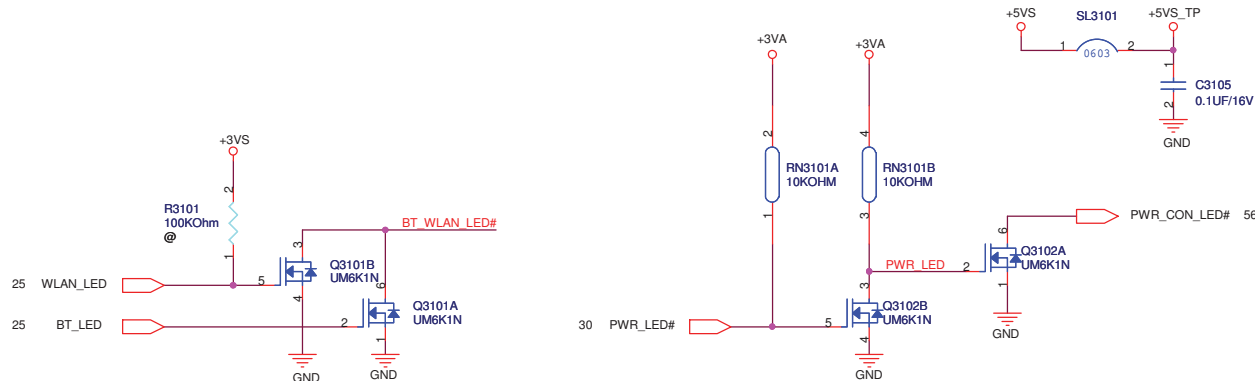
Keyboard

TOP connector 下接觸
PIN1上面 KSO7 ; 下面 KSO24



12 Pin Touch-Pad Conn.

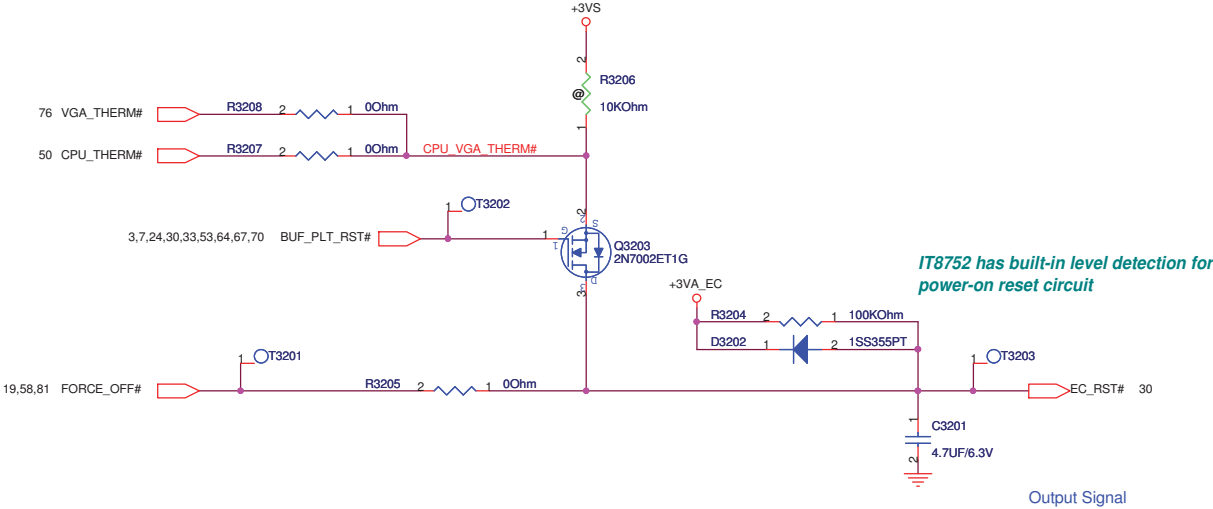
TP M/B TOP 上接觸 PIN1 左邊 CLK ; TP
SMALL BOTTOM 下接觸. Cable 折兩次



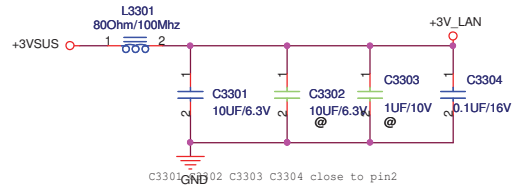
12G18340120C

ASUS		Title : EC_IT8541(2/2)KB, TP	
ASUSTek COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet 31 of 100	

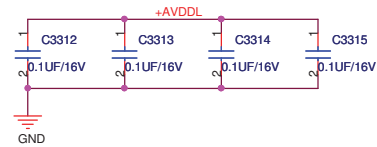
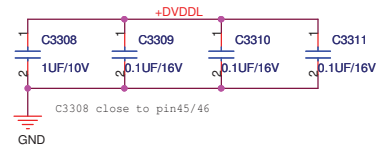
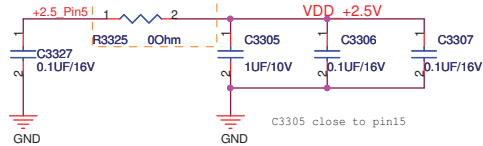
Thermal Policy



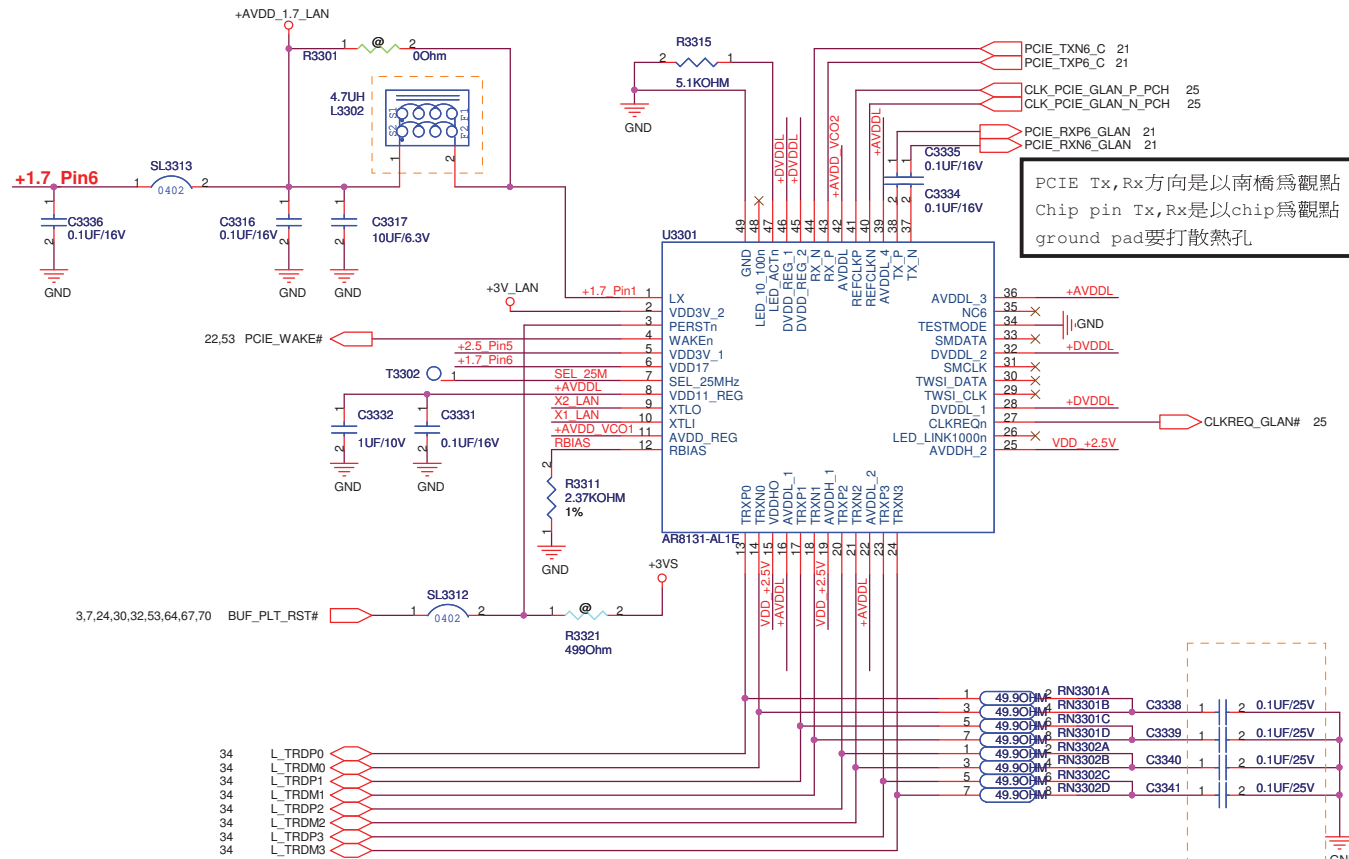
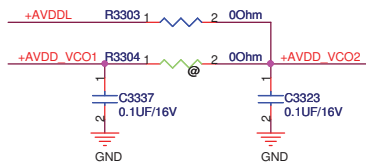
R1.1,item L34



For Design IP: R3325: 0 Ohm

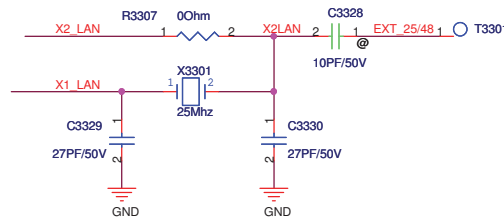


AR8131 with overclock: Remove R3315, R3303
Not overclock: Remove R3304

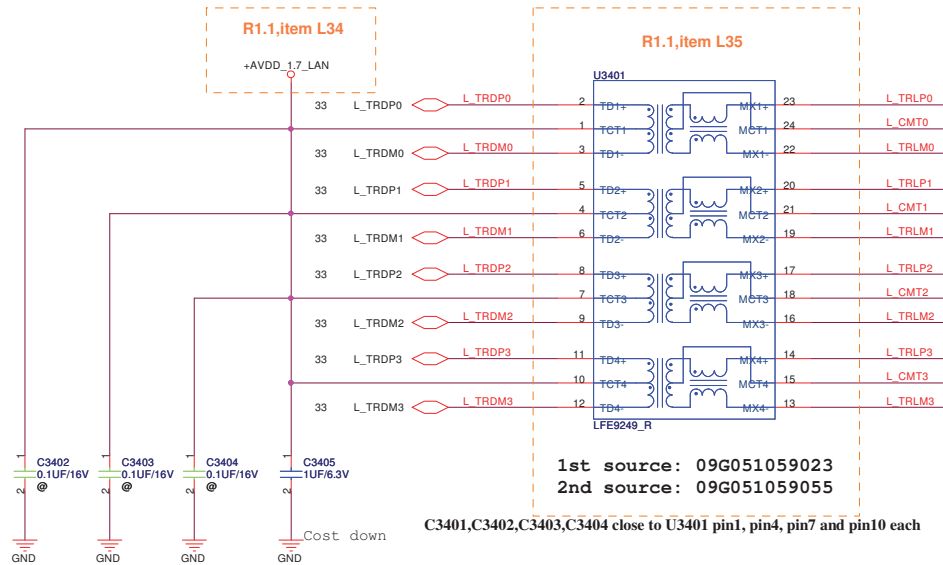


PCIE Tx, Rx方向是以南橋為觀點
Chip pin Tx, Rx是以chip為觀點
ground pad要打散熱孔

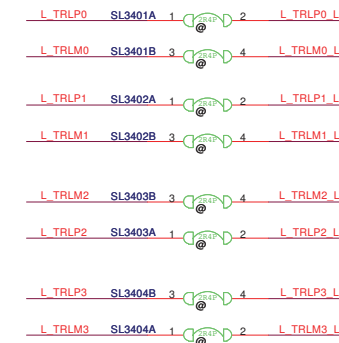
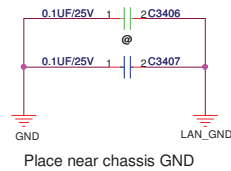
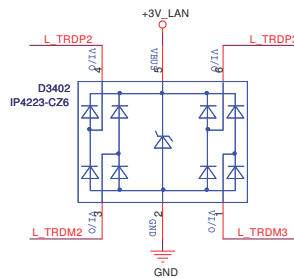
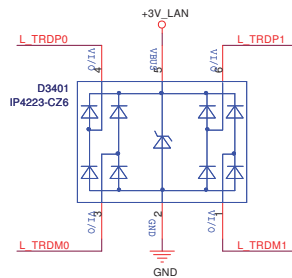
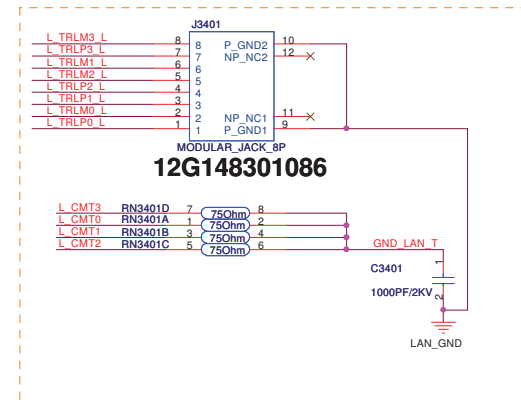
AR8131/25MHz: Remove C3328

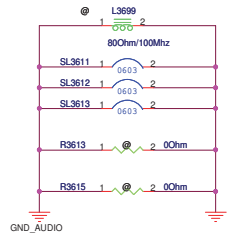


ASUS		Title : LAN-AR8131	
ASUSTek COMPUTER INC. NB4		Engineer: Jerry Mou	
Size B	Project Name K72Jr	Rev 2.0	
Date: Friday, December 11, 2009	Sheet	33	of 100



connector without modem





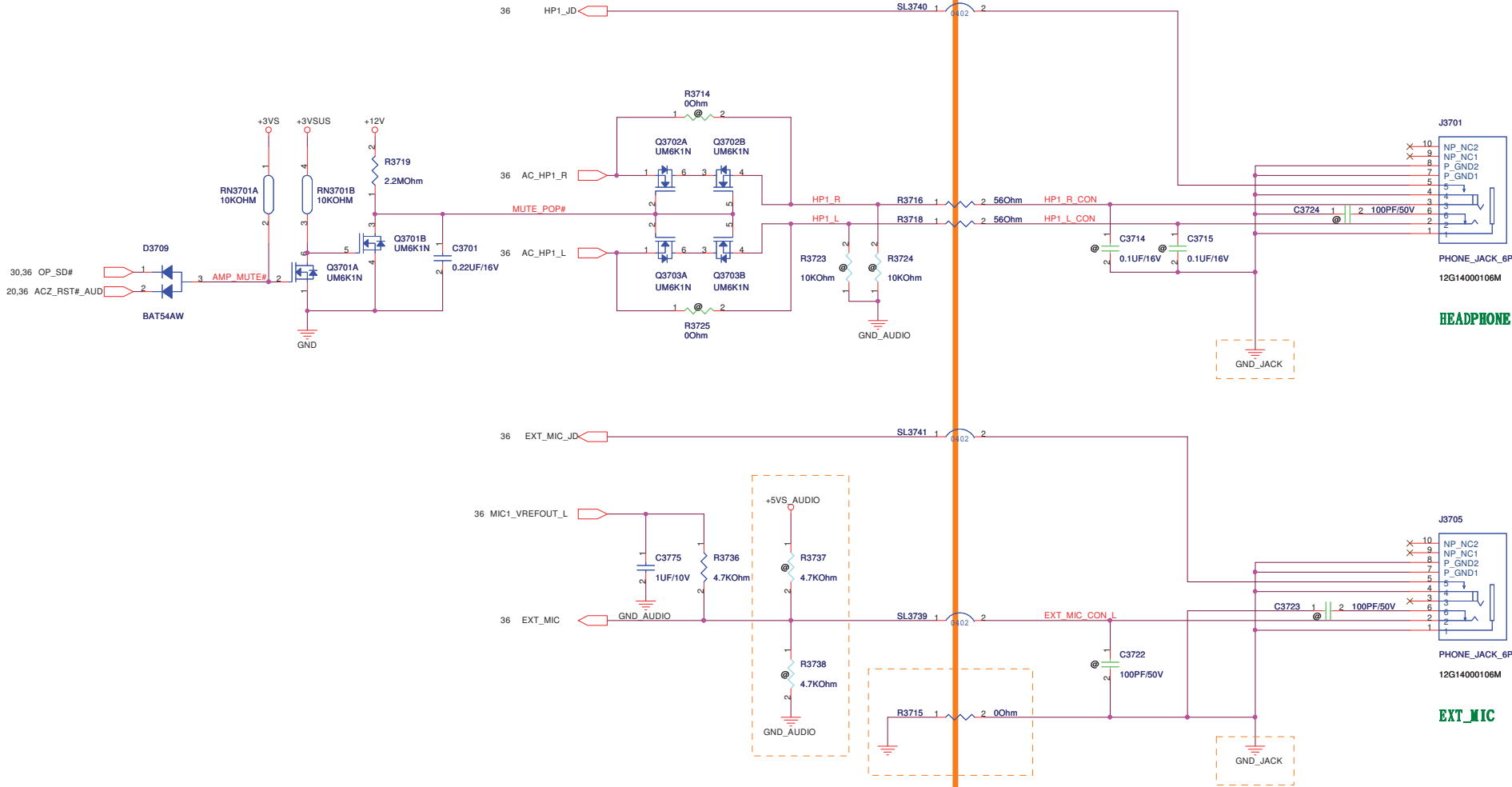
FOR ADJUST MODE:

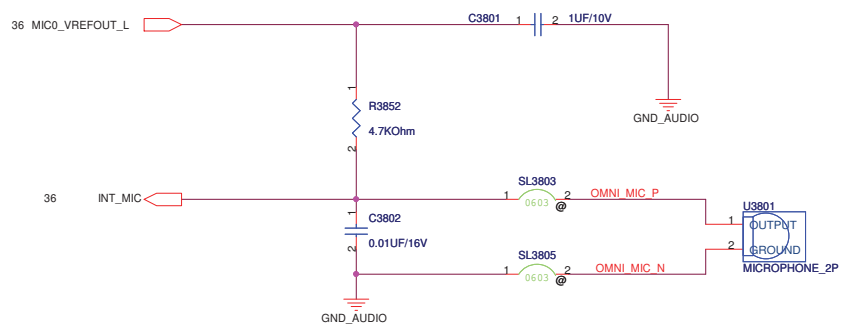
$$V_o = 1.25 * (1 + R_{2506} / R_{2505})$$

$$= 1.25 * (1 + 100K / 34.8K) = 4.84$$

The schematic diagram illustrates the audio input circuit for the ESP32. It features a +5V_AUDIO supply connected to a 2.49KOhm resistor (R3686). The other end of the resistor is connected to a node labeled SENSE_A. This node is also connected to a 0.1uF/16V capacitor (C3647), which is connected to GND_AUDIO. The SENSE_A node is further connected to a 10KOhm resistor (R3629). The other end of R3629 is connected to the EXT_MIC_ID pin (37) and the HP1_ID pin (37). The circuit is also labeled SENSE_B.

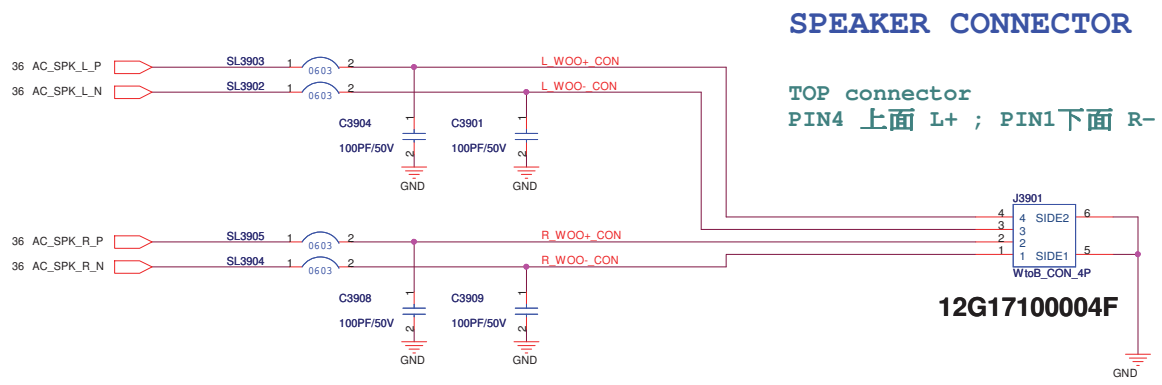
ASUS		Title : CODEC IDT92HD81	
ASUSTeK COMPUTER INC. NB2		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr	Rev 2.0	
Date: Friday, December 11, 2009	Sheet	36	of 100

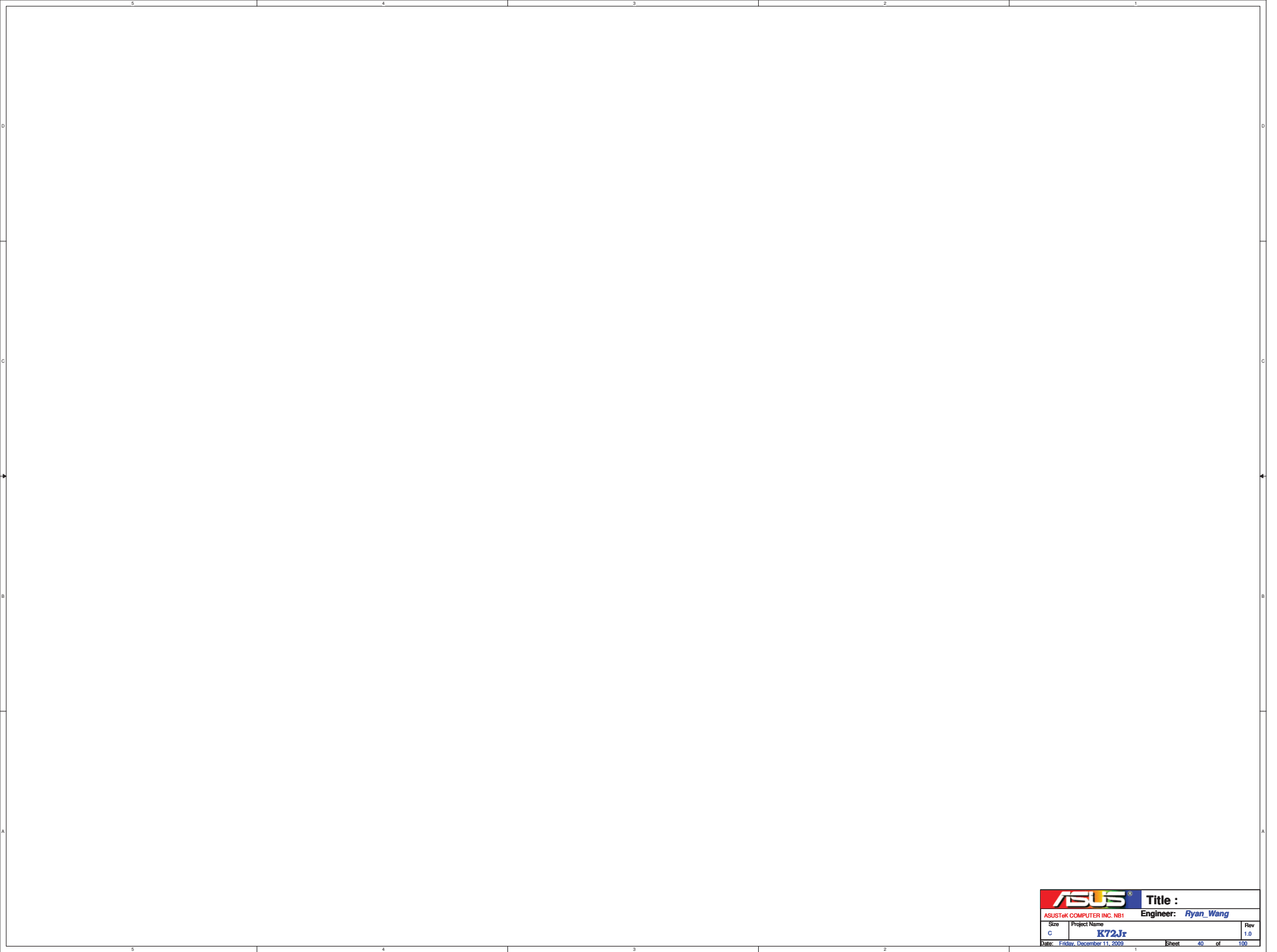




<Variant Name>

ASUS		Title : AUD_I_MIC	
ASUSTeK COMPUTER INC. NB2		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	38 of 100

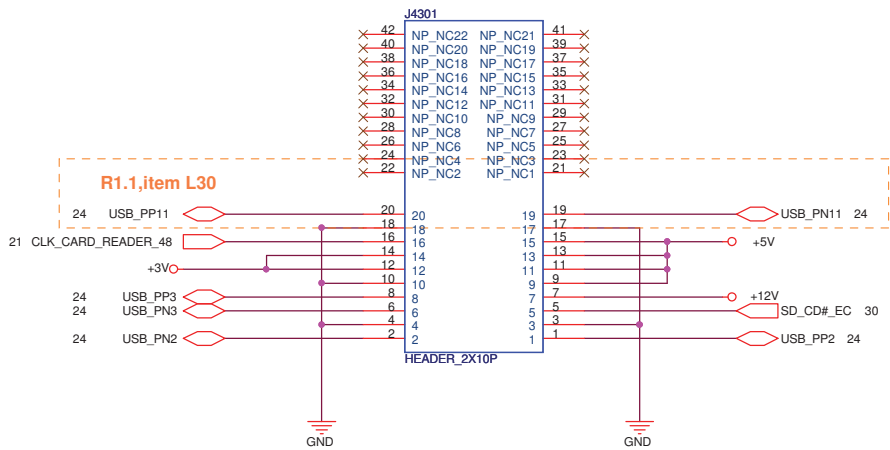




		Title :	
ASUSTeK COMPUTER INC. NB1		Engineer: <i>Ryan_Wang</i>	
Size	Project Name		Rev
C	K72Jr		1.0
Date: Friday, December 11, 2009		Sheet	40 of 100

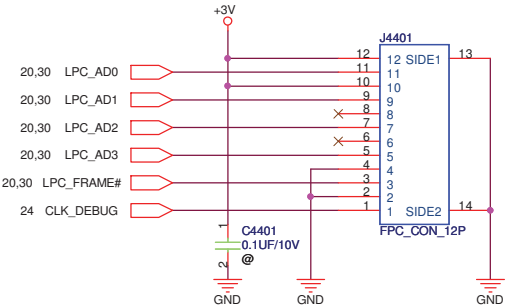
K72J USB Board_20 Pin CON

TOP connector
左上 PIN20 USB_PP4 ; 右上 PIN19 USB_PN4
左下 PIN2 USB_PN2 ; 右下 PIN1 USB_PP2

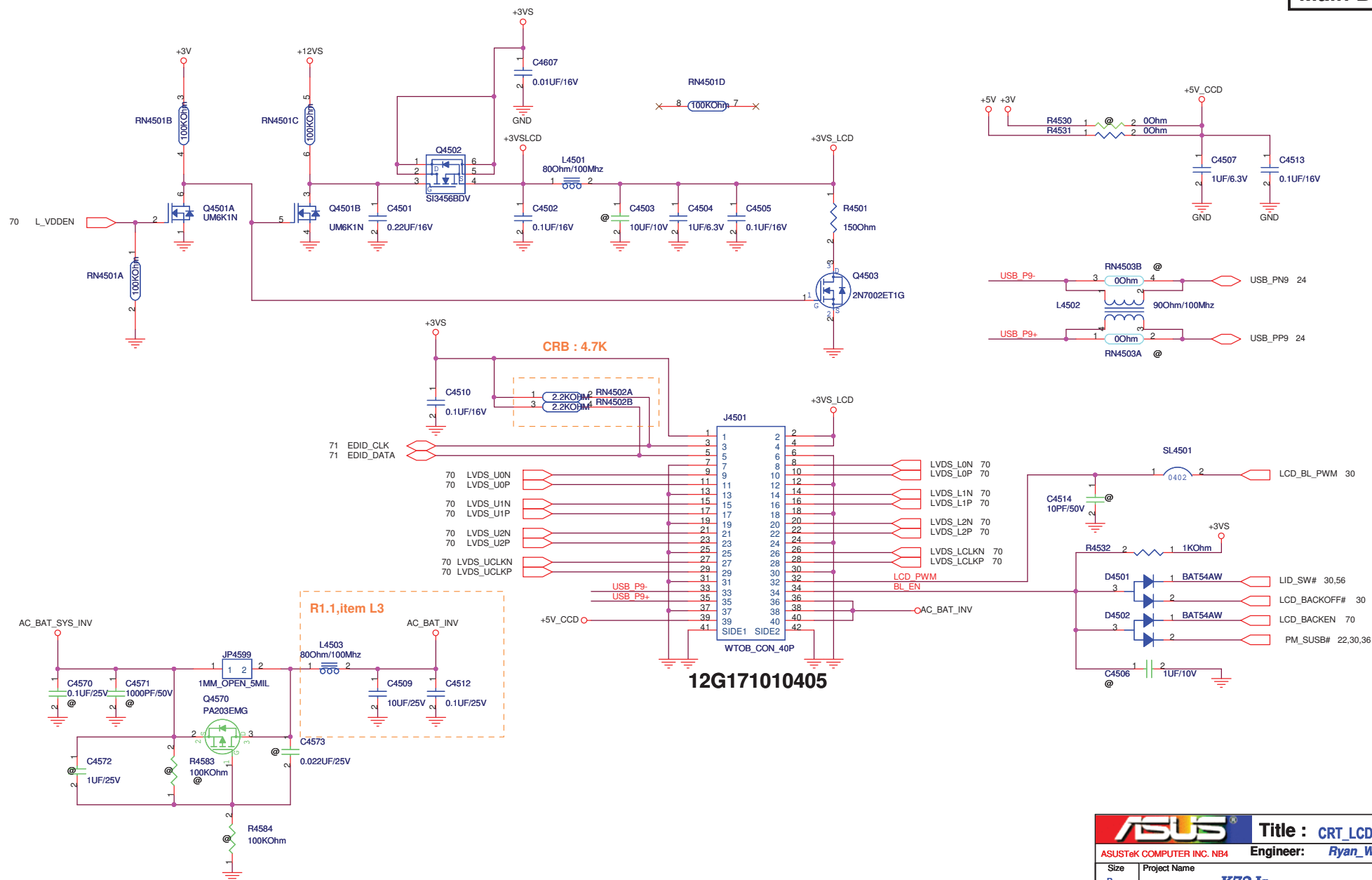


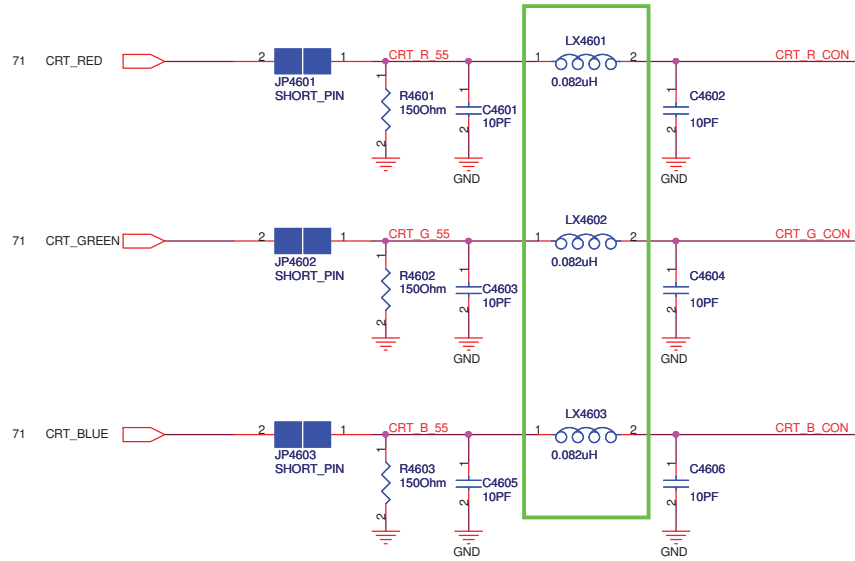
2nd : 12G06120020A

LPC Debug Port

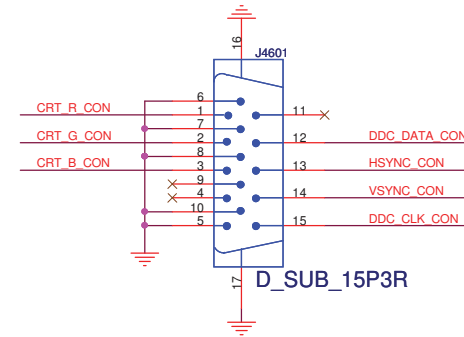
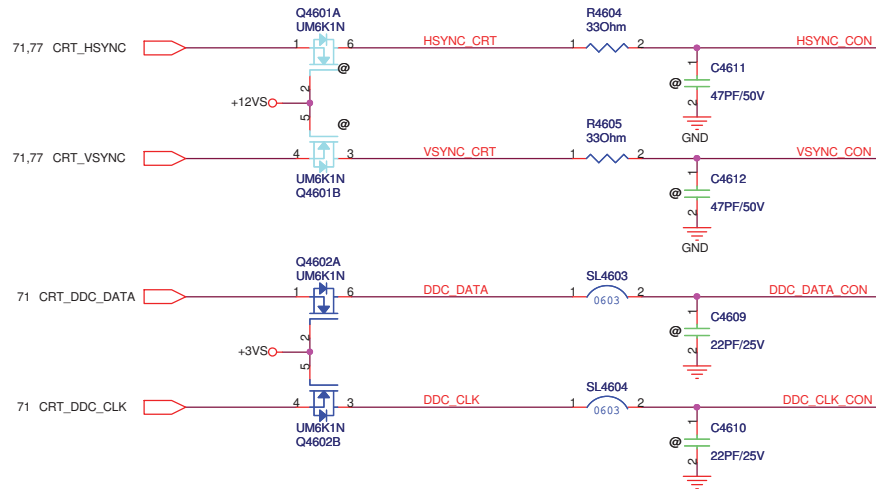


TP M/B TOP 下接觸 PIN1 上面 CLK ; Pin 12 下面 +3V

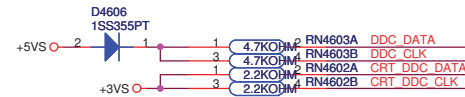
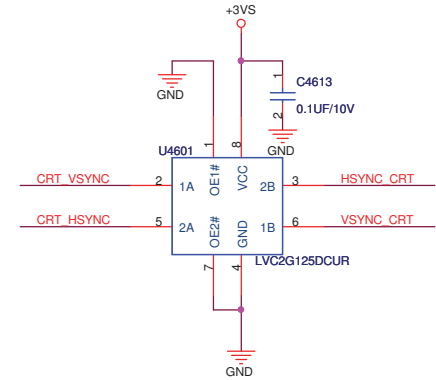




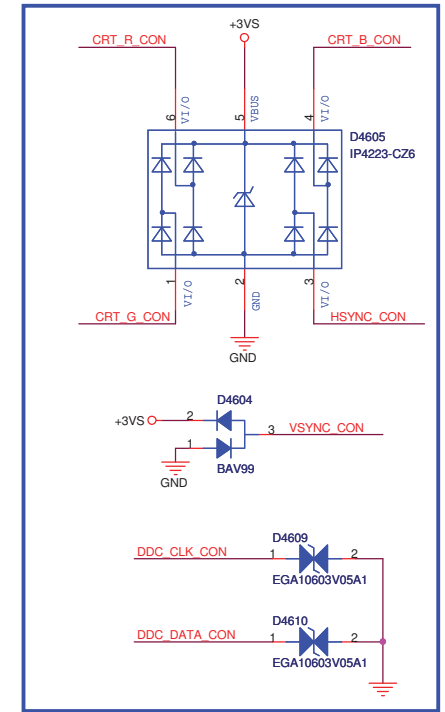
09G013047105



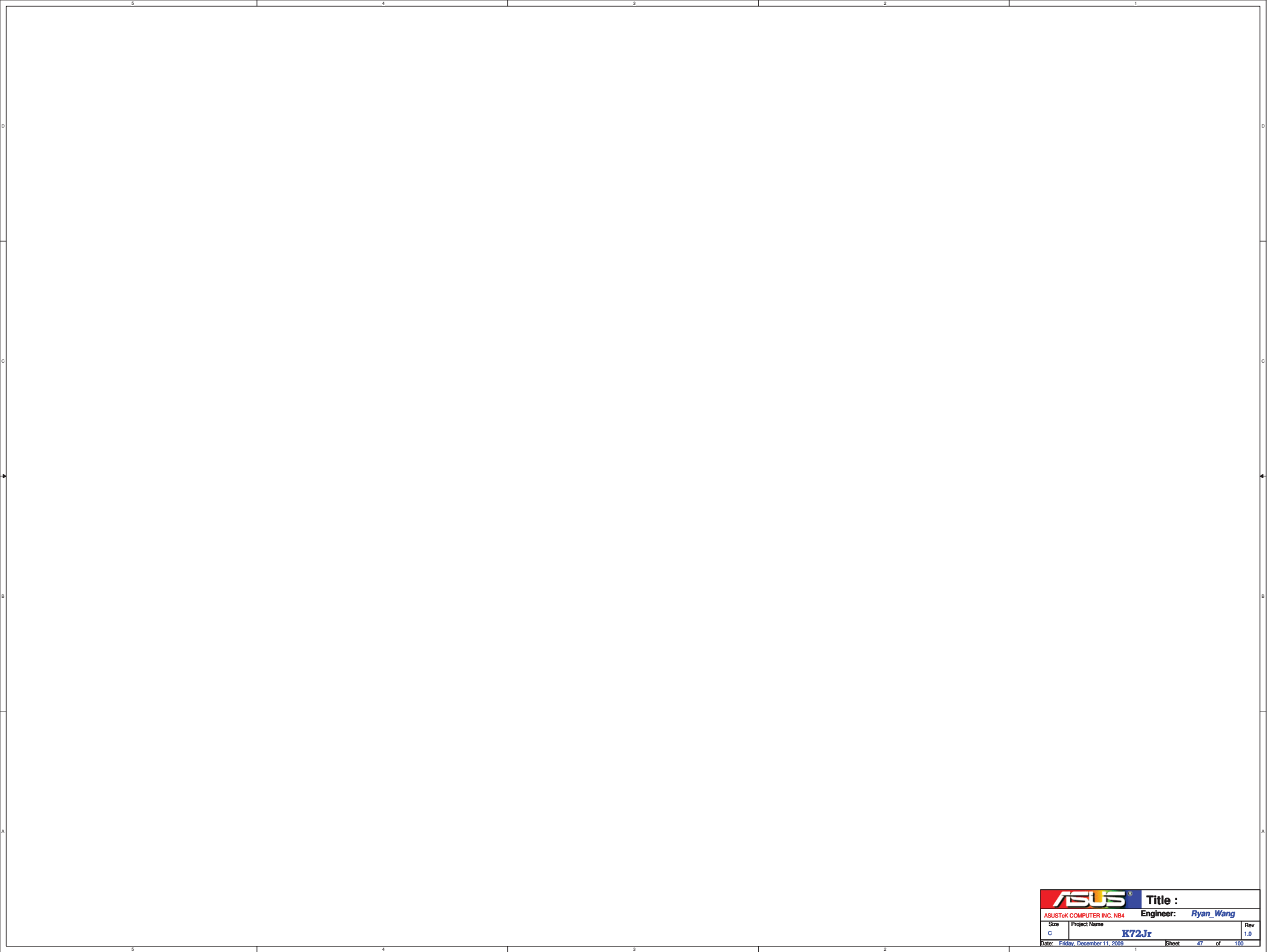
12G101102155



PLACE ESD Diodes near connector



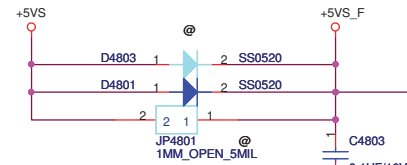
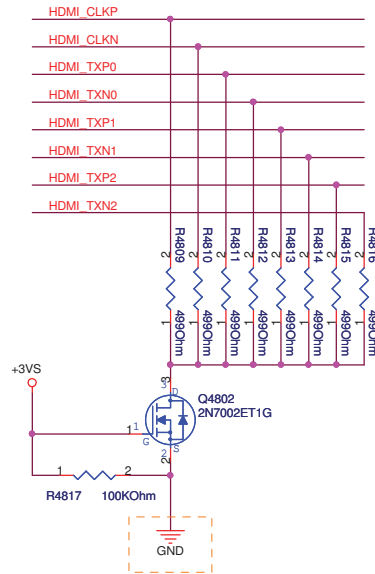
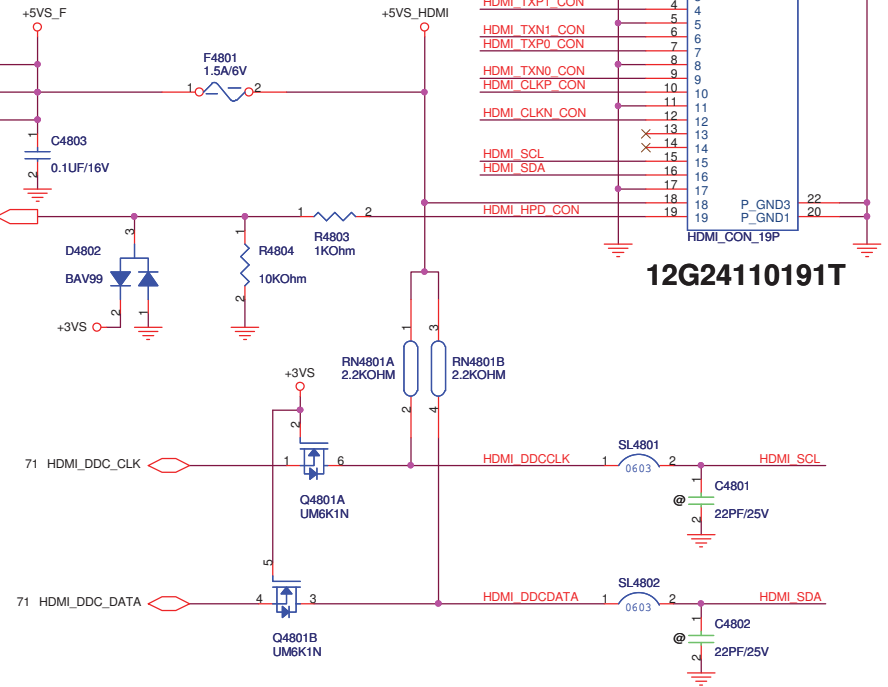
ASUS		Title : CRT_D-Sub	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr	Date: Friday, December 11, 2009	Rev 2.0
Sheet 46 of 100			



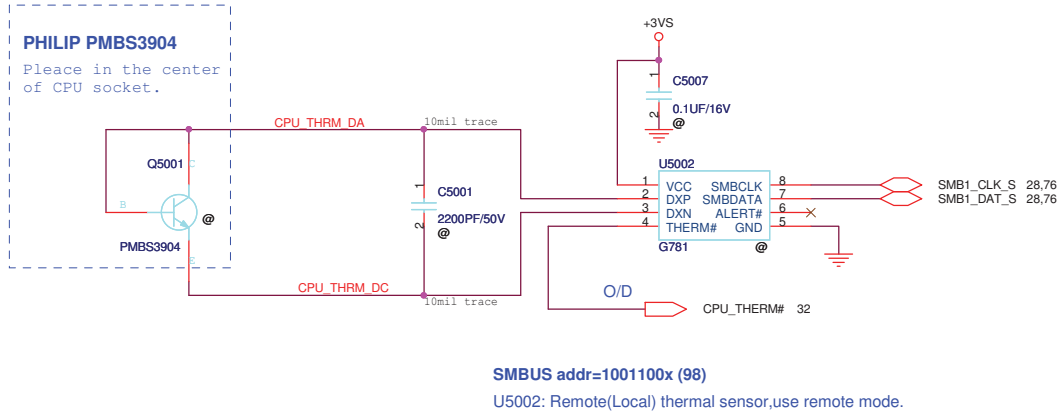
		Title :	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size	Project Name		Rev
C	K72Jr		1.0
Date: Friday, December 11, 2009		Sheet	47 of 100

PLACE HDMI 0.1uF near connector J4801

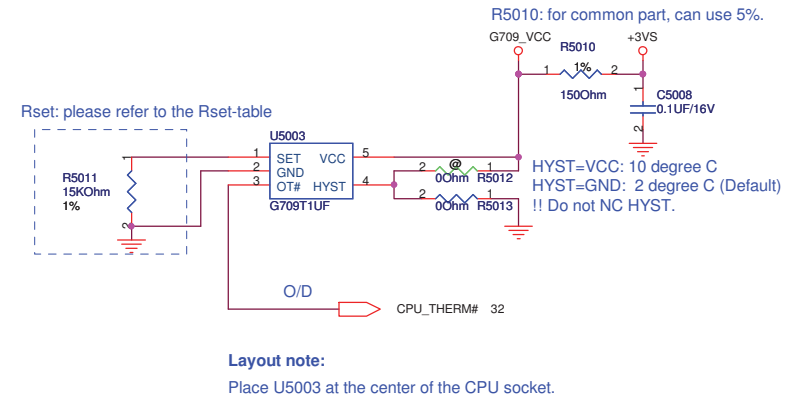
71	HDMI_CLKP_VGA	C4804	1	2	0.1UF/16V	HDMI_CLKP
71	HDMI_CLKN_VGA	C4805	1	2	0.1UF/16V	HDMI_CLKN
71	HDMI_TXP0_VGA	C4806	1	2	0.1UF/16V	HDMI_TXP0
71	HDMI_TXN0_VGA	C4807	1	2	0.1UF/16V	HDMI_TXN0
71	HDMI_TXP1_VGA	C4808	1	2	0.1UF/16V	HDMI_TXP1
71	HDMI_TXN1_VGA	C4809	1	2	0.1UF/16V	HDMI_TXN1
71	HDMI_TXP2_VGA	C4810	1	2	0.1UF/16V	HDMI_TXP2
71	HDMI_TXN2_VGA	C4811	1	2	0.1UF/16V	HDMI_TXN2

F4801 changed to 07G014020210
POLYSWITCH SMD 0.2A/24V(1206)

CPU Thermal Sensor

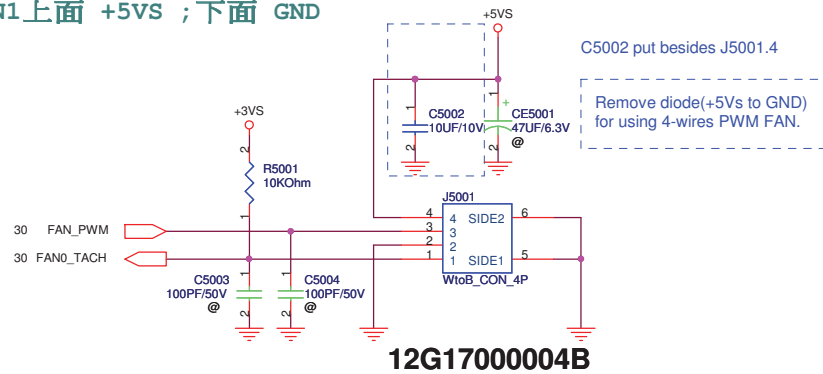


CPU Thermal Sensor



PWM Fan

BOTTOM connector
PIN1上面 +5VS ;下面 GND


$$R_{set}(Kohm)=0.0012T^*T-0.9308*T+96.147$$

Resistor Accuracy: +/- 1%

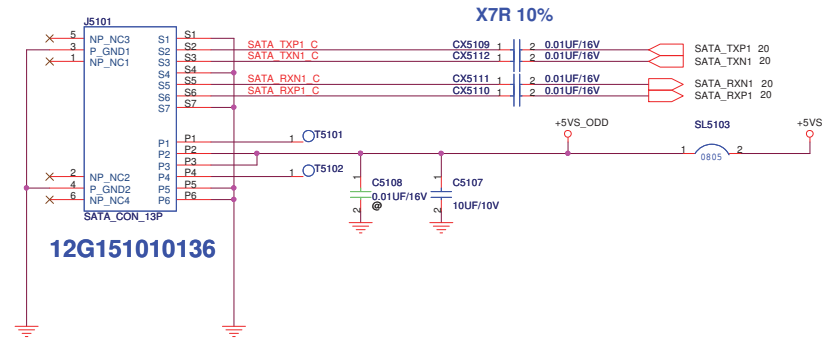
G709 Temperature Threshold Accuracy: -4.7 degree C ~ +4.7 degree C

Set center temperature=96.06 degree C

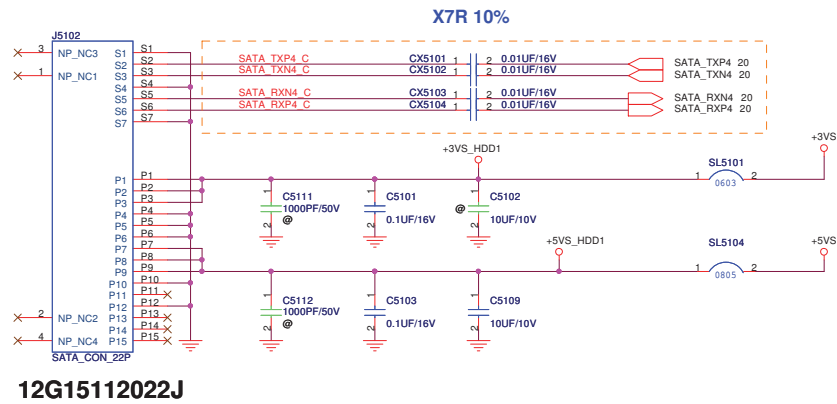
Rset value is depend on thermal request.

For M60J, possible board shutdown temperature: 91 ~ 101 degree C.

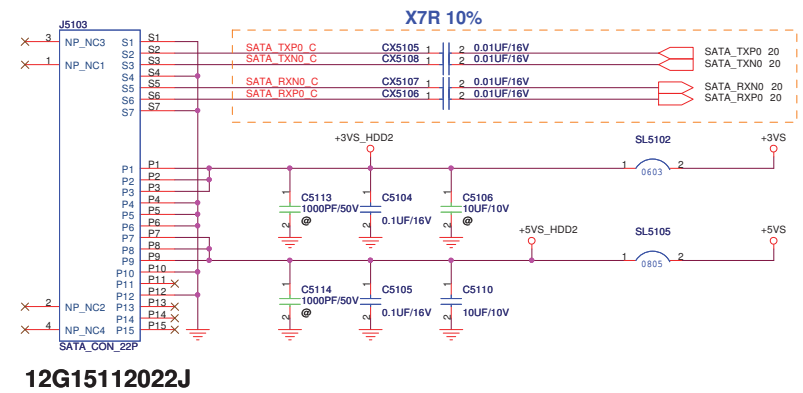
ODD

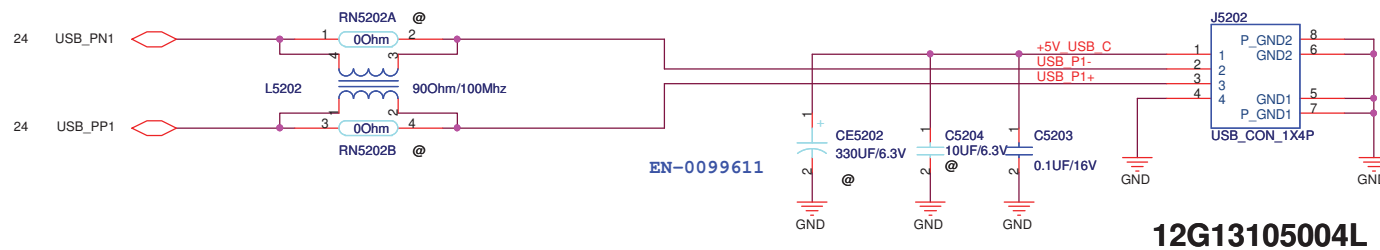
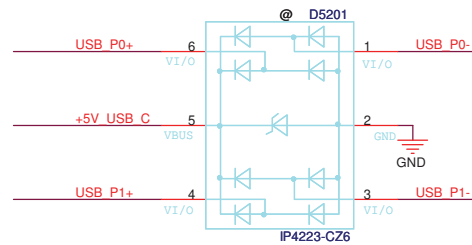
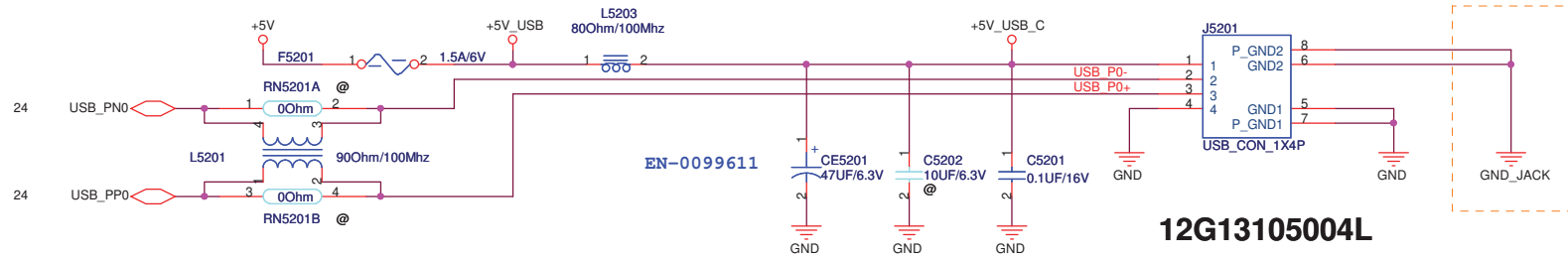


HDD (2nd) Right side

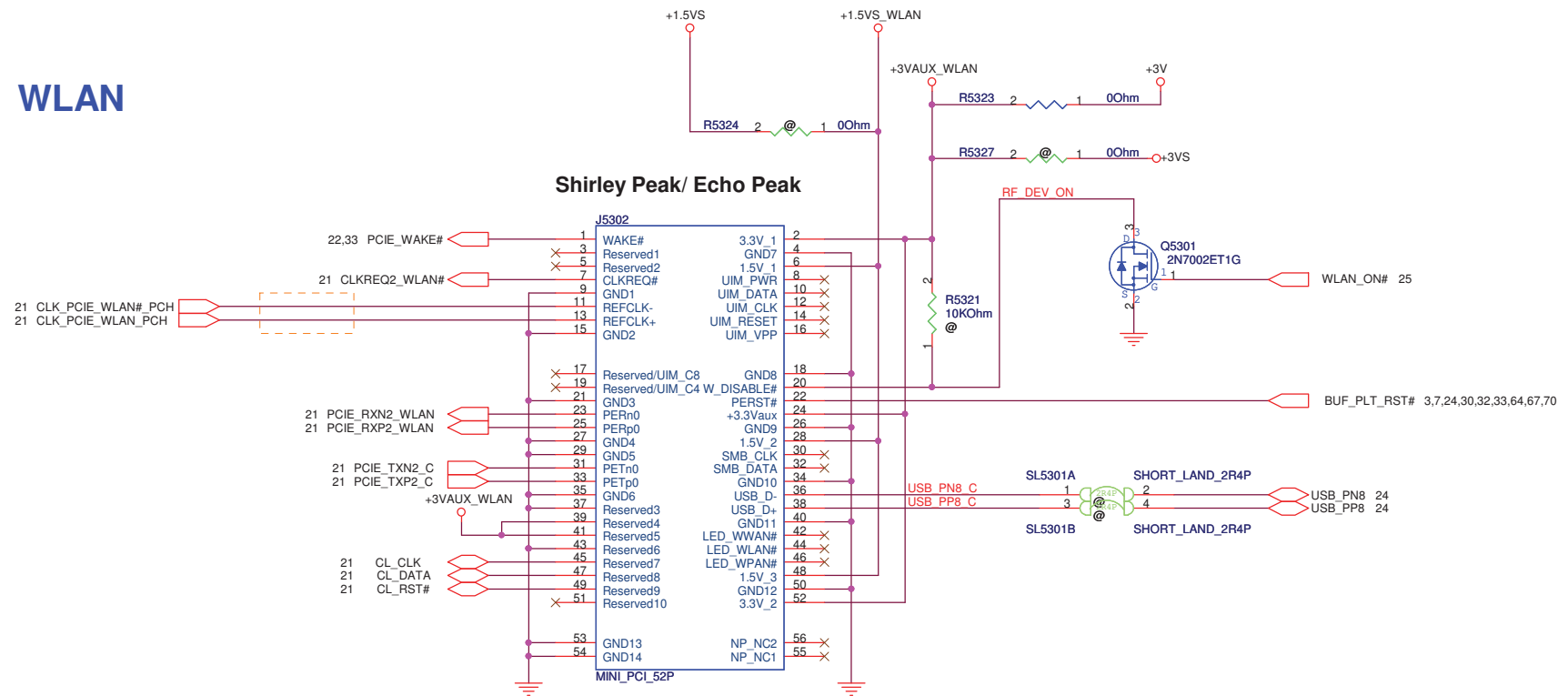


HDD (1st) Left side





WLAN

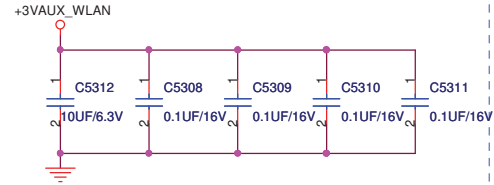


12G03011052N

WLAN +3VAUX bypass capacitor:

Place 0.1uF near pin 2,24,52,39 41.

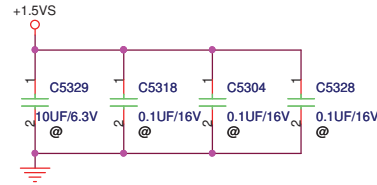
Place 10uF near +3VAUX_WLAN source side.



WLAN +1.5VS bypass capacitor:

Place 0.1uF near pin 6,28,48.

Place 10uF near +1.5VS source side.

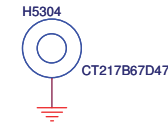
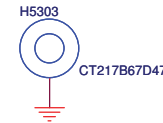


WLAN nuts:

Minicard spec R1.2:

Full size card= 2pcs.

Half size card= 2pcs.

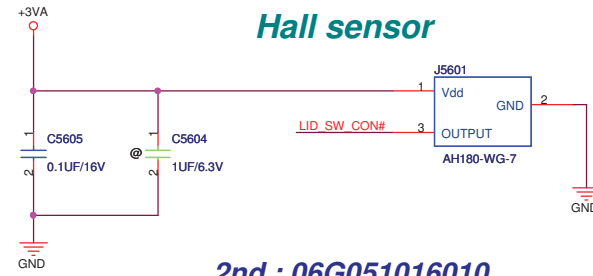
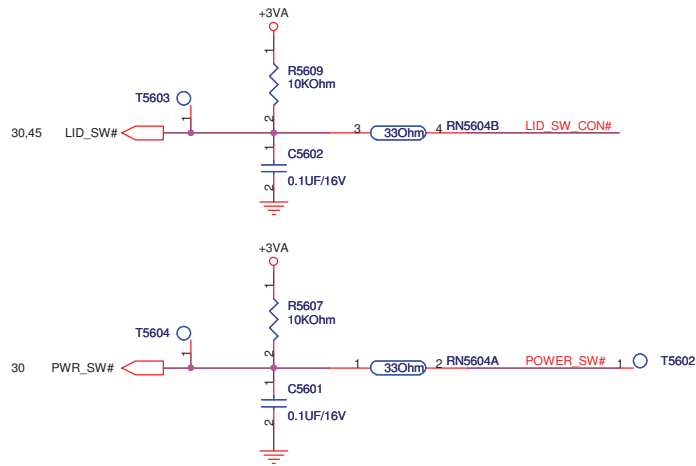


13G021043011

13G021043011

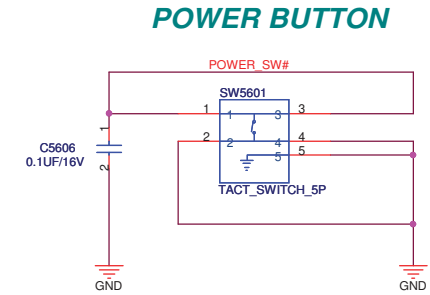
2ND : 13G021085000

ASUS		Title :MINICARD(WLAN)	
ASUSTeK COMPUTER INC. NB6		Engineer: Jerry Mou	
Size	Project Name	Rev	
Custom	K72Jr	2.0	
Date: Friday, December 11, 2009		Sheet	53 of 100



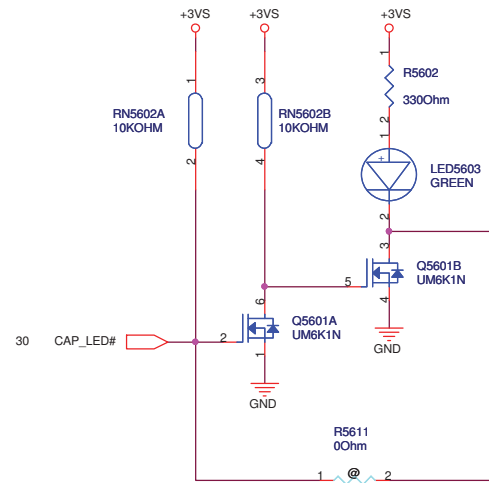
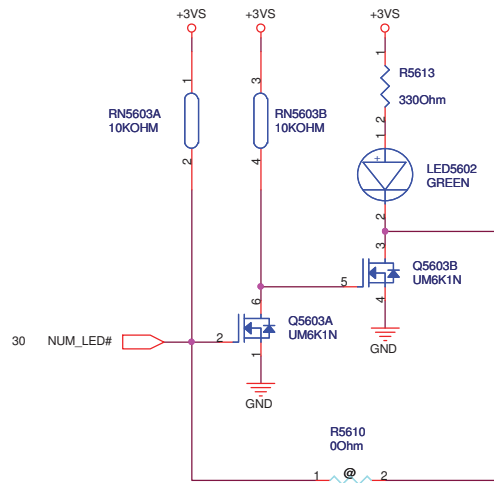
2nd : 06G051016010

(3rd : 06G036022010)



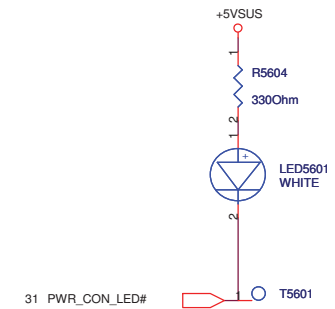
2nd : 07G015200351

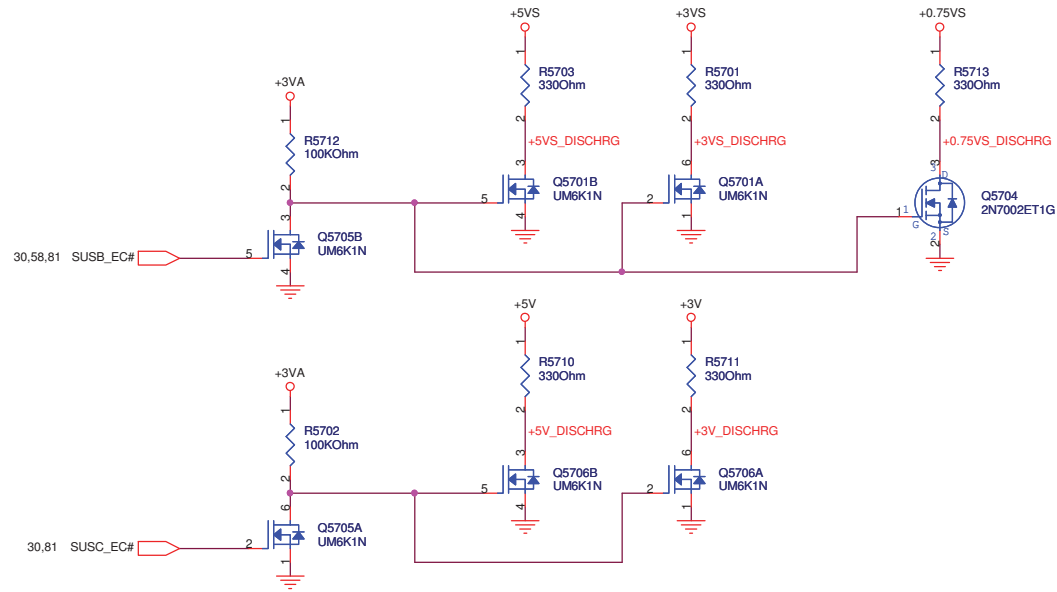
(3rd : 07G015500051)



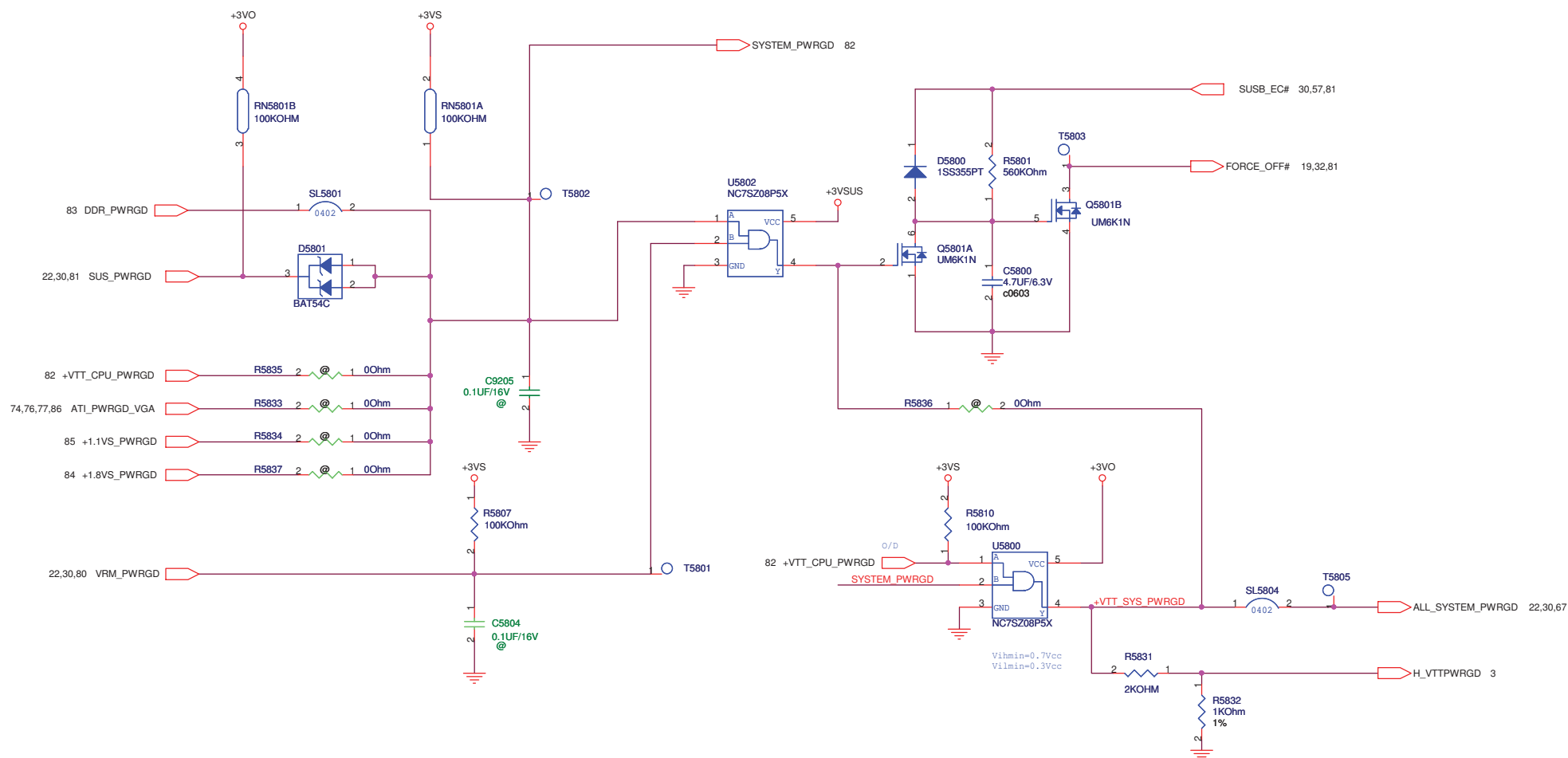
2nd : 07G01570130A

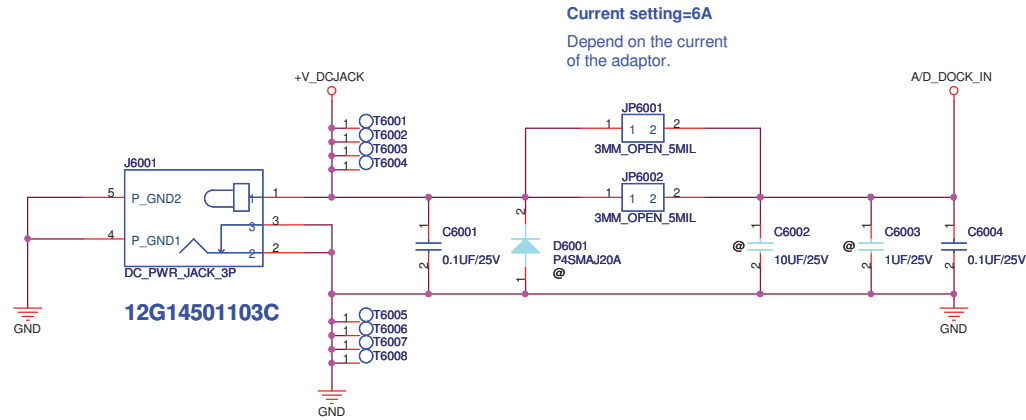
(3rd : 07G015L0042A)



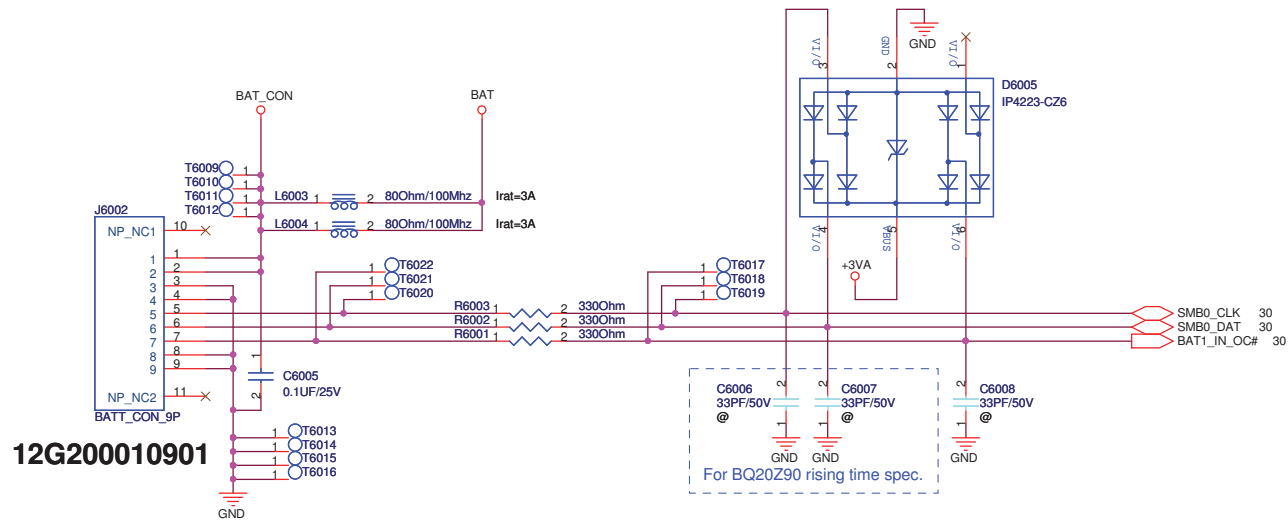


POWER GOOD DETECTOR





DC Jack

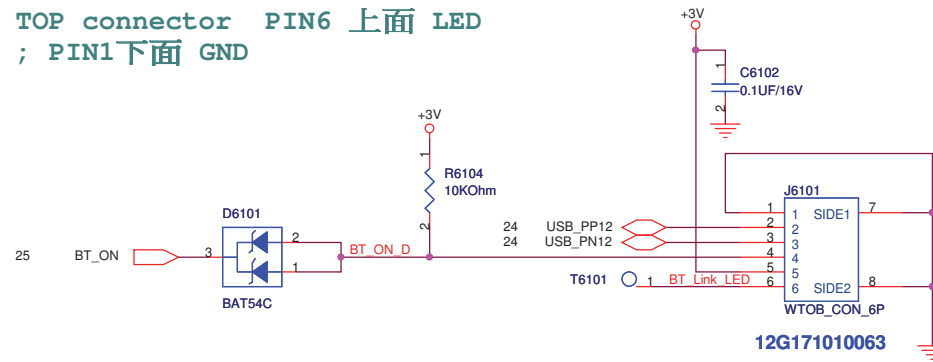


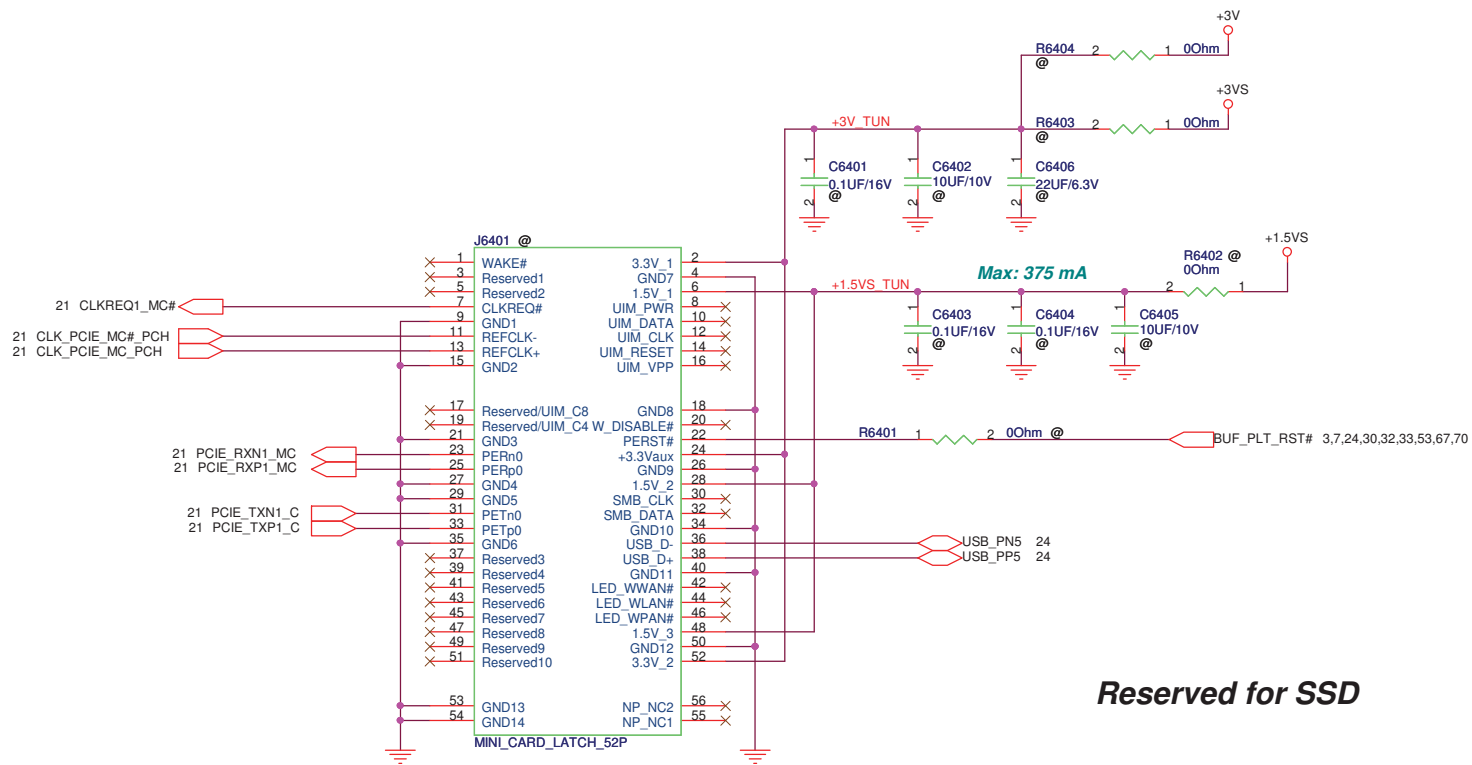
Battery Connector

ASUS		Title : DC_DC & BAT Conn.	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	60 of 100

BLUETOOTH

TOP connector PIN6 上面 LED
; PIN1下面 GND

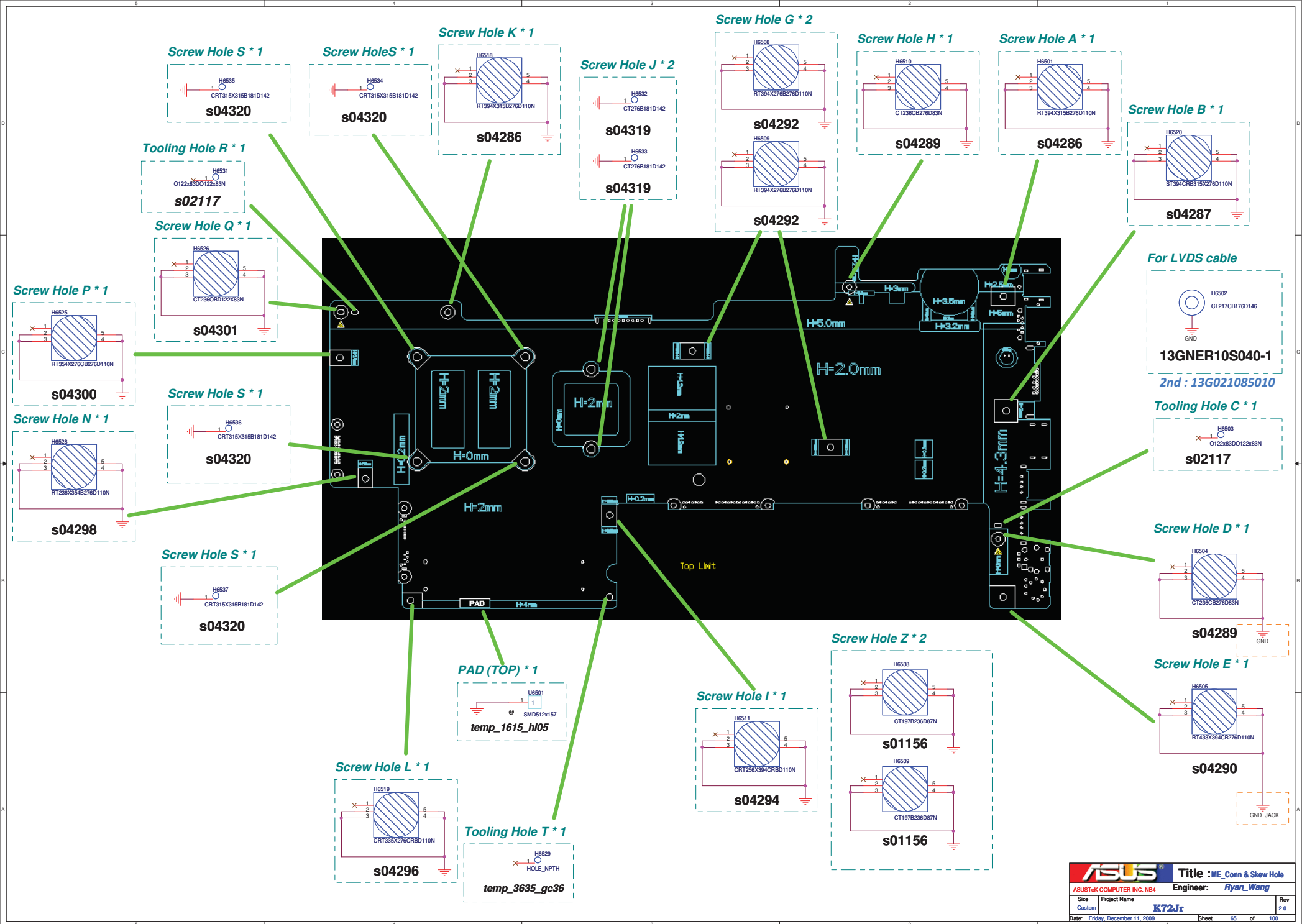




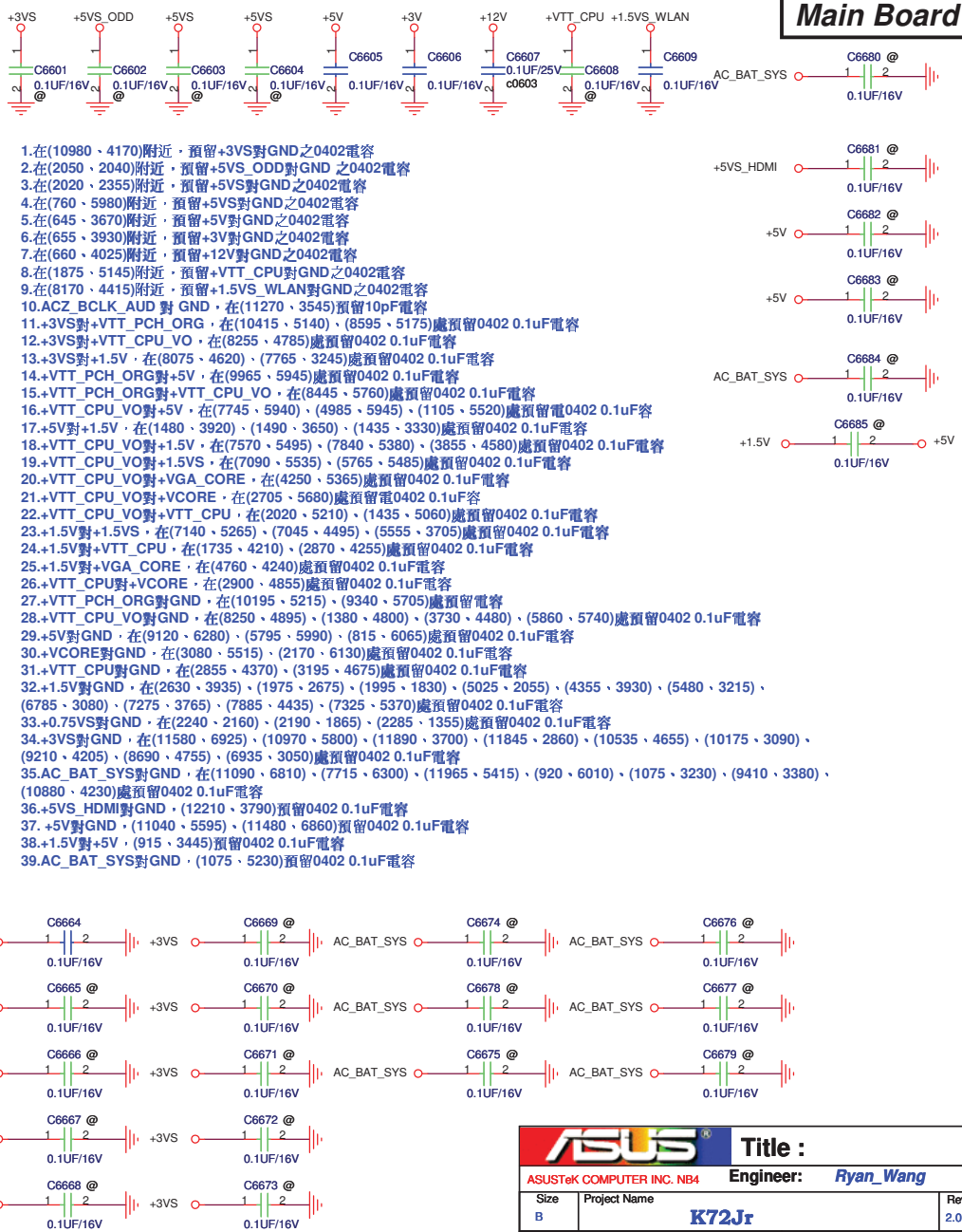
12G030000525



		Title :	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	64 of 100

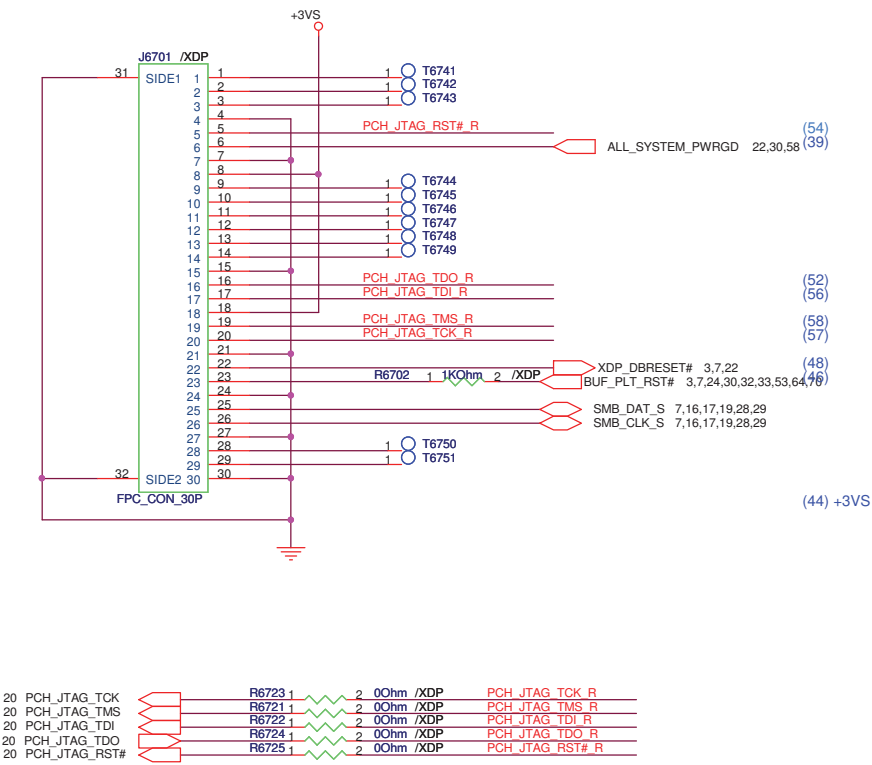


Main Board

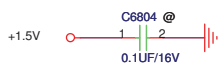
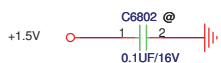
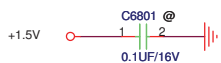
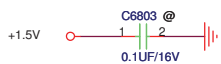
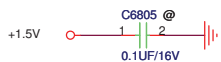
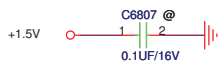
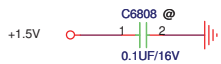
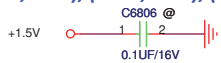


ASUS		Title :	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009	Sheet	66	of 100

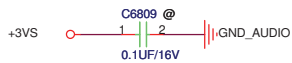
PCH XDP



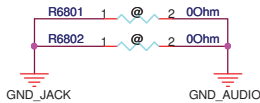
2009/8/25
1.5V對GND, (1975,4025), (3250,4075), (3325,2310), (3870,2300), (3445,1720), (3735,1805), (3225,1420), (3635,1500)預留0402 電容



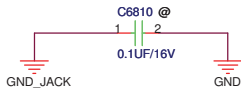
INT_MIC 跨 +3VS & GND_Audio 在in2切割，預留+3VS對GND_AUDIO 電容



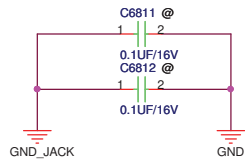
GND_Jack對GND_AUDIO 留0歐姆電阻: (11990, 2240), (11895, 1695)



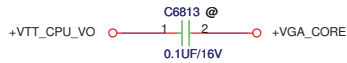
GND_Jack對GND: (12015, 2405)預留電容



GND_audio對GND: (11655, 2495), (11655, 2200)預留電容



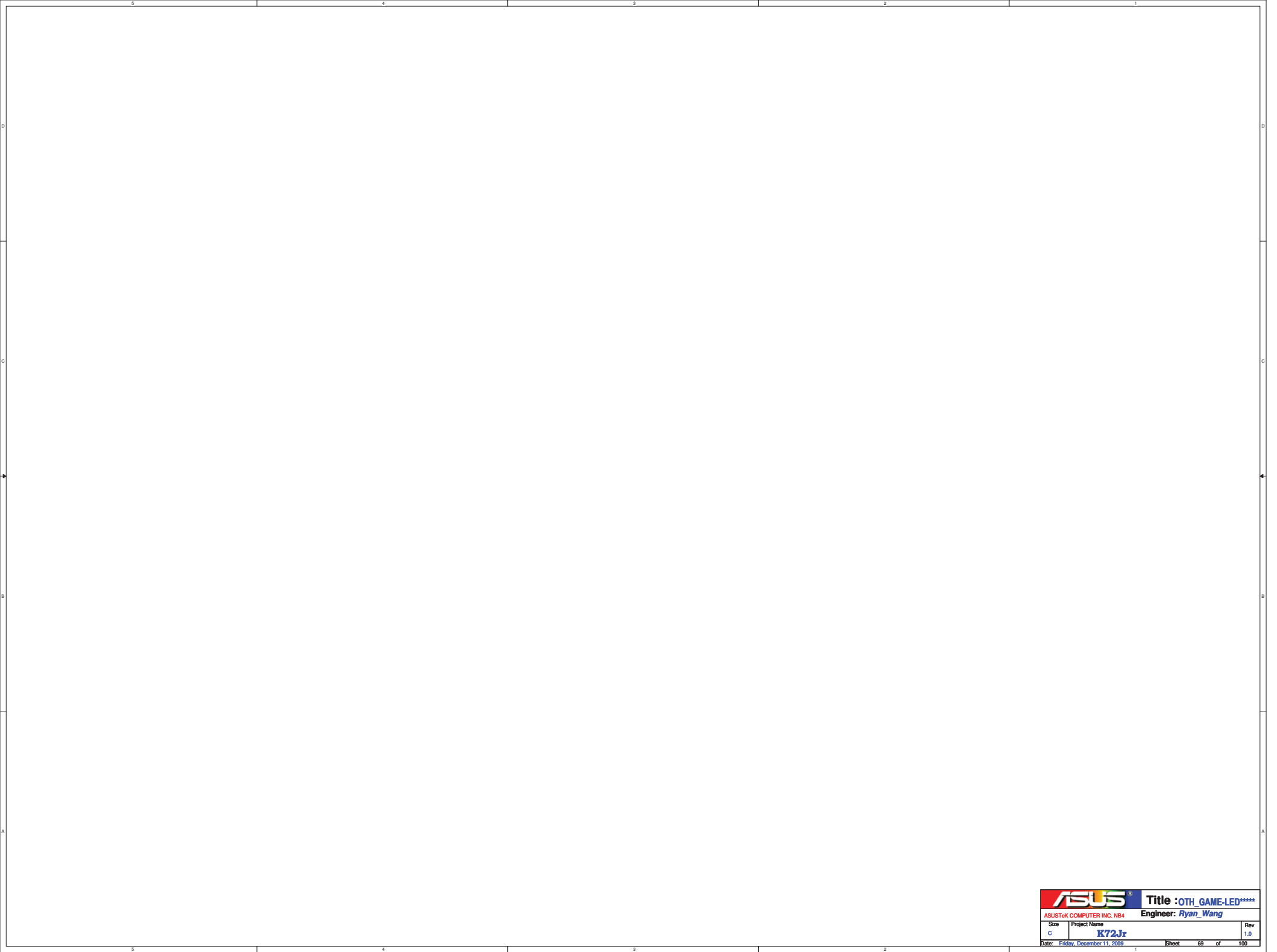
+VTT_CPU_VO對+VGA_Core: (5310, 5430)預留電容



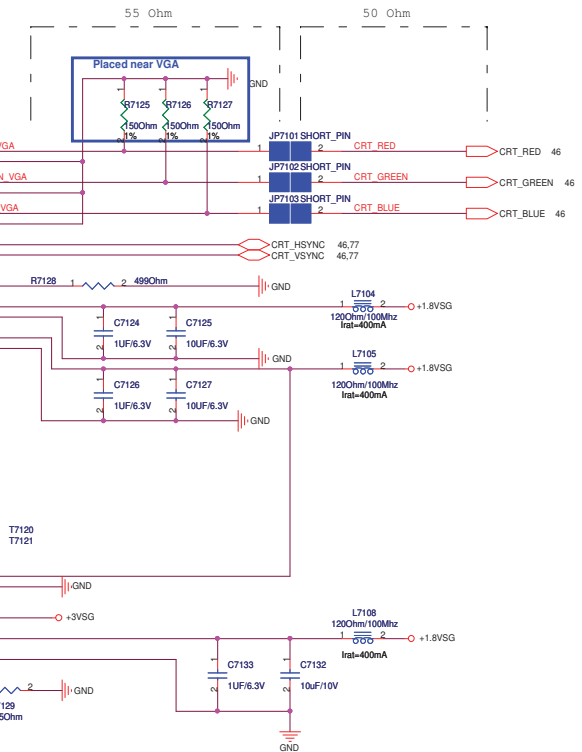
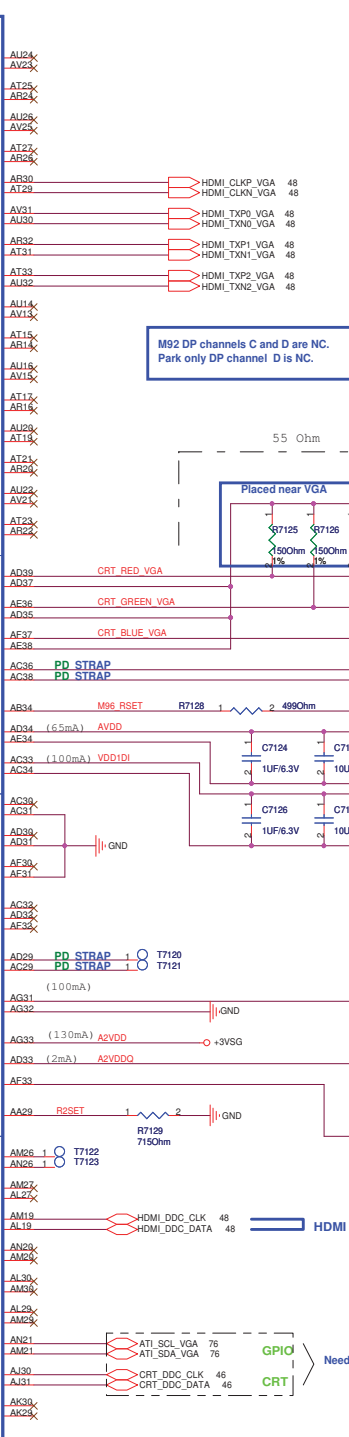
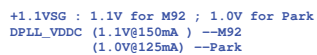
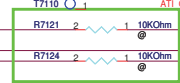
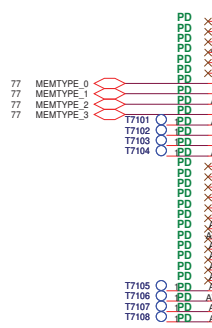
+5V對+VTT_CPU_VO:(2565, 5990)預留電容



ASUS		Title : OTH_LCM	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet 68	of 100

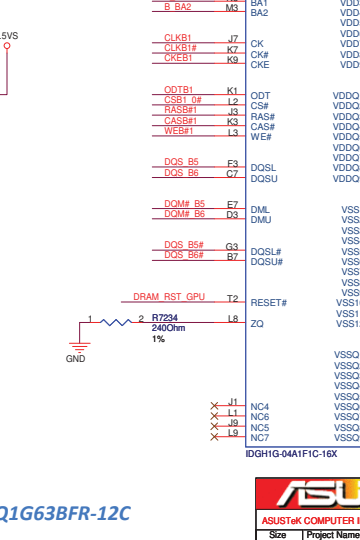
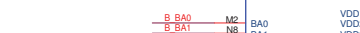
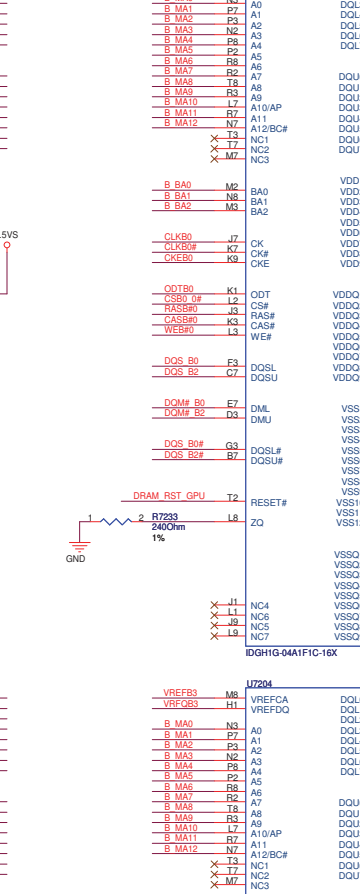
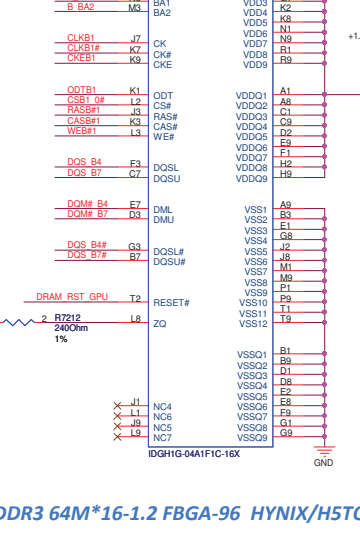
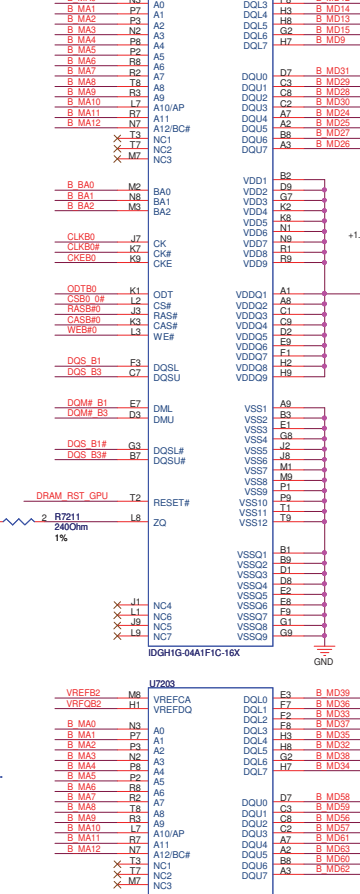
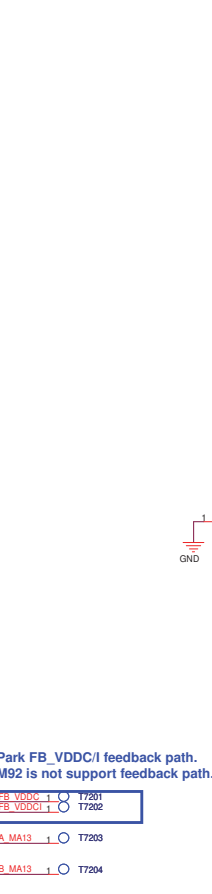
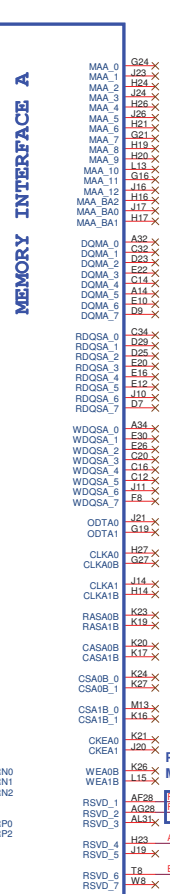
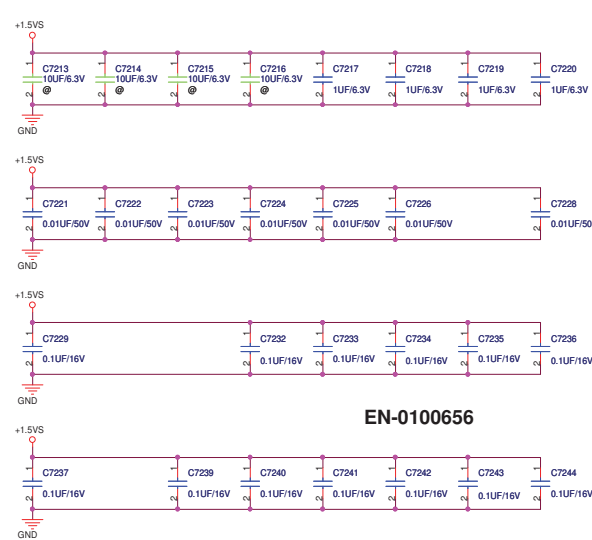




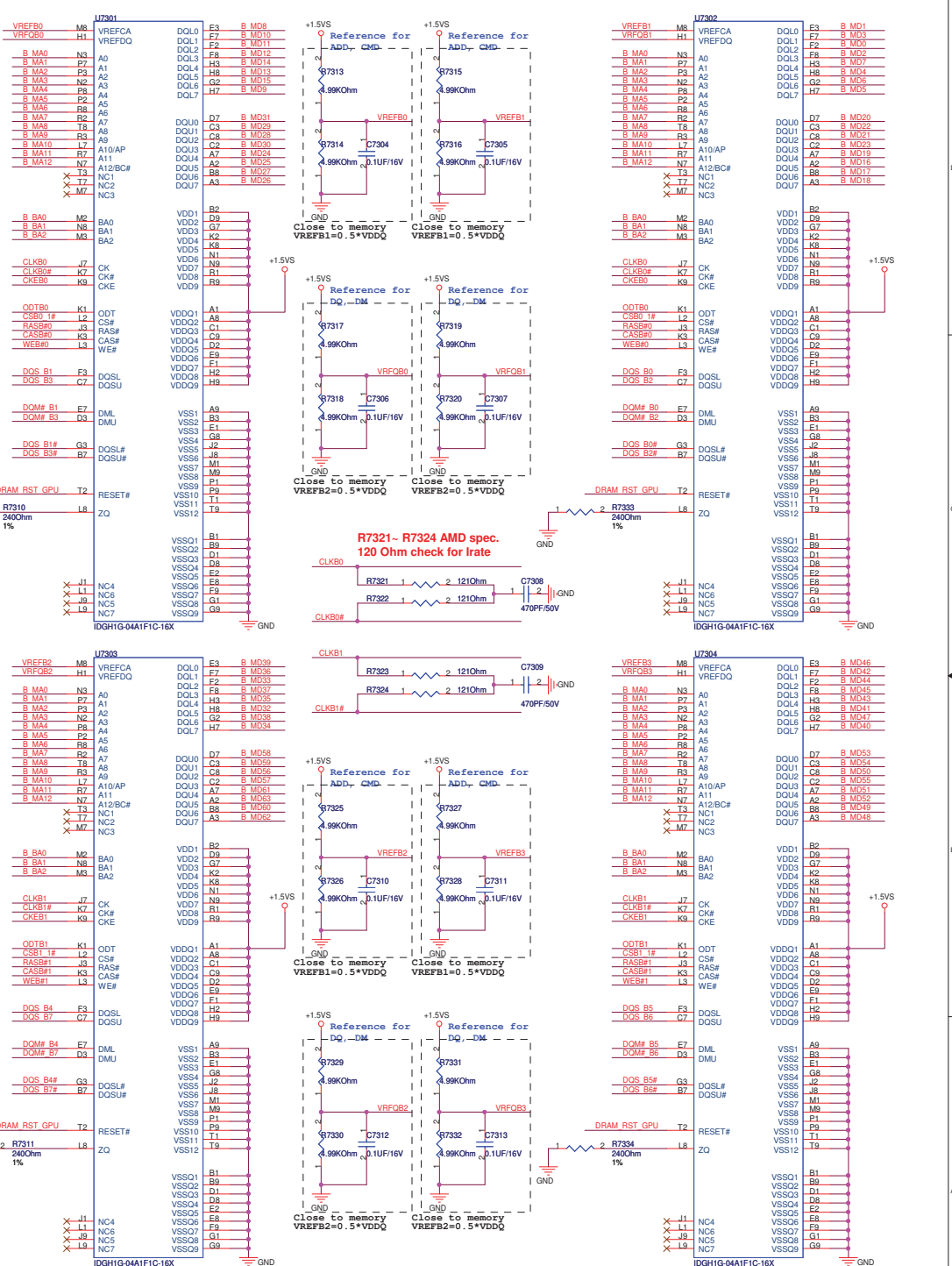
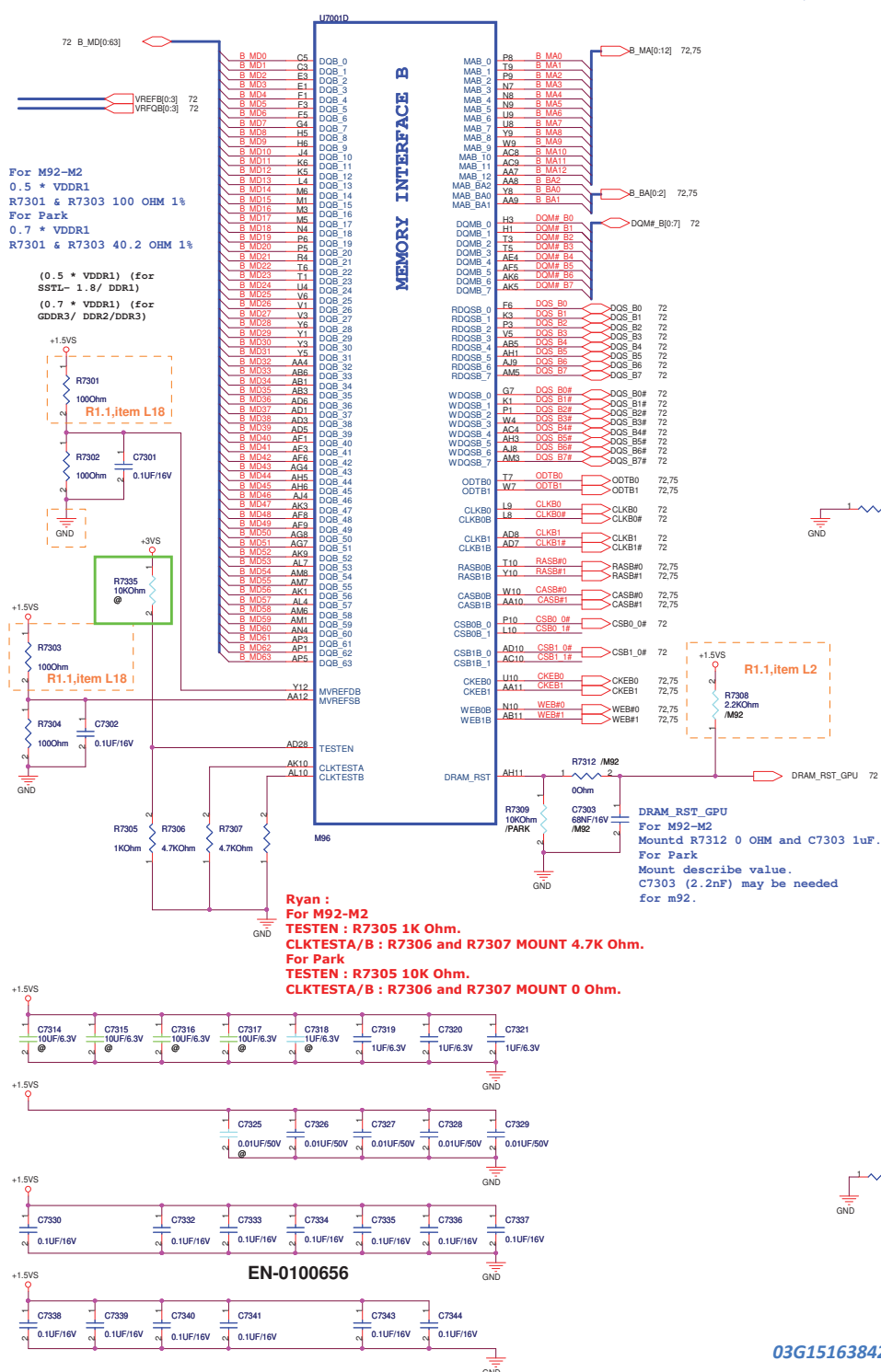


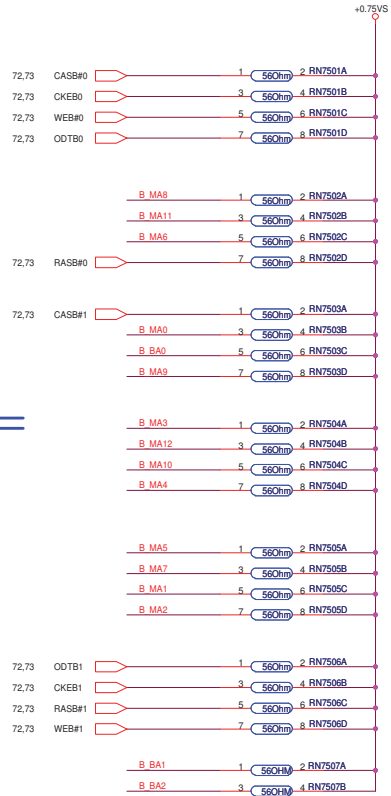
	B_MDIO[63]	73
	B_MAJ[12]	73,75
	B_BA[2]	73,75
	DOMM_B[0:7]	73
	VREFB[0:3]	73
	VREFB[0:3]	73
	DOS_B0	73
	DOS_B1	73
	DOS_B2	73
	DOS_B3	73
	DOS_B4	73
	DOS_B5	73
	DOS_B6	73
	DOS_B7	73
	DOS_B#	73
	DOS_B1#	73
	DOS_B2#	73
	DOS_B3#	73
	DOS_B4#	73
	DOS_B5#	73
	DOS_B6#	73
	DOS_B7#	73
	ODTB0	73,75
	ODTB1	73,75
	CLKB0	73
	CLKB#	73
	CLKB1	73
	CLKB1#	73
	RASSB0	73,75
	RASSB1	73,75
	CASSB0	73,75
	CASSB1	73,75
	KEB0	73,75
	KEB1	73,75
	WEB0	73,75
	WEB1	73,75
	CSB0_0#	73
	CSB1_0#	73
DRAM_RST_GPU	DRAM_RST_GPU	73

MEMORY INTERFACE A



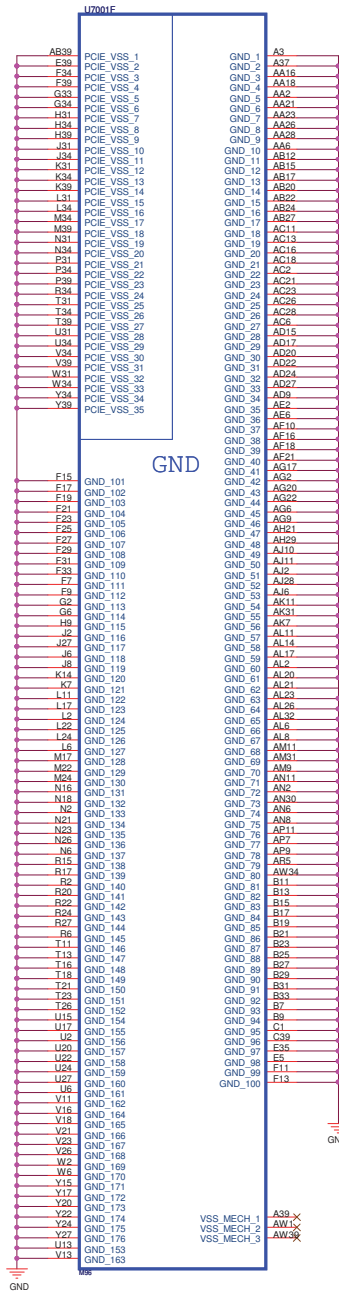
Channel B: Dual 1GB Rank DDR3 (Rank1)





72.73 B_MA[0:12]

72.73 B_BA[0:2]



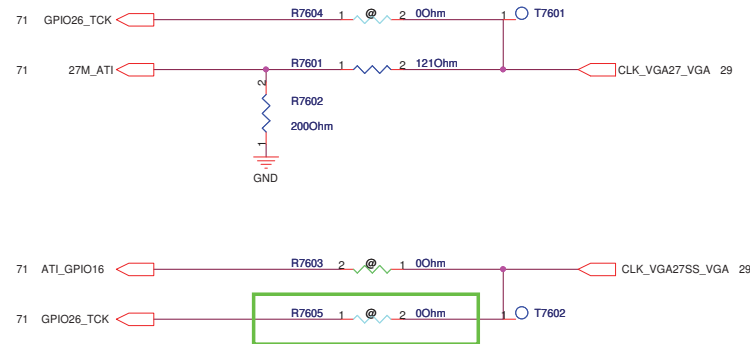
For Park : FB_GND feedback path unmount R7501.
For M92 is GND pin mount R7501.



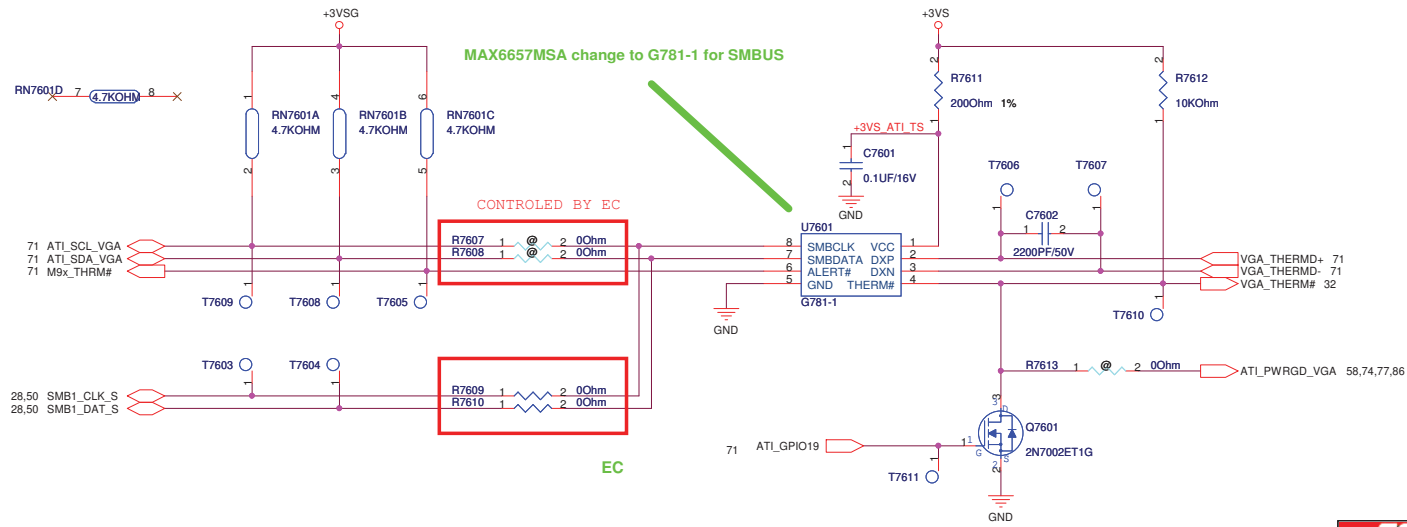
AL21 : PowerXpress Mode Enable

Memory Clock SS (Reserved)

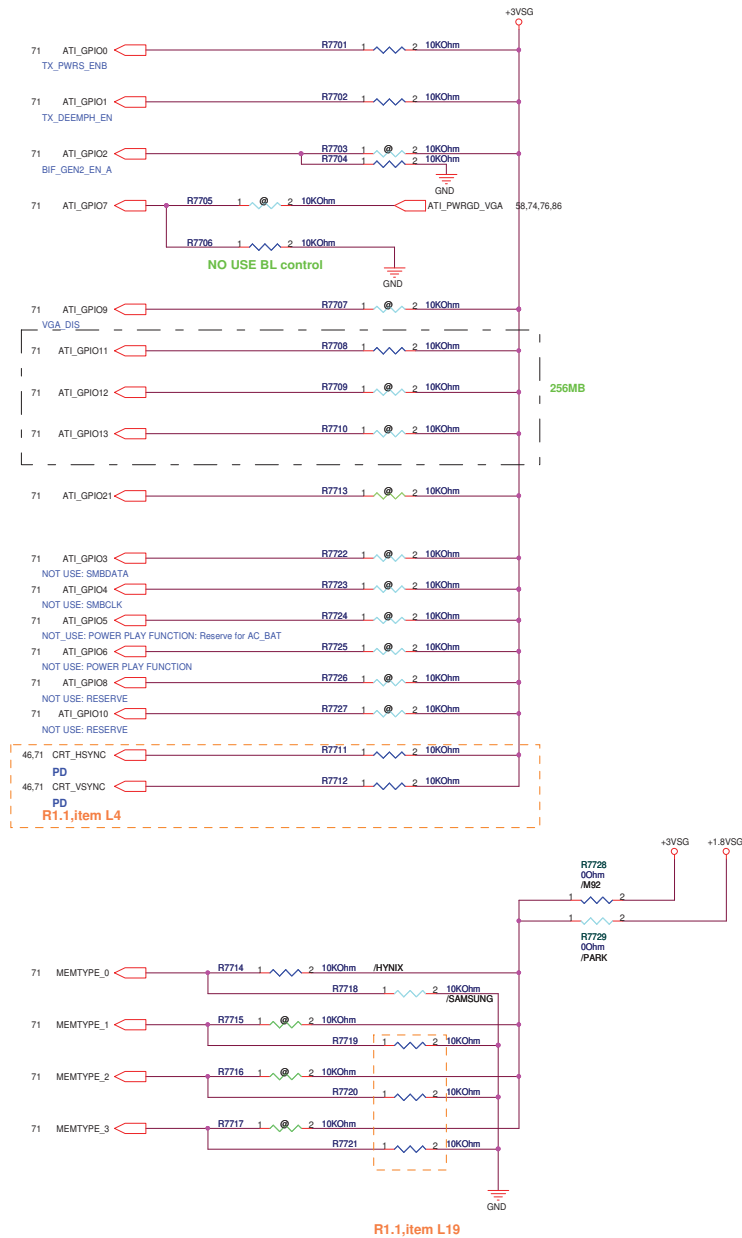
S0 (Spread Percentage Select):
GND: TBD%
VDD: TBD% (default PU)
NC : TBD%



	SMBUS SLAVE ADDRESS
G781	98 (1 0 0 1 1 0 0)
G781-1	9A (1 0 0 1 1 0 1)



OPTION STRAPS



VDD4_VDDR5 : 3.3V for M92 ; 1.8V for Park
M92-M2 mount R7401& unmount L7402
Park mount L7402 & unmount R7401

M92 Straps

STRAPS	PIN	DESCRIPTION	ASIC DEFAULT
VIP_DEVICE_STRAP_EN	V2SYNC	0 - Ignore VIP device straps (DVPDATA_20) 1 - Use VIP device straps (DVPDATA_20)	0 (internal pull-down)
TX_PWRS_ENB	GPIO0	Transmitter Power Savings Enable 0: 50% Tx output swing for mobile mode 1: full Tx output swing This setting can only be used if the PCIe bus design meets the "Low Loss Interconnect" requirements.	0 (internal pull-down)
TX_DEEMPH_EN	GPIO1	Transmitter De-emphasis Enable 0: Tx de-emphasis disabled for mobile mode 1: Tx de-emphasis enabled	0 (internal pull-down)
BIF_GEN2_EN_A	GPIO2	1 = Advertises the PCI-E device as 5.0 GT/s capable at power-on 0 = Advertises the PCI-E device as 2.5 GT/s capable at power-on	0
VGA_DIS	GPIO9	0 - VGA Controller capacity enabled 1 - The device will not be recognized as the system's VGA controller	0 (internal pull-down)
ROMIDCFG(2:0)	GPIO(13:11)	If BIOS_ROM_EN=1, then Config(2:0) defines the ROM type. If BIOS_ROM_EN=0, then Config(2:0) defines the primary memory aperture size. 128MB---x000 32MB---Not Support 2GB---Not Support 256MB---x001 512MB---Not Support 4GB---Not Support 64MB---x010 1GB---Not Support	0000 (internal pull-down)
BIOS_ROM_EN	GPIO22_ROMCSB	Enable external BIOS ROM device 0-Disable external BIOS ROM device 1-Enable external BIOS ROM device	0 (internal pull-down)
AUD[1] AUD[0]	PEG_CRT_HSYNC_VGA PEG_CRT_VSYNC_VGA	AUD[1:0]: 00: No audio function; 01: Audio for DisplayPort and HDMI if adapter is detected; 10: Audio for DisplayPort only; 11: Audio for both DisplayPort and HDMI	0 (internal pull-down)
Reserved	H2SYNC GPIO 21_BB_EN GENERICC	ATI internal use only . THIS PAD HAS AN INTERNAL PULL-DOWN AND MUST BE 0 V AT RESET.	0 (internal pull-down)

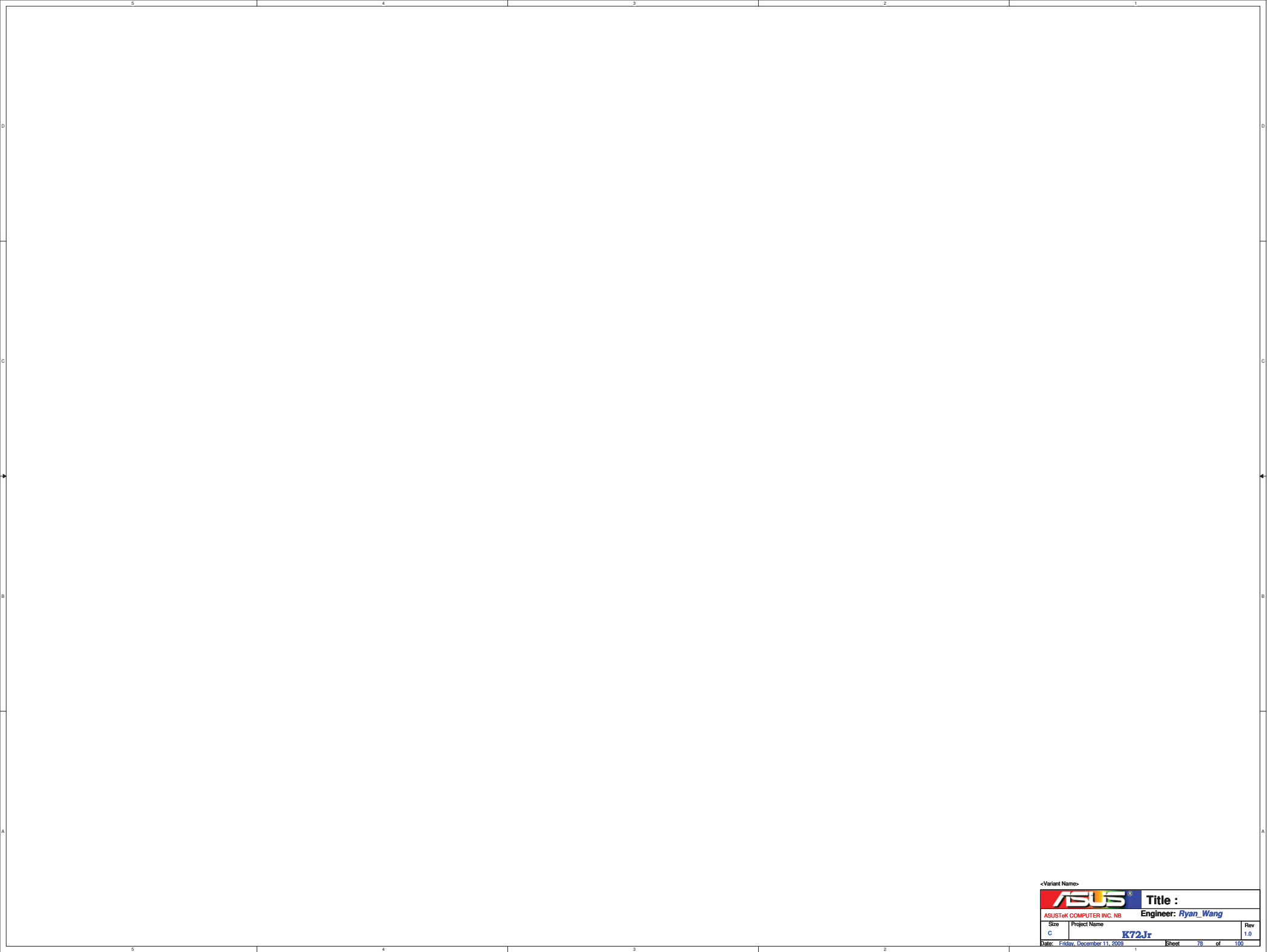
AUDIO_EN	VIP_3	Enable HD Audio function in the PCI configuration space 0 - Disable HD Audio 1 - Enable HD Audio	0 (internal pull-down)
64BAR_EN_A	VIP_5	Enable 64-bit BARs Most commonly this strap is left at the default (32-bit BARs)	0 (internal pull-down)
MSI_DIS	VIP_1	Disable Message Signaled Interrupt is both a ROM strap and a pin strap. The pin strap is only applicable if a BIOS ROM is not present	0 (internal pull-down)
VIP_DEVICE	VHAD_0	VIP_DEVICE_STRAP_EN is set 0 =>not used VIP Host interface VIP_DEVICE_STRAP_EN is set 1 =>used VIP Host interface	0 (internal pull-down)
DEBUG ACCESS	GPIO4	Debug_access strap 3.3V ---ON 0V ---OFF	0 (internal pull-down)
DEBUG_L2C_ENABLE	GPIO6	ATI internal use only . Other logic must not affect this signal during RESET Recommended to 0	0 (internal pull-down)

Dual Rank DDR3 1GB need AMD check pull low or high for following DDR3 VRAM
03G151638020 DDR3 64M*16-1.2 FBGA-96 SAMSUNG/K4W1G1646E-HC12
03G151638421 DDR3 64M*16-1.2 FBGA-96 HYNIX/H5TQ1G63BFR-12C

Memory ID Board Straps

Vendor	DVPDATA(3,2,1,0)	ID	DDR3 Memory Type	Channel Size
Samsung	0000	0	64M*16 (512MB) Dual Rank 512*2 = 1G	B channel dual-link
Hynix	0001	1	64M*16 (512MB) Dual Rank 512*2 = 1G	B channel dual-link

+VGA CORE	RTop	RBot	PWRCNTL_0	PWRCNTL_1
0.9V	8K	40K	Low	Low
1V	8K	40K 60.4K	High	Low
1.1V	8K	40K 30.1K	Low	High
1.2V	8K	40K 60.4K 30.1K	High	High



<Variant Name>

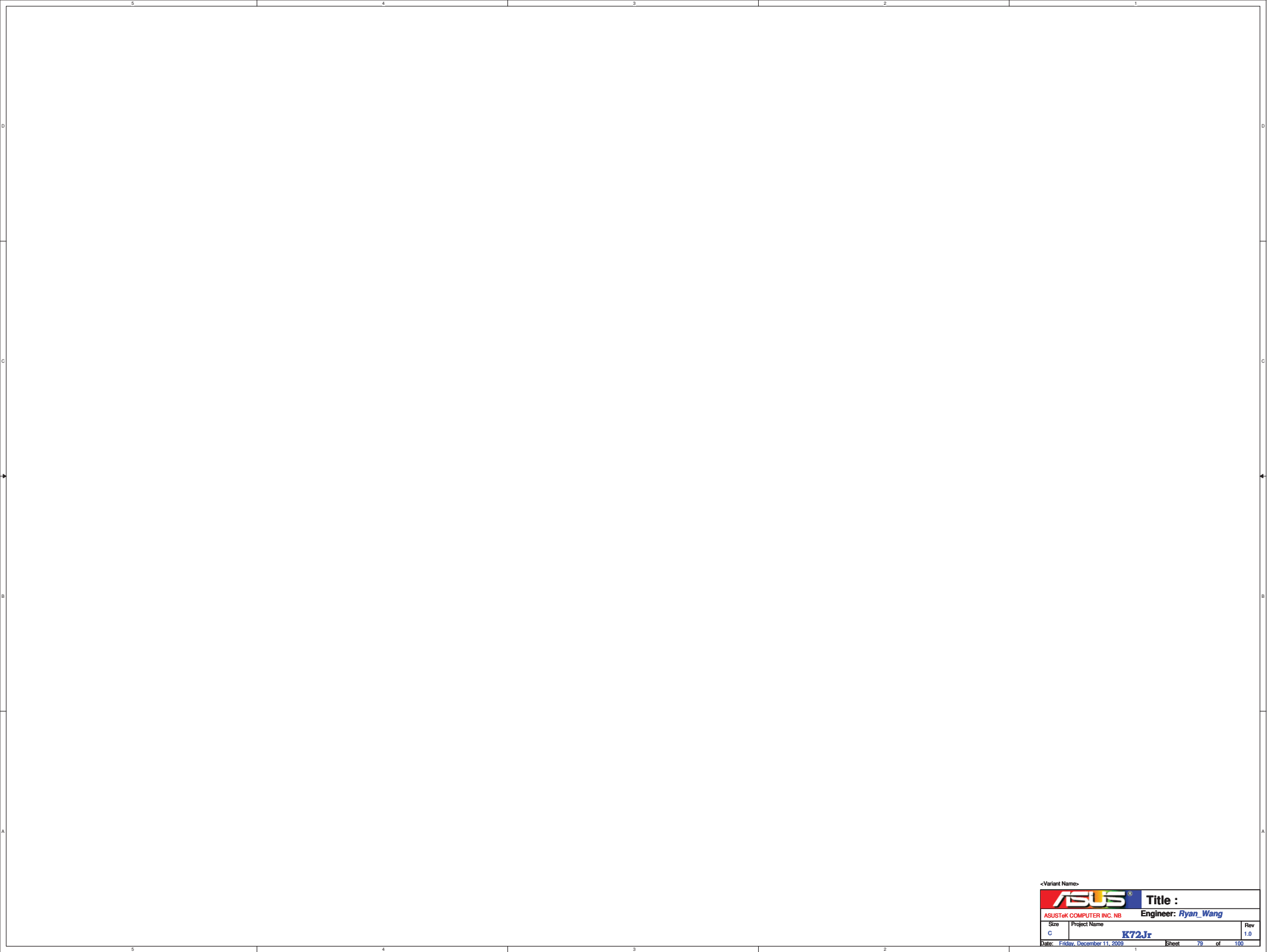
**ASUS**[®]

Title :

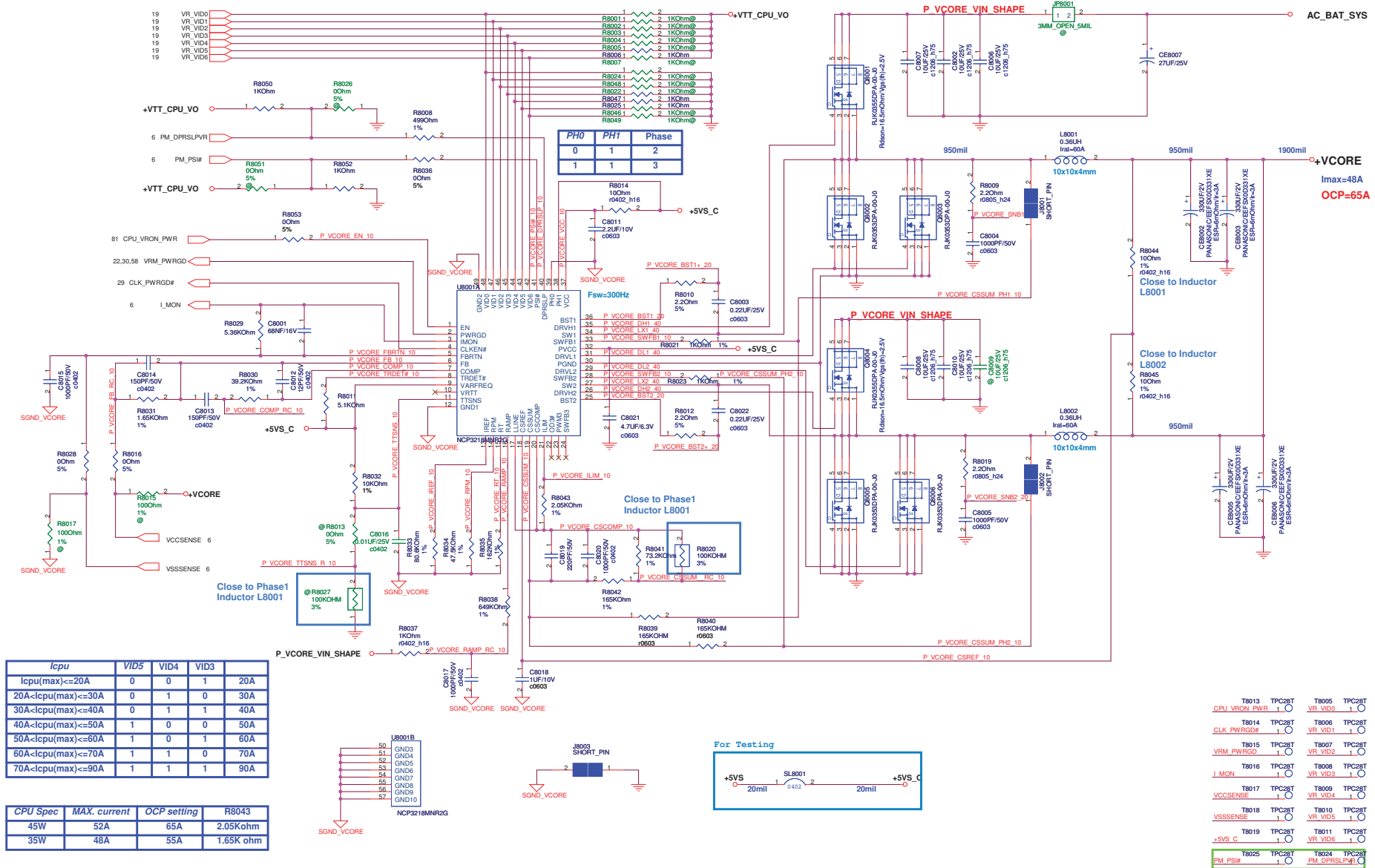
ASUSTeK COMPUTER INC. NB

Engineer: *Ryan_Wang*

Size	Project Name	Rev
C	K72Jr	1.0
Date: Friday, December 11, 2009		Sheet 78 of 100



IMVP6.5 CPU VCORE REGULATOR

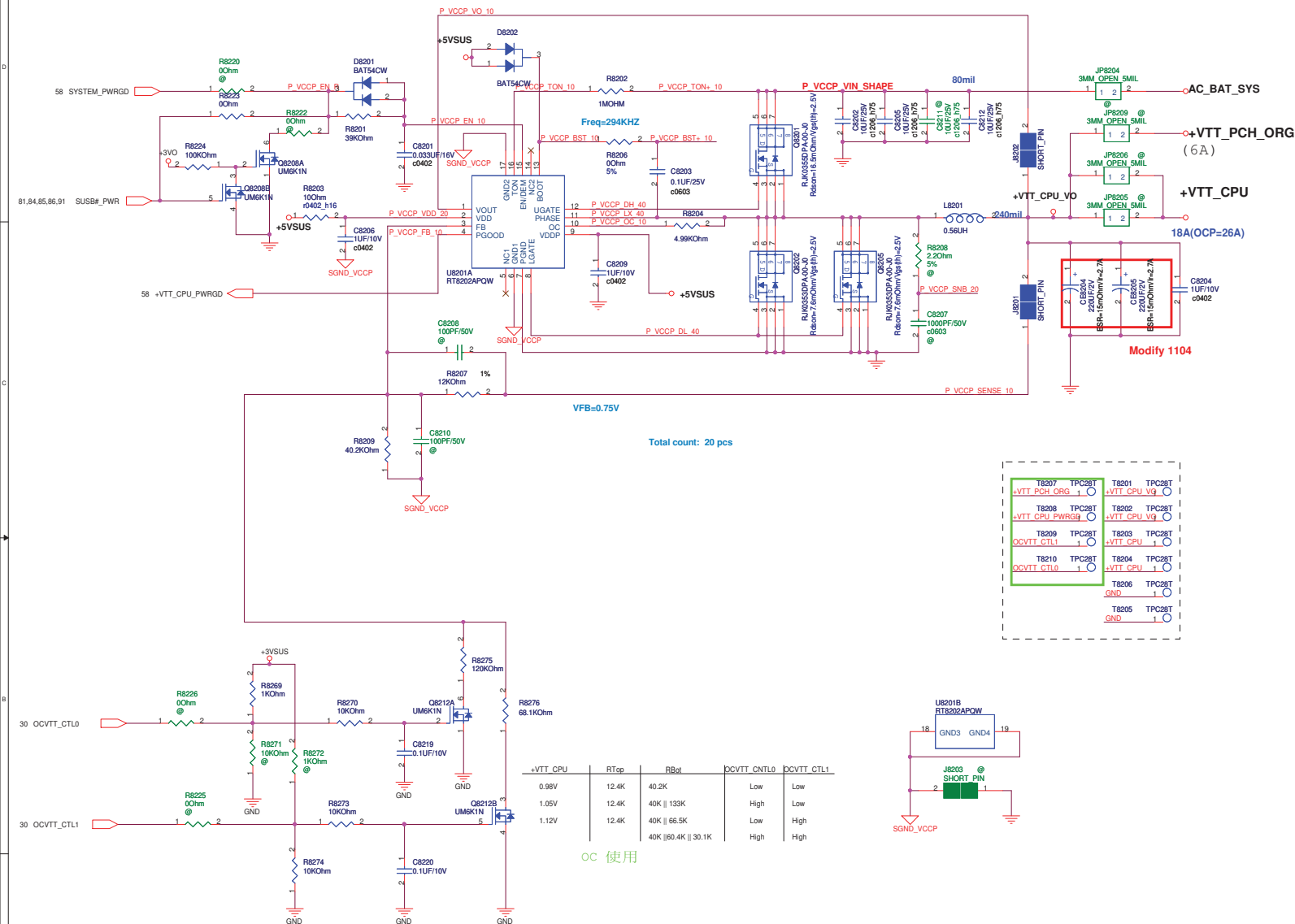


Total count: 73 pcs

<Variant Name>

ASUS		Title : +VCORE	
ASUSTeK COMPUTER INC. NBI		Engineer: CH	
Size	Project Name		Rev
Custom	K72J		1.0
Date: Friday, January 28, 2010		Sheet	80 of 100

+VCCP POWER SUPPLY



Power stage

+VTT_CPU:

1. I/P Current:
 $I_{in} = V_o / I_o / (0.75 \cdot V_{in}) = 1.32A$
2. Ripple Current:
 $I_{rip} = 5.9A$
3. Ripple Voltage:
 $ESR / I_1 = 10m\Omega$
 $V = 59mV$
4. Inductor Spec:
 $I_{sat} = 30.5A$
 $I_{dc} = 22.9A$
 $DCR = 1.4m\Omega$
5. MOSFET Spec:
H-side MOSFET: RJK0355DPA
- $R_{ds}(ON) = 16.5m\Omega$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

L-side MOSFET: RJK0353DPA

Rds(ON)=7.6mohm (Vgs=4.5 V)
I cont = 35A (T=25 °C)
I peak =140 A (Pause =10 us)

Controller

+VTT_CPU

1. **Voltage & Current:**
 $+V_{CCP} = 1.05V / 26A$
2. **Frequency:**
 $F = 294KHZ$
3. **OCp:**
 $Set R8204 = 4.99\ Kohm$
 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 26.26A$
4. **Soft start time:**
The Soft Start duration is 1.35ms
5. **Inrush Current:**
 $C_{total} = 220\ uF$
 $I_{inrush} = C \cdot V_{out} / SS_time$
 $I_{inrush} = 0.17\ A$

Part Selection

- | 1. MOSFET: | 2. Inductor: | 3. Output Cap: |
|--------------------------------|---|--------------------------------|
| PPAK56 | Molding063 | 7343 |
| High Side | FDVE0630-H-1R0M=P3
09G02X103506(HF) | EEFCX0D221YR
11G08D1227D0 |
| RJK035SDPA
07G005B14011(HF) | PCMC063T-1R0MN
09G02X103022 | EEFCX0D221R
11G08D2227D1 |
| RJK035SDPA
07G005B14010 | MPC7301R0M1
09G02X103H11 | ACAS2R0S221E15
11G09D2227D0 |
| Low Side | | |
| RJK035SDPA
07G005A92010 | Ferrite104 | |
| | FDUE1040D-H-1R0M=P3
09G02X103T25(HF) | |
| PPAK33 | | |
| High Side | PCMC104T-1R0MN
09G02X103U00 | |
| S17356DN
07G005A80011(HF) | MPO104-1R0
09G02X103R01 | |

<Variant Name>

+1.5V & 0.75VS POWER SUPPLY

Power stage

- DDR II:**
- I/P Current:**
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.052A$
 - Ripple Current:**
 $I_{rip} = 3.07A$
 - Ripple Voltage:**
 $ESR/1 = 10mohm$
 $V = 30.7mV$
 - Inductor Spec:**
 $I_{sat} = 10.9A$
 $I_{dc} = 10A$
 $DCR = 12.1mohm$
 - MOSFET Spec:**
H-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

- L-side MOSFET: RJK0355DPA**
- $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

Controller

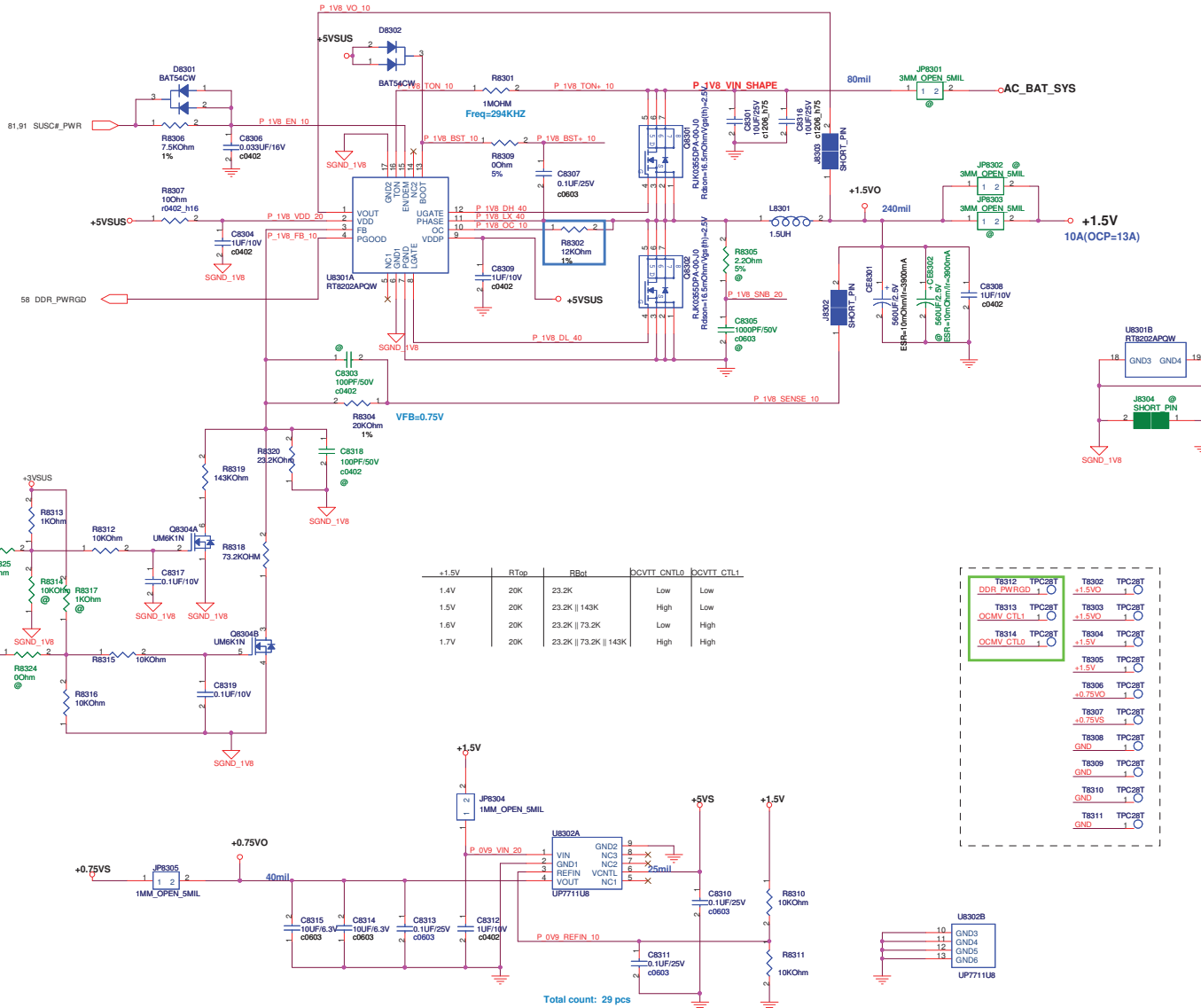
- DDR II:**
- Voltage & Current:**
 $+1.5V: 1.5V / 10A$
 $+0.75V: 0.75V / 1A$
 - Frequency:**
 $F = 294KHZ$
 - OCF:**
Set $R8302 = 12Kohm$
 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 14A$
 - Soft start time:**
The Soft Start duration is 1.35ms
 - Inrush Current:**
 $C_{total} = 560uF$
 $I_{inrush} = C \cdot V_{out} / SS_time$
 $I_{inrush} = 0.17A$

Part Selection

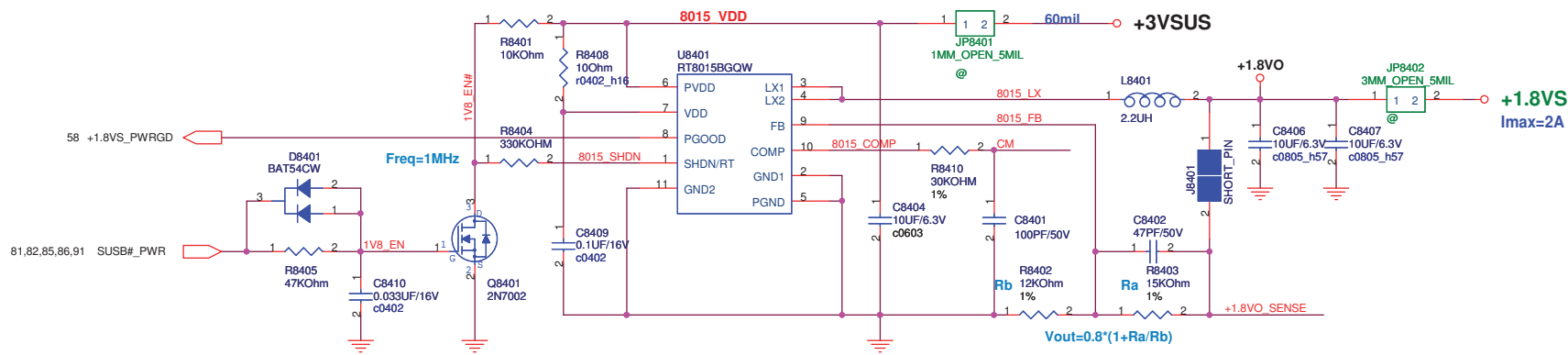
- MOSFET:**
PPAK56
High Side
RJK0355DPA
07G005B14011(HF)
 - Inductor:**
Molding063
FDVE0630-H-2R2M=P3
09G02X223809(HF)
 - Output Cap:**
7343
EEFCX0D221YR
11G08D1227D0
- Low Side
RJK0355DPA
07G005B14010
- Low Side
RJK0353DPA
07G005A92010
- PPAK33
High Side
S1732DN
07G005A80011(HF)

<Variant Name>

ASUS		Title : POWER_IO_DDR	
ASUSTek COMPUTER INC. NB		Engineer: CH_LU	
Size	Project Name	Rev	
Custom	K72J	1.0	
Date: Friday, January 29, 2010		Sheet	83 of 100



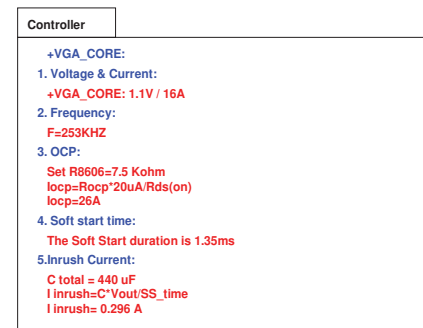
+1.8V POWER SUPPLY



+1.8VS @ 2A

1. Supply Voltage:
 $V_{IN} = 3.3V$ (2.6V ~ 5.5V)
2. Supply Voltage:
 $V_{OUT} = 1.8V / 2A$
3. Current Limit:
 $I_{limit} = 3.2A$
4. Continue Current:
 $I_{cont} = 2A$
5. Feedback Voltage:
 $V_{FB} = 0.8V$
6. Switching Frequency:
 $R_{rt} = 330\text{ Kohm}$
 $F_{sw} = 1\text{ MHz}$

T8403	TPC28T
+1.8VO	1
T8404	TPC28T
+1.8VS	1
T8405	TPC28T
GND	1
T8406	TPC28T
GND	1
T8407	TPC28T
+1.8VS PWRGD	1

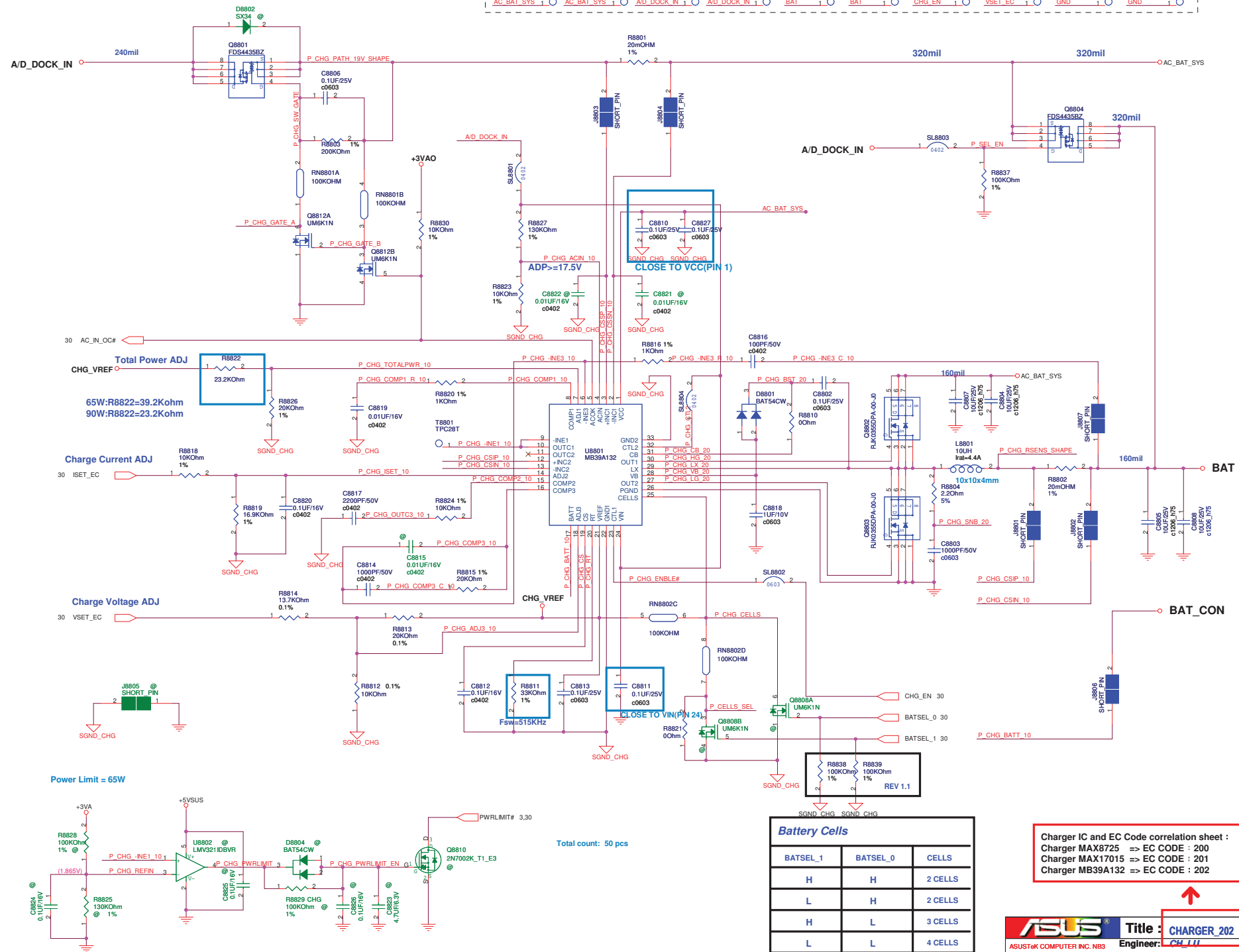


+VGA CORE	RTop	RBot	PWRCNTL_0	PWRCNTL_1
0.90V	8K	40.2K	Low	Low
1.00V	8K	40.2K 60.4K	High	Low
1.12V	8K	40.2K 27K	Low	High
1.22V	8K	40.2K 60.4K 27K	High	High



<Variant Name>			
		Title :	
<OrigName>		Engineer:	
Size	Project Name		Rev
Custom			1.0
Date: Friday, January 28, 2010		Sheet	87 of 100

T8902 TPC28T	T8905 TPC28T	T8908 TPC28T	T8911 TPC28T	T8914 TPC28T	T8917 TPC28T	T8920 TPC28T	T8924 TPC28T	T8927 TPC28T	T8929 TPC28T
AC_BAT_SYS_1	AC_BAT_SYS_1	AD_DOCK_IN_1	AD_DOCK_IN_1	BAT_1	BAT_1	BATSEL_0_1	AC_IN_OC#_1	PWRLIMIT#_1	GND
T8903 TPC28T	T8906 TPC28T	T8909 TPC28T	T8912 TPC28T	T8915 TPC28T	T8918 TPC28T	T8921 TPC28T	T8925 TPC28T	T8928 TPC28T	T8930 TPC28T
AC_BAT_SYS_1	AC_BAT_SYS_1	AD_DOCK_IN_1	AD_DOCK_IN_1	BAT_1	BAT_1	BATSEL_1_1	ISET_EC_1	GND	GND
T8904 TPC28T	T8907 TPC28T	T8910 TPC28T	T8913 TPC28T	T8916 TPC28T	T8919 TPC28T	T8922 TPC28T	T8926 TPC28T	T8932 TPC28T	T8931 TPC28T
AC_BAT_SYS_1	AC_BAT_SYS_1	AD_DOCK_IN_1	AD_DOCK_IN_1	BAT_1	BAT_1	BATSEL_1_1	CHG_EN_1	GND	GND



Battery Cells		
BATSEL_1	BATSEL_0	CELLS
H	H	2 CELLS
L	H	2 CELLS
H	L	3 CELLS
L	L	4 CELLS

Charger IC and EC Code correlation sheet :
Charger MAX8725 => EC CODE : 200
Charger MAX17015 => EC CODE : 201
Charger MB39A132 => EC CODE : 202



<Variant Name>

		Title :	
<OrgName>		Engineer:	
Size	Project Name		Rev
Custom			1.0
Date: Friday, January 28, 2010		Sheet	89 of 100

BATTERY IN DETECT

<Variant Name>



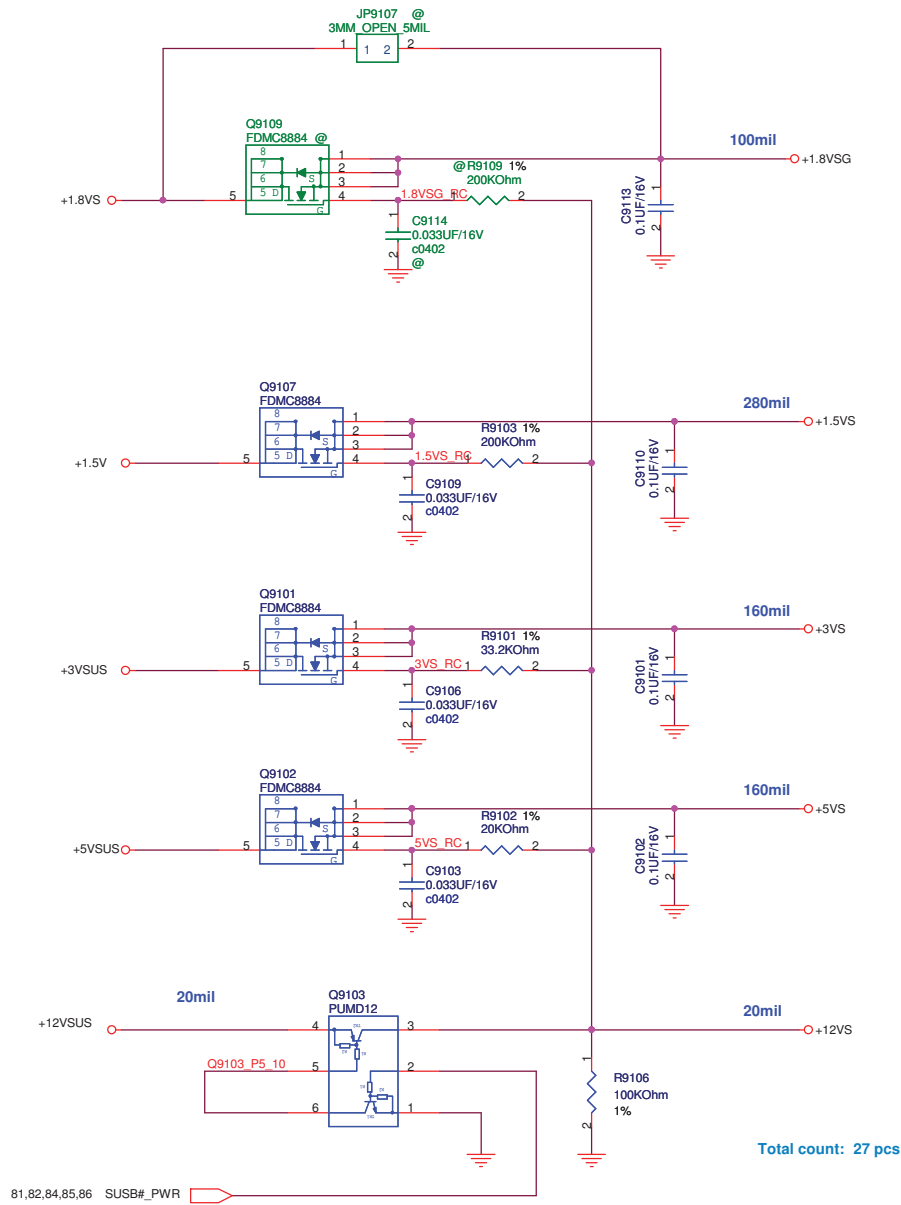
Title :POWER_DETECT

ASUSTeK COMPUTER INC. NBEngineer: Morris

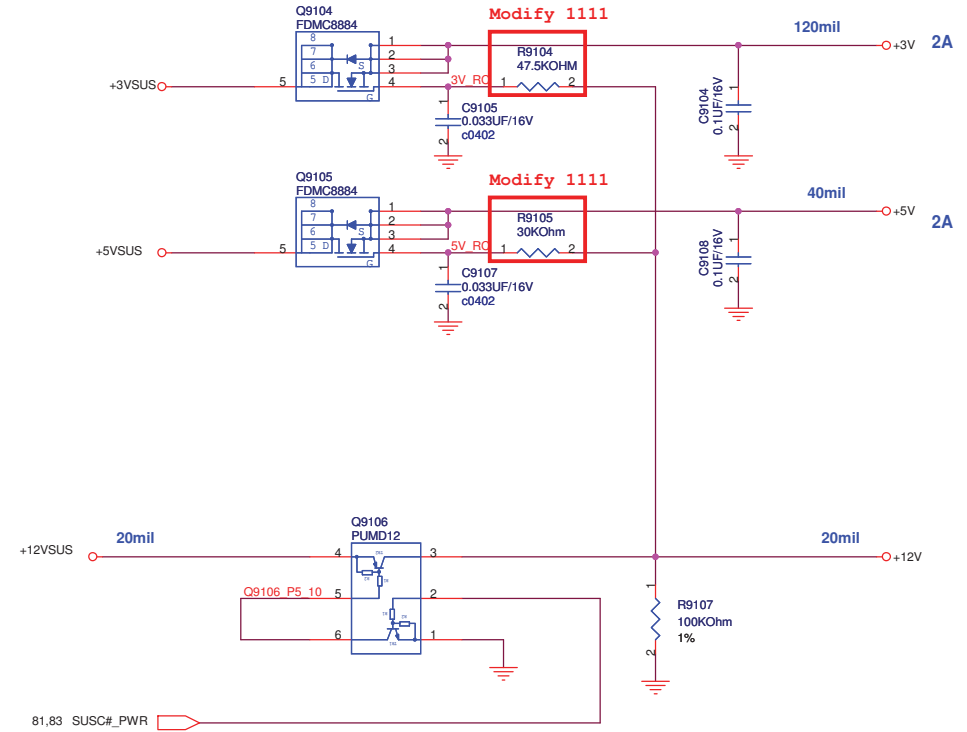
Size	Project Name	Rev
Custom	Design IP	1.0

Date: Friday, January 29, 2010Sheet 90 of 100

SUSB#_PWR POWER



SUSC#_PWR POWER



+12VS	T9107	TPC28T	T9101	TPC28T
+3V	T9108	TPC28T	T9102	TPC28T
+5V	T9109	TPC28T	T9103	TPC28T
+12V	T9110	TPC28T	T9104	TPC28T
GND	T9111	TPC28T	T9105	TPC28T
GND	T9112	TPC28T	T9106	TPC28T

<Variant Name>

ASUS Title : POWER_LOAD SWITCH

ASUSTek COMPUTER INC. NB Engineer: CH_LU

Size	Project Name	Rev
B	K72J	1.0

Date: Friday, January 29, 2010 Sheet 91 of 100

History

R1.0 to R1.1 :

Page 3 : Change R0363,R0364 to RN0302.
Remove SL0311,SL0312.
Change R0366,R0367 to SL0319,SL0320.
Change R0351 to SL0321.

Page 5 : DNI R0501,R0502,R0505,R0506.

Page 6 : Remove R0616,R0601.
Change R0607 to SL0601.
Change R0605,R0606 to RN0601.

Page 14 : Change CE1407 from 220uF to 100uF for cost down.
Change CE1401~CE1403,CE1406 from POSCAP to TAN for cost down.
Change JP1402 to R1414,R1415 for EMI request.
Correct CE1404 part reference to C1450.

Page 16 : Change R1605,R1606 to SL1601,SL1602.

Page 17 : Change R1705,R1706 to SL1701,SL1702.

Page 18 : Change C1811,C1802 from 0.1uF/10V to 0.1uF/16V.
Remove R1809,R1810.
Change R1801,R1802,R1803,R1804 to RN1802.

Page 19 : Add OC/UC circuit (IT8268).

Page 21 : Remove RX2105,RX2106,RX2107,RX2108,RX2140,RX2141.
Change R2136,R2137 to RN2101.

Page 22 : Chaneg R2257 to SL2201.
Remove R2245.
Change R2246 to SL2202.
Change R2239,R2240 to SL2203,SL2204.

Page 23 : Change R2322,R2323 to RN2301.

Page 24 : Change RX2401,RX2404,RX2406 from 22ohm to 47ohm.
Remove T2413.
Change RP2401~RP2403 to RN2401~RN2405.
Change Card Reader to USB port 11.

Page 25 : Remove R2504,R2523.

Page 26 : Remove JP2601.
Add D2605,R2623,Q2621,R2637,C2617 for ITE8541.

Page 27 : Change +VTT_PCH to +VTT_PCH_ORG.

Page 28 : Change SPI ROM circuit for ITE8541.

Page 29 : Add R2922 for CLK_PWRGD# (open drain).
Add +VDD_1.05 for ICS9LVS3162.

Page 30 : Add U3004 co-lay with U3003.
Add R3010 for X'tal free option.
Add R3008,R3006 for ITE8541 VSUS_ON.
Add OCVTT_CTL0/1,OCMV_CTL0/1 for OC/UC option.

Page 31 : Change C3105 from 0.1uF/10V to 0.1uF/16V.

Page 33 : Remove R3314.
Remove AR8121 option circuit.

Page 34 : Change Transformer to 09G051059023 / 09G051059055.
Change +AVDD_CEN_LAN to +AVDD_1.7_LAN.

Page 37 : Change Jack Ground from GND_AUDIO to GND_JACK.
Add SL3740 for HP1_JD , SL3741 for EXT_MIC_JD.

Page 45 : Change R4501 from 330ohm to 150ohm.
C4507 from 1uF/10V to 1uF/6.3V.
Change C4511(0.1uF/10V) to C4513(0.1uF/16V).
Change RNX4501,LX4501 to SL4501.
Change C4514 connect to R4529 pin1.
Change L4503,C4509,C4512 connection.

Page 48 : Change VGND to GND.
Change F4801 from 0.2A/30V to 1.5A/6V.
Add D4803.

Page 53 : Remove RX5305,RX5306.

Page 56 : Change C5605 from 0.1uF/10V to 0.1uF/16V.
Change LED5601~LED5603 from BLUE to GREEN.
Change LED voltage from +5VS/+5VA to +3VS/+3VSUS.
Add CAP_LED#,NUM_LED# pull-up for open drain signal.

Page 57 : Change Q5703B to NC , R5708 pin1 to +VTT_CPU_VO.

Page 58 : Add R5836 (DNI).

Page 60 : Remove L6001,L6002.

Page 65 : Add H6502 for LVDS cable.

Page 68 : Add caps for EMI request.

Page 70 : Change VGND to GND.

Page 71 : Remove R7124.

Page 73 : Change VGND to GND.

Page 74 : Change CE7401 from 3528 to 7343 type.
Change all +VGA_CORE 0.01uF to 1uF for PARK.

Page 75 : Add RN7501~RN7507 for dual rank memory.

Page 76 : Change VGND to GND.

Page 80 : Mount R8050,R8052.
Change R8050,R8051,VID pull-up to +VTT_CPU_VO.

Page 82 : Change +VTT_PCH to +VTT_PCH_ORG.
Add OV/UV circuit , remove 1.1V support.

Page 83 : Add OV/UV circuit.

Page 84 : Change R8405 from 330K to 200K ohm for +1.8VS timing.

Page 86 : Change 5V_RUN to +5VSUS , VGND to GND.

Page 91 : Change JP8207 to JP9107.

*** Change all M92 parts to PARK parts ***

		Title : HISTORY	
<OrgName>		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	96 of 98

R1.1 to R1.2 :

Page 20 : Change C2001,C2002 from 18pF to 15pF.

Page 24 : DNI U2401 , mount R2413.

Page 26 : DNI D2605 , mount R2623 for ITE8541.

Page 28 : DNI R2848 , mount R2857 for ITE8541.
Mount R2866~R2869 for ITE8541.

Page 29 : DNI L2904 & R2921 , mount L2903 for ICS9LVS3162.

Page 30 : DNI R3008 , mount R3006 for ITE8541.
Change C3016,C3017 from 15pF to 10pF.
DNI U3003,R3014 , mount R3002~R3005 for ITE8541.

Page 33 : Add R3321 for signal integrity.

Page 36 : Add D3601 for pop noise.

Page 37 : Change D3709 from RB717F to BAT54AW.
Change C3701 to X7R.

Page 45 : Change C4504 from 1uF/10V to 1uF/6.3V.

Page 47 : Change C4804~C4811 to X5R type.
Change R4801,R4802 to RN4801.

Page 57 : DNI R5705,R5706,Q5703,R5708,R5714,R5715,Q5707,R5712.

Page 58 : Change D5801 from BAT54CW to BAT54C.

Page 65 : Remove H6521,H6522,H6506,H6507,H6523,H6524.

Page 74 : Change L7405 to 09G013120400.
DNI Q7401,L7407 , mount R7402.
Change R7402 to 0805 type.

Page 75 : DNI R7501 for PARK.
Change pin AL21 to test point.

Page 82 : DNI R8220 & R8222 , mount R8223.
Add R8225 & R8226.
DNI R8271 & R8272.

Page 83 : Add R8324 & R8325.
DNI R8314 & R8317.

Page 84 : Change R8405 from 200K to 47K ohm for +1.8VS timing.

Page 85 : Add JP8505 , R8509.
Change R8511 from 7.5K to 5.1K ohm.
DNI U8501 related circuit for cost down.

R1.2 to R1.3 :

Page 21 : Change R2157 from 39 ohm to 15 ohm for single load.

Page 25 : Change PCB ID resistors.

Page 30 : Change R3021,R3023 from 47K ohm to 100K ohm for battery team request.
Add R3030 for VSUS_ON connection.
Delete J3001 & U3004 from schematic.
Add R3011 & Q3002 for ITE8570 X'tal free option.

Page 38 : Change R3852 to 0 ohm , C3801 to DNI.

Page 40 : Change SL4501 to L4502 for EMI request.

Page 52 : Change SL5201,SL5202 to L5201,L5202 for EMI request.

Page 65 : Modify H6518 shape for ME request.

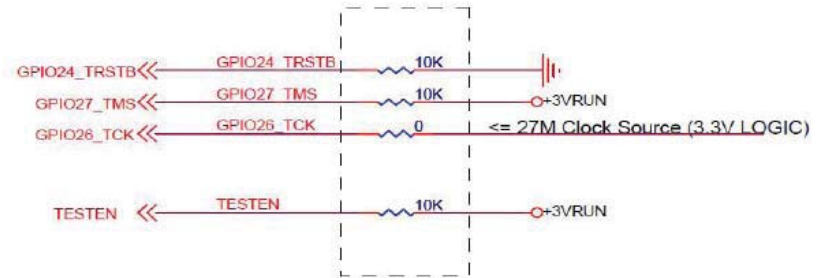
Page 71 : Change R7128 to 0402 type.

Page 77 : Change R7714 to /HYNIX , R7718 to /SAMSUNG.

Page 80 : Change 8029 to 5.36K , C8001 to 68nF , R8032 to 10K , C8019 to 220pF.
Change R8039,R8040 to 165K ohm.

Page 82 : Change CE8202 to C8221 & C8222 (DNI).

Page 70~77 : Add PARK errarta items as below.



In current reference design, TESTEN is pulled down through a resistor and GPIO24_TRSTB may be pulled-high or floating. To implement option 2, both of these resistors should be depopulated (keep the resistor pad for debugging purposes).

Option 2 requires that:

- 1) TESTEN and GPIO27_TMS be pulled high (3.3V)
- 2) GPIO24_TRSTB be pulled to ground (0V), and
- 3) A clock source (1KHz ~27MHz, 3.3V level) be provided on GPIO26_TCK (through a 0 Ohm resistor). The 27MHz oscillator output can be used (if present).

R1.3 to R2.0 :

Page 19 : Add R1903.

Page 20 : DNI R2034~R2039 for Production PCH.

Page 21 : Change R2157 from 15 ohm to 24.9 ohm.

Page 32 : Mount R3207 for G709.

Page 36 : Change INT_MIC to Codec Port A for feedback issue.

Page 37 : Change Phone Jack P/N from 12G14030106L to 12G14000106M.

Page 38 : Change Internal Mic reference voltage to codec output.

Page 46 : DNI Q4601 , mount U4601 , change SL4601 & SL4602 to 33 ohm for HDMI audio disappear issue.

Page 48 : DNI D4803 for cost down.

Page 50 : Add G709 circuit , DNI G781 circuit.

Page 51 : Change R5101~R5103 to short land.

Page 56 : Change LED5601 from Green to White , R5604 pin1 from +3VSUS to +5VSUS.

Page 57 : Delete Q5702 & Q5703 & Q5707 discharge circuit , change Q5704 to 2N7002.

Page 60 : Delete JP6003 & JP6004.

Page 65 : Delete H6527.

Page 66 : Change C6607 from 0.1uF/16V to 0.1uF/25V.

Page 71 : Add U7101 & R7131 for PARK errata E2 , DNI R7121 & R7124 for production PARK.

Page 73 : DNI R7335 , mount R7305 for production PARK.

Page 76 : DNI R7605 for production PARK.

Page 82 : Modify CE8204 & CE8205 package.

Page 91 : Change R9104 to 47.5K , R9105 to 30K for power on fail issue.